

Ares-2 (LAR-2)

AMD CEZANNE Schematics

RESISTOR

Symbol name	Value	Tolerance (J: 5%, F: 1%, D: 0.5%, B: 0.1 %)	Rating 0402=> 1/16W, 25V 0603 => 1/16W, 75V 0805 => 1/10W, 100V	Size 2=>0402, 3=>0603, 5=>0805, 6=>1206, 0=>1210
10KR3	10K Ohm	If no letter, it means J: 5%	1/16W, 75V	0603
33D3R5	33.3 Ohm	If no letter, it means J: 5%	1/10W, 100V	0805
1KR3F	1K Ohm	F: 1%	1/16W, 75V	0603

The naming rule is value + R + size + tolerance.
For the value, it can be read by the number before R. (R means resistor)
For the tolerance, it can be read from the last letter.
For the rating, we don't show on the symbol name.
For the size, R2=>0402, R3=>0603, R5=>0805.....

CAPACITOR

Symbol name	Value	Tolerance (M: +/-20, K: +/-10, Z: +80/-20)	Rating	Size 2=>0402, 3=>0603, 5=>0805, 6=>1206, 0=>1210
SCD1U10V2MX-1	0.1uF	M/X5R	10V	0402
SC10U6D3V5MX	10uF	M/X5R	6.3V	0805
SC2D2U16V5ZY	2.2uF	Z/Y5V	16V	0805

The naming rule is:
Capacitor type + value + rating + size + tolerance + material
SCD1U10V2MX-1
SC=> SMT Ceramic, TC=> POS cap or SP cap
D1U => 0.1uF
10V => the voltage rating is 10V
2=> 0402, 3=>0603, 5=>0805
M=>tolerance M, K, Z
X=> X7R/X5R, Y=> Y5V
-1 => symbol version, nonsense to EE characteristic

DESCRIPTION

BOM control parts :
TEXT with PURPLE color near part reference



BOM control name
Part reference
Symbol name

DY	DUMMY
PCBID	PCB NO. control for SW
SKUID	CPU Type change for SW
MEM_IDx_x	Memory ID for SW
DDR4_CTRL	SDP DDP setting
SDP/DDP	Select single DIE (SDP) Dual DIE(DDP)
HDT	Debug Connectors
EMC	For EMC test request
PSL	KBC PSL model control
YOGA,YOGA2	YOGA model setting
ZZ	For Test Piont /Hole /ShortPad
MS	Modern stand by
DASH/NON_DASH	DASH function control
YOGA/CLAMSHELL	YOGA/CLAMSHELL control
dTPM/fTPM	TPM/NON_TPM control
WOW/NON_WOW	WOW control

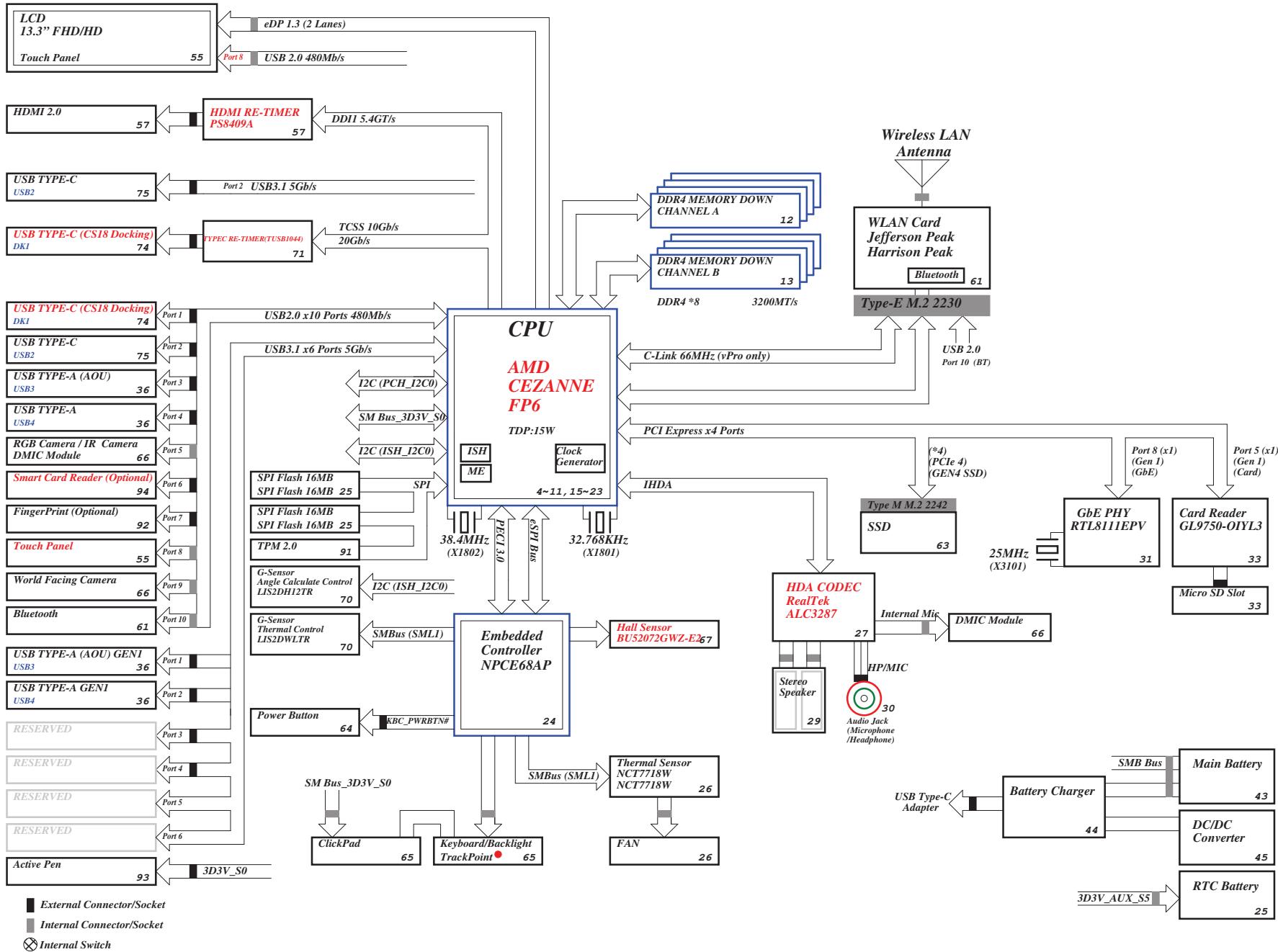
LAR2 CZ

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COVER PAGE		
Size A3	Document Number	Rev -2
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AMD CEZANNE Block Diagram

Project Code: 4PD0P7010001

PCB(Raw Card): 203088-SD

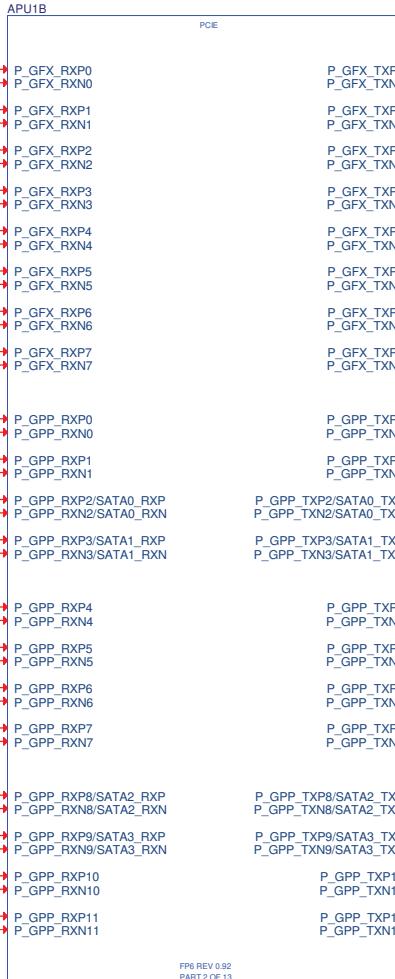


PCB Layer Stackup	
10 Layers	
L1: Component (TOP)	
L2: GND	
L3: Signal	
L4: GND	
L5: Signal	
L6: Signal	
L7: GND	
L8: Signal	
L9: GND	
L10: Component (BOTTOM)	

Battery Charger/Selector	BQ25710RSNR	44
20V_VINT_IN	I9V_DCBATOUT_BT+	
System DC/DC 5V	SY8288CRAC	45
I9V_DCBATOUT	3V_SS_AUX_SS	
System DC/DC 3D3V	SY8288BRAC	45
I9V_DCBATOUT	3D3V_AUX_SS	
VCORE	MP2945GU	46
VCORE	MP86901	47
I9V_DCBATOUT	IV_CPU_CORE	
VDDCR_SOC	MP86901	48
I9V_DCBATOUT	IV_VDDCR_SOC	
		50
DC/DC ID2V_S3	RT8231CGQW	51
I9V_DCBATOUT	ID2V_S3	
DC/DC 0D6V_VREF_S0	RT8231CGQW	51
ID2V_S3	0D6V_VREF_S0	
DC/DC 2D5V_S5	APL5934	51
5V_SS	2D5V_S3	
DC/DC 0D75V_S5	RT5753	52
3D3V_SS	0D75V_SS	
DC/DC 0D75V_S0	RT5753	52
3D3V_SS	0D75V_S0	
DC/DC ID8V_S5	SY8386RHC	53
I9V_DCBATOUT	ID8V_SS	

SSID = PCH

GFX & GPP, 85Ω



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SSD1 M.2 (PCIE)

63	SSD_PCIE_RX_P0
63	SSD_PCIE_RX_N0
63	SSD_PCIE_RX_P1
63	SSD_PCIE_RX_N1
63	SSD_PCIE_RX_P2
63	SSD_PCIE_RX_N2
63	SSD_PCIE_RX_P3
63	SSD_PCIE_RX_N3
63	SSD_PCIE_TX_CON_P0
63	SSD_PCIE_TX_CON_N0
63	SSD_PCIE_TX_CON_P1
63	SSD_PCIE_TX_CON_N1
63	SSD_PCIE_TX_CON_P2
63	SSD_PCIE_TX_CON_N2
63	SSD_PCIE_TX_CON_P3
63	SSD_PCIE_TX_CON_N3

M.2 SSD1 (PCIE)

SSD_PCIE_RX_P0	G11
SSD_PCIE_RX_N0	F11
SSD_PCIE_RX_P1	J10
SSD_PCIE_RX_N1	H11
SSD_PCIE_RX_P2	G8
SSD_PCIE_RX_N2	F8
SSD_PCIE_RX_P3	G6
SSD_PCIE_RX_N3	F7

IR CAMARA

SD CARD

NIC GLAN

WLAN

SD CARD

NIC GLAN

31	LAN_PCIE_RX_N
31	LAN_PCIE_RX_P
31	LAN_PCIE_TX_C_P
31	LAN_PCIE_TX_C_N

WLAN

61	WLAN_PCIE_RX_N
61	WLAN_PCIE_RX_P
61	WLAN_PCIE_TX_CON_N
61	WLAN_PCIE_TX_CON_P

IR CAMARA

56	COD_PCIE_RX_N
56	COD_PCIE_RX_P
56	COD_PCIE_TX_C_N
56	COD_PCIE_TX_C_P

M.2 SSD1 (PCIE)

IR CAMARA

SD CARD

NIC GLAN

WLAN

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CPU (RSVD)

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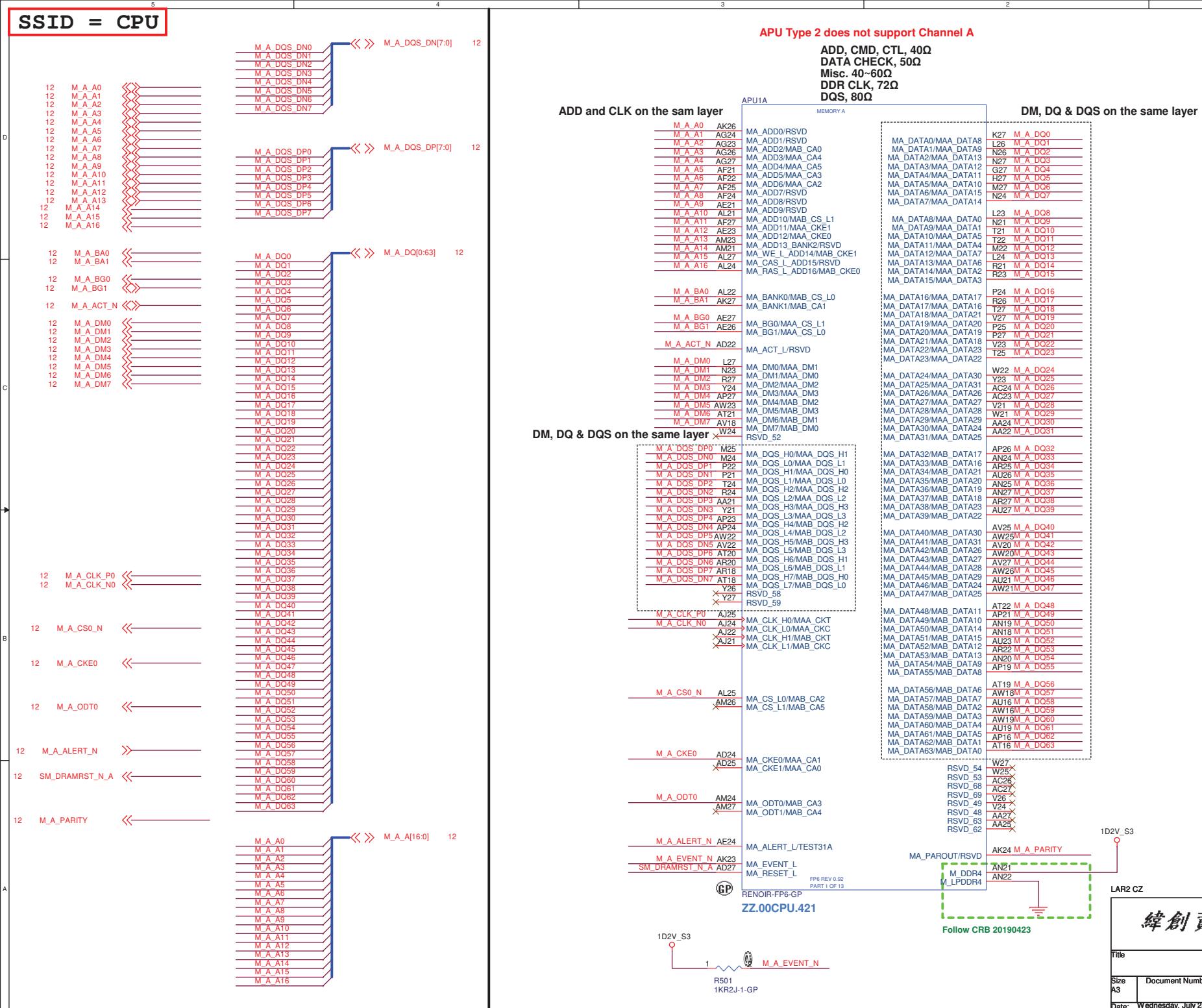
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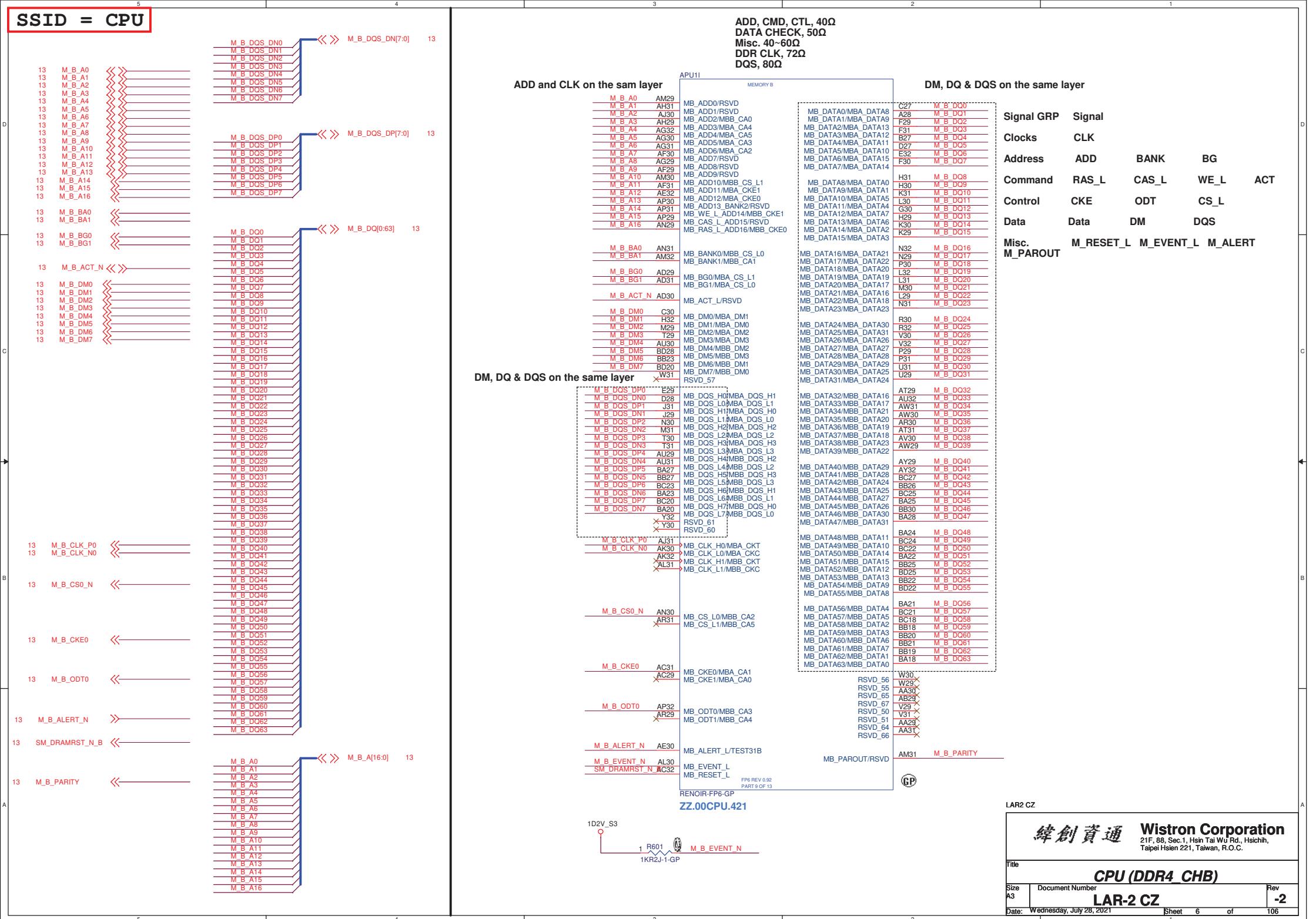
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SSID = CPU

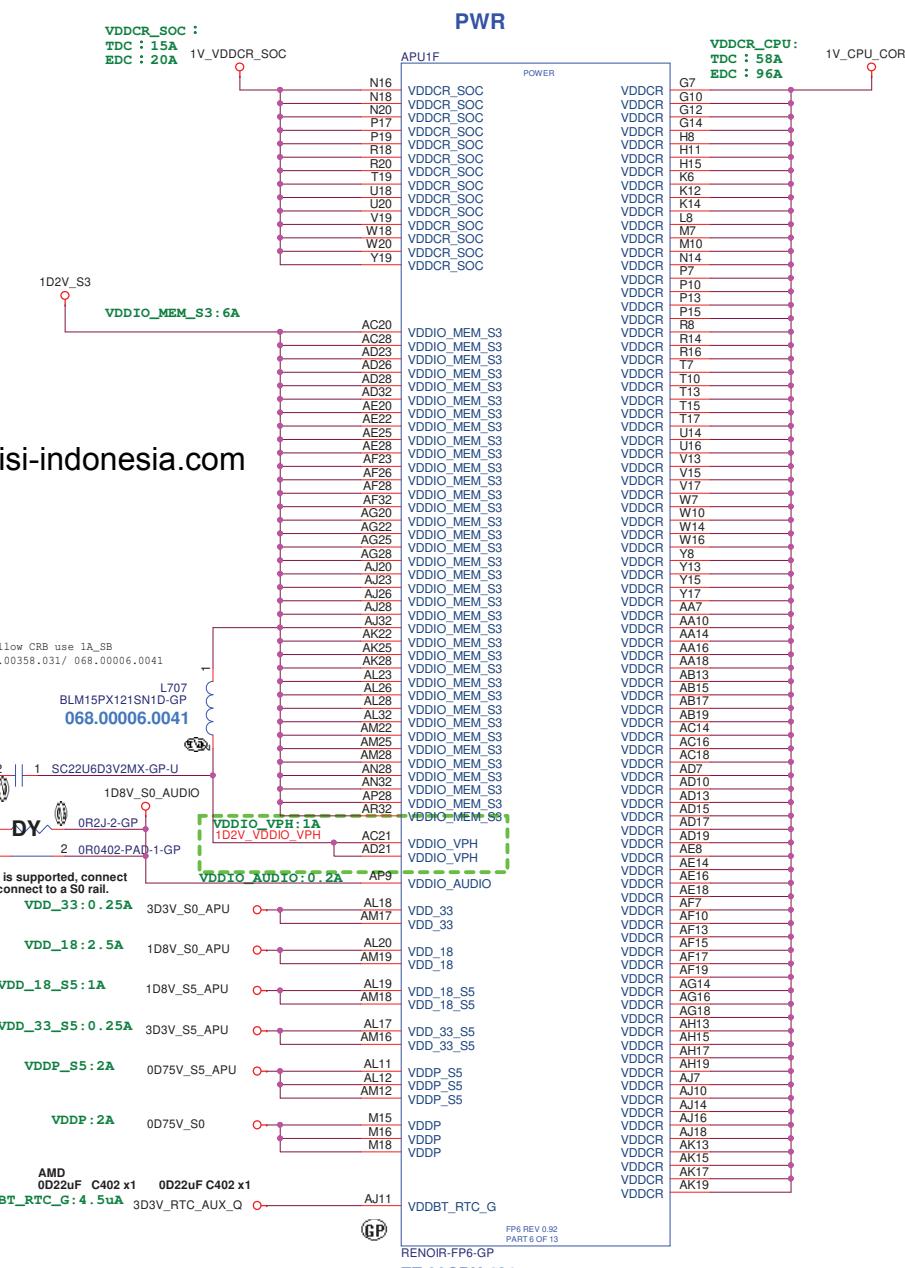


SSID = CPU

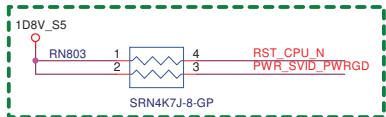
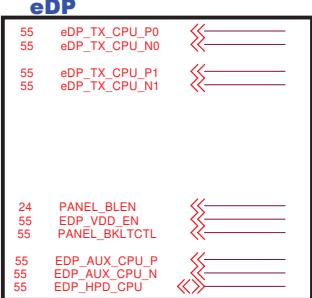
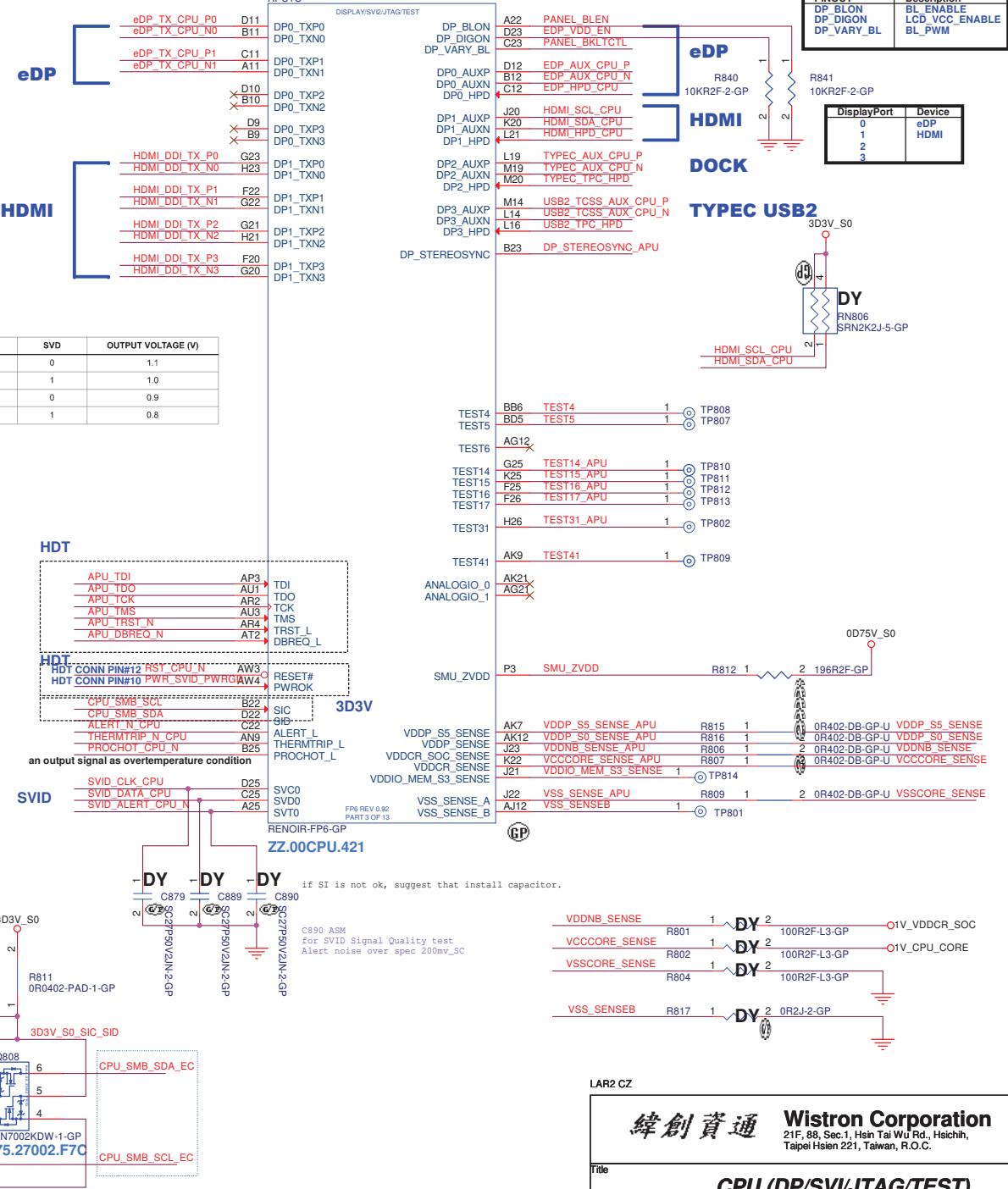
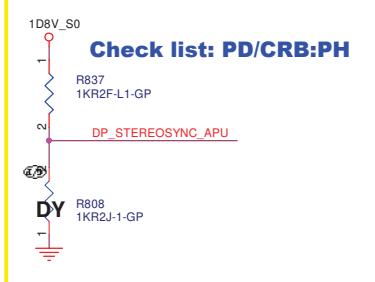
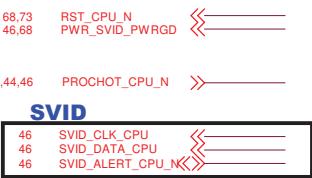
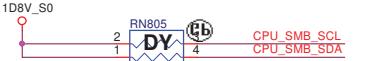
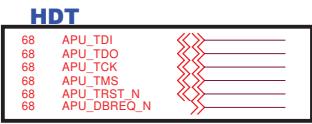
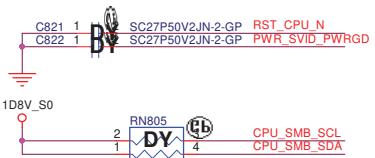
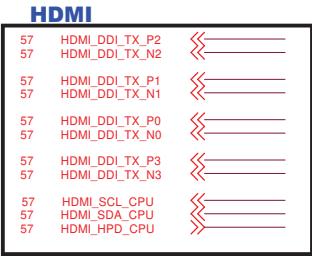
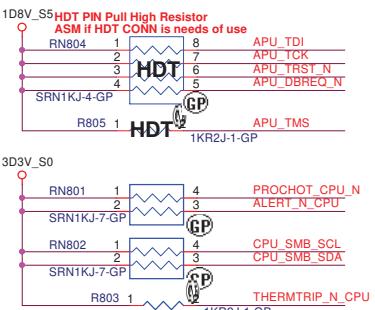
SVI	FP4 – Bristol Ridge	FP5 – Raven Ridge
Supply 1	VDDCR_CPU – x86 Cores	VDDCR_VDD – x86 Cores, GPU
Supply 2	VDDCR_NB – Rest Of Chip	VDDCR_SOC – Rest Of Chip
Supply 3	VDDCR_GFX – GPU	N/A
Sum@15W	TDC: 56A, EDC: 87A	TDC: 45A, EDC: 58A

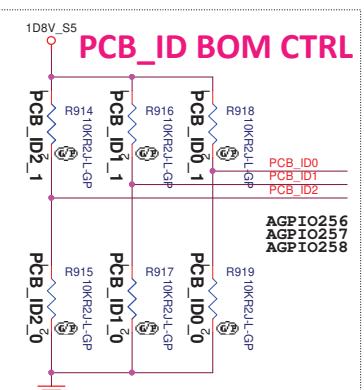
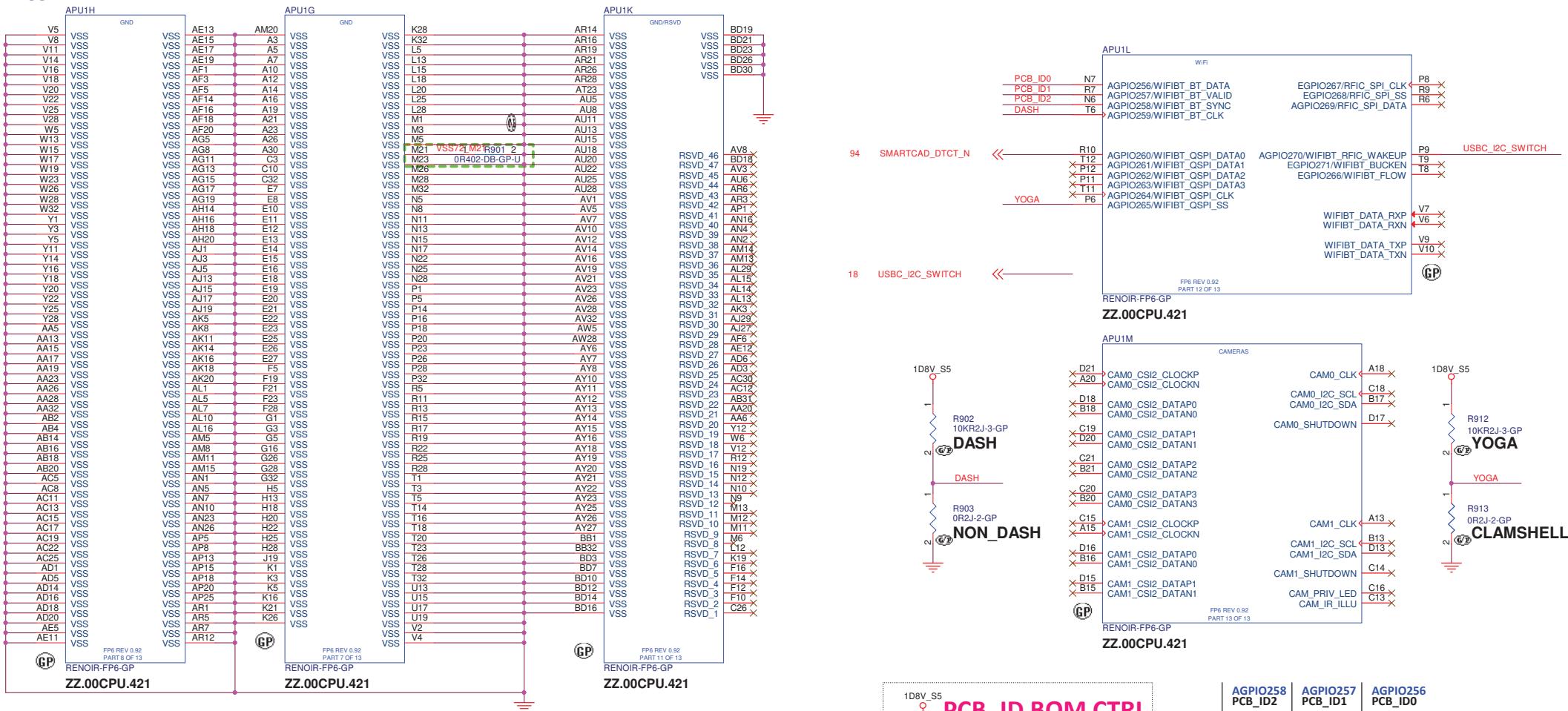
Table 5. FP6 Processor Voltage Supply Currents

Supply	Nominal Voltage at Pkg Ball (V) ²	Condition	SYSTEM_CONFIGURATION					
			1 10W	2 15W	3 25W	4 35W	5 45W	6 54W
VDDCR_VDD	(0.65–TBD) ³	TDC ³	20	33	44	51	58	
		EDC	34	50	70	90		96
		Max Loadstep ⁴	29	43	65	76		84
VDDCR_SOC	(0.7–TBD) ⁵	TDC ³	10		13		15	
		EDC	13		17		20	
		Max Loadstep ⁴						
VDDIO_MEM_S3 ⁶	1.10	TDC			6.00			
	1.20	TDC			6.00			
	1.10	TDC			1.00			
VDDIO_VPH ⁷	1.20	TDC			1.00			
	1.80	TDC			1.00			
	0.75	TDC			2.00			
VDDP	0.75	TDC			2.00			
VDD_S5	0.75	TDC			2.00			
VDD_18	1.80	TDC			2.50			
VDD_18_S5	1.80	TDC			1.00			
VDD_33	3.30	TDC			0.25			
VDD_33_S5	3.30	TDC			0.25			
VDDIO_AUDIO	1.20	TDC			0.20			
	1.50	TDC			0.20			
	1.80	TDC			0.20			
VDDBT_RTC_G	3.00	TDC			4.5μA			



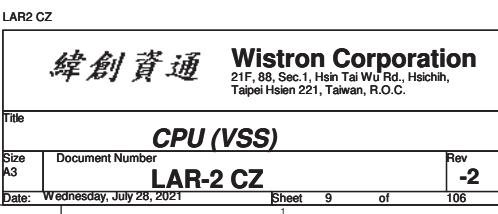
15.3.5 VDDIO_VPH Power Delivery and Decoupling
VDDIO_VPH is the dedicated supply voltage for DisplayPort 0 and PCIe phys. When DisplayPort 0 is used for eDP, the source of VDDIO_VPH can be the same source as VDDIO_MEM_S3. This allows lower power and better battery life. When DisplayPort 0 is used for DP or TMDS, the source of VDDIO_VPH can be the same source as VDD_18.

SSID = PCH**DISPLAY/SVI/JTAG/TEST**APU Type I(CZ): 1D8V
APU Type II(CZ-L): 3D3V**HDT EVT stage 要上**

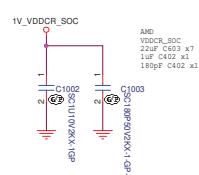
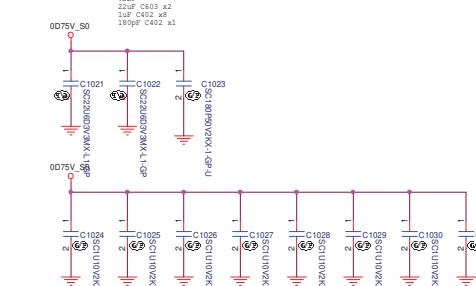
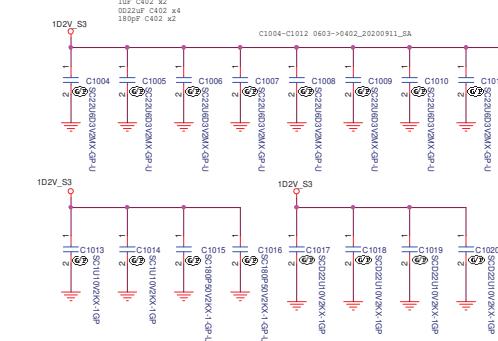
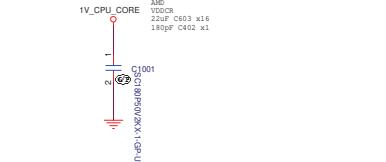
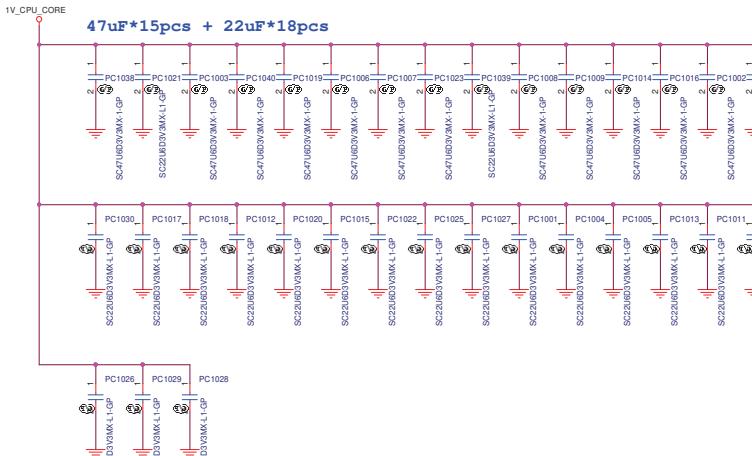


	AGPIO258 PCB_ID2	AGPIO257 PCB_ID1	AGPIO256 PCB_ID0
	SA 0	1	1
	SB 0	1	0
2	SC 0	0	1
	SD 0	0	0
	-1 1	0	0
	-2 1	0	1
R	-3 1	1	0

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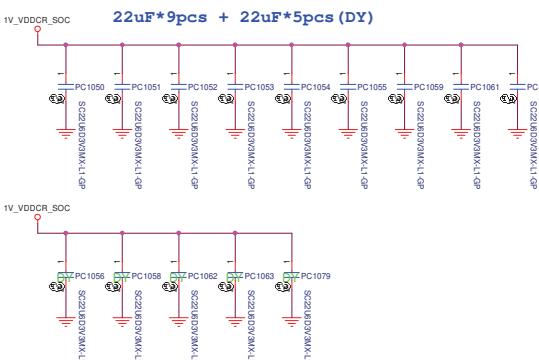


1V_VDDCORE AMD_FP6_25W



RED:ASM
YELLOW:PC1056
GREEN:PC1058 + PC1062 + PC1063 + PC1079
23200629_SC

1V_VDDCR_SOC



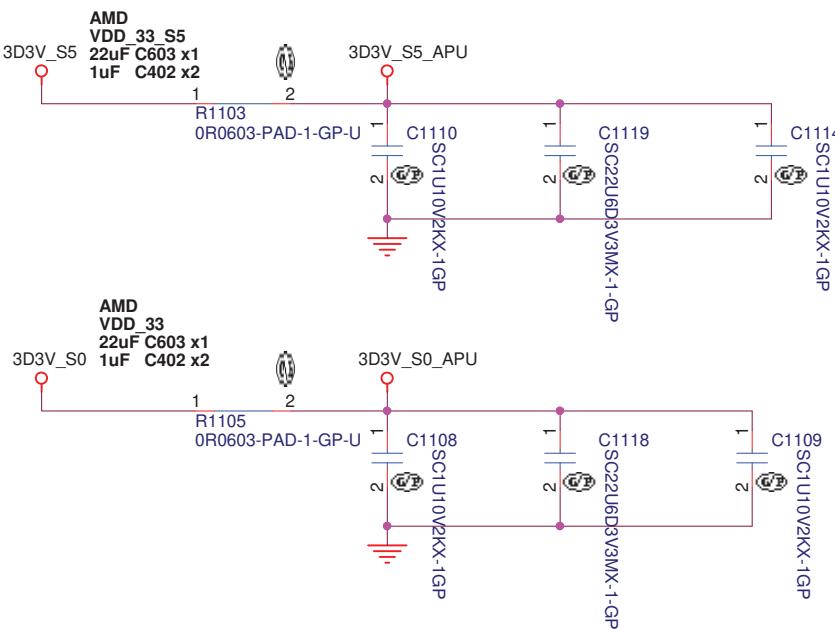
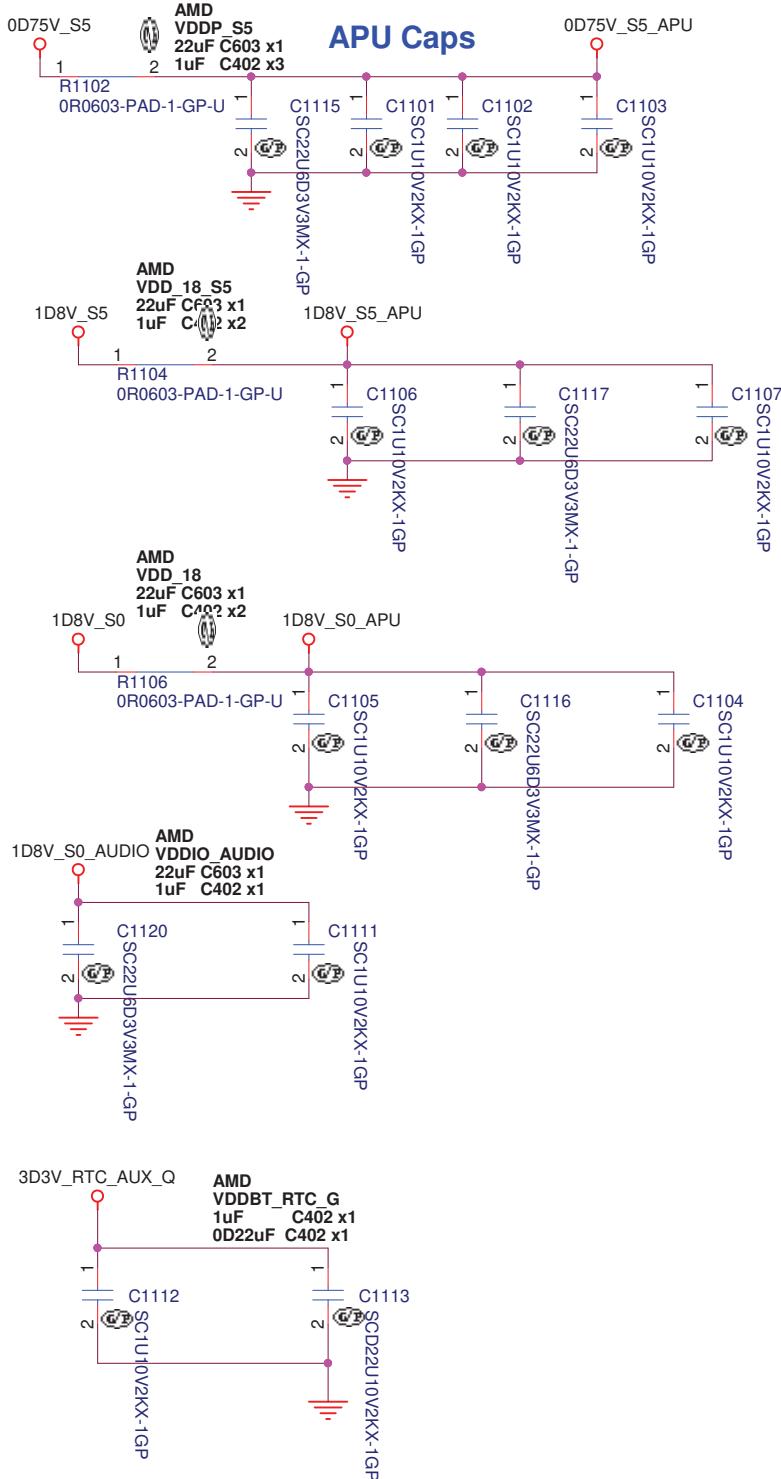


Table 110. Decoupling Capacitors for Processor Power

Capacitor	VDDBT_RTC_G
Value	VDDIO_AUDIO
22 µF	VDD_33
1.0 µF	VDD_33_S5
0.22 µF	VDD_18
180 pF	VDD_18_S5
	VDDP_S5
	VDDP
	VDDIO_MEM_S3 ¹ , ²
	VDDCR_SOC
	VDDCR

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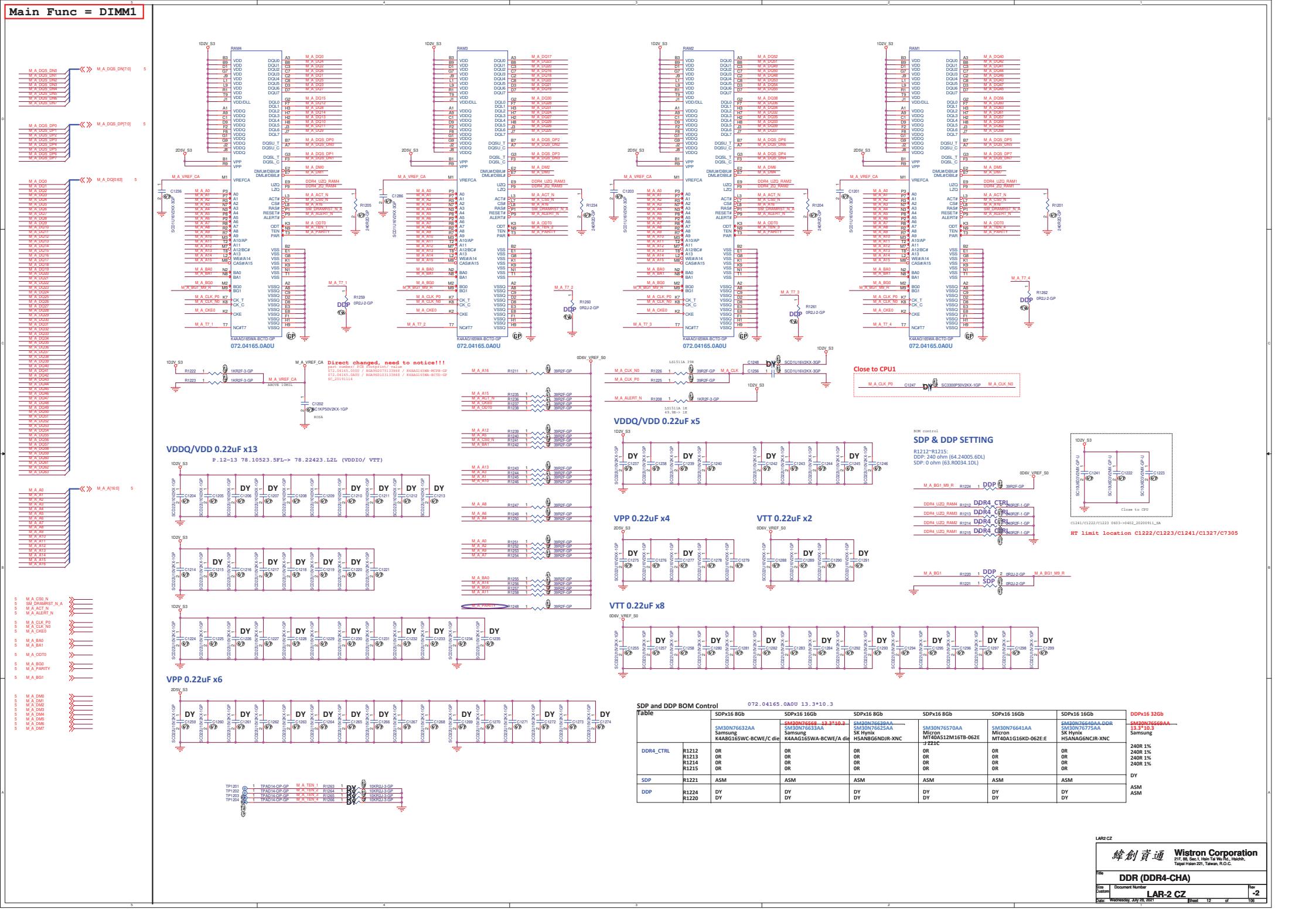
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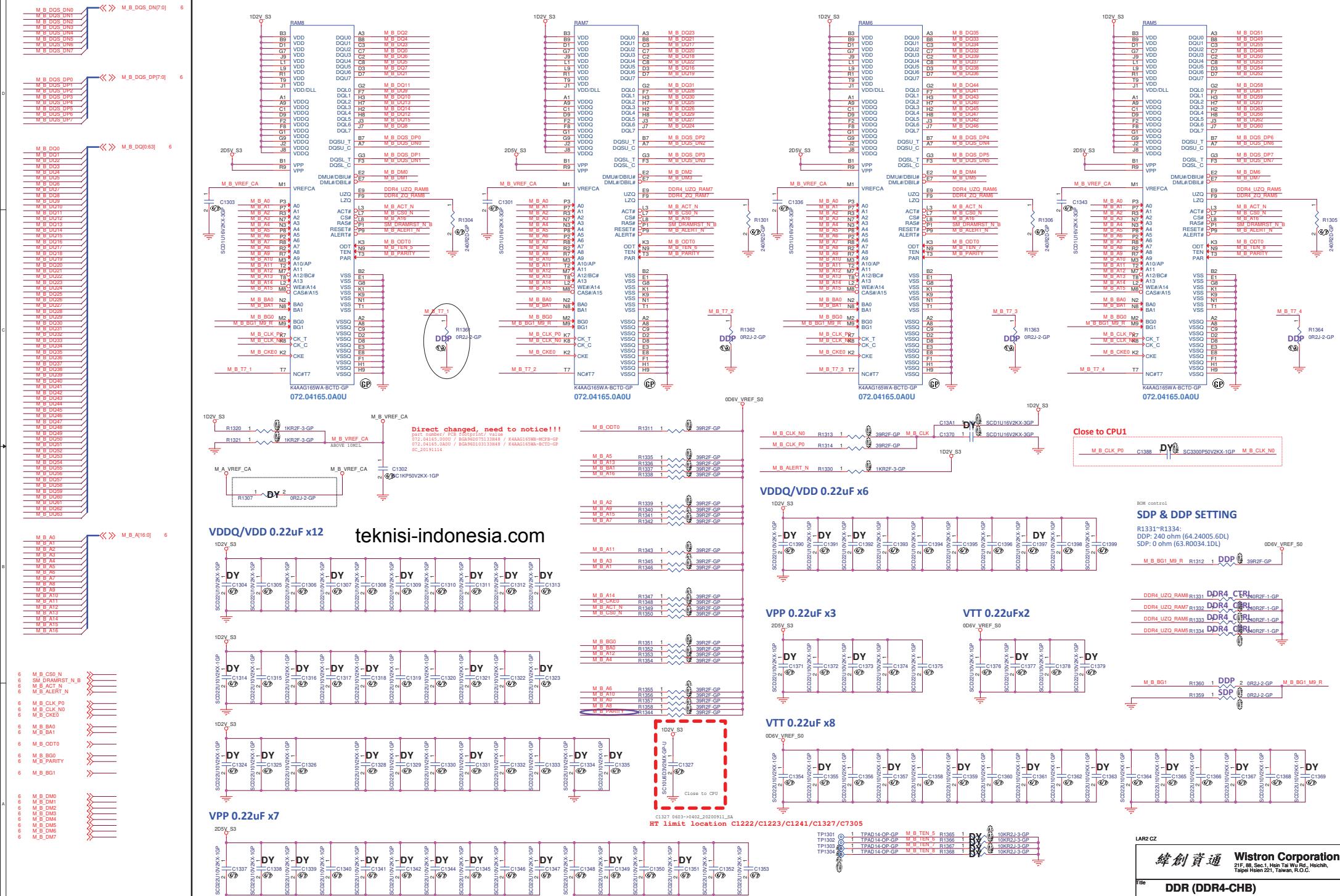
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DDR (RSVD)

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FCH (RSVD)

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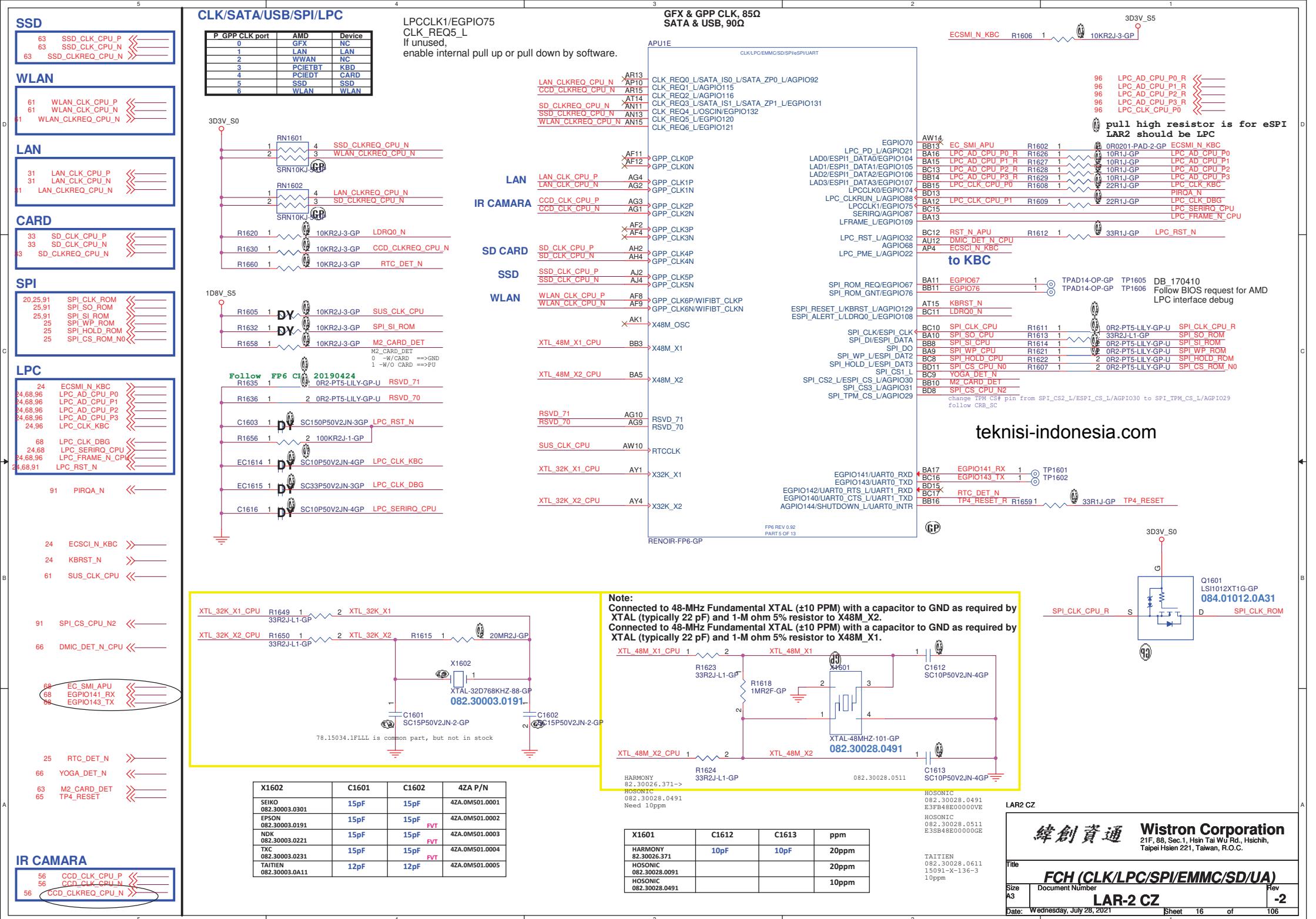
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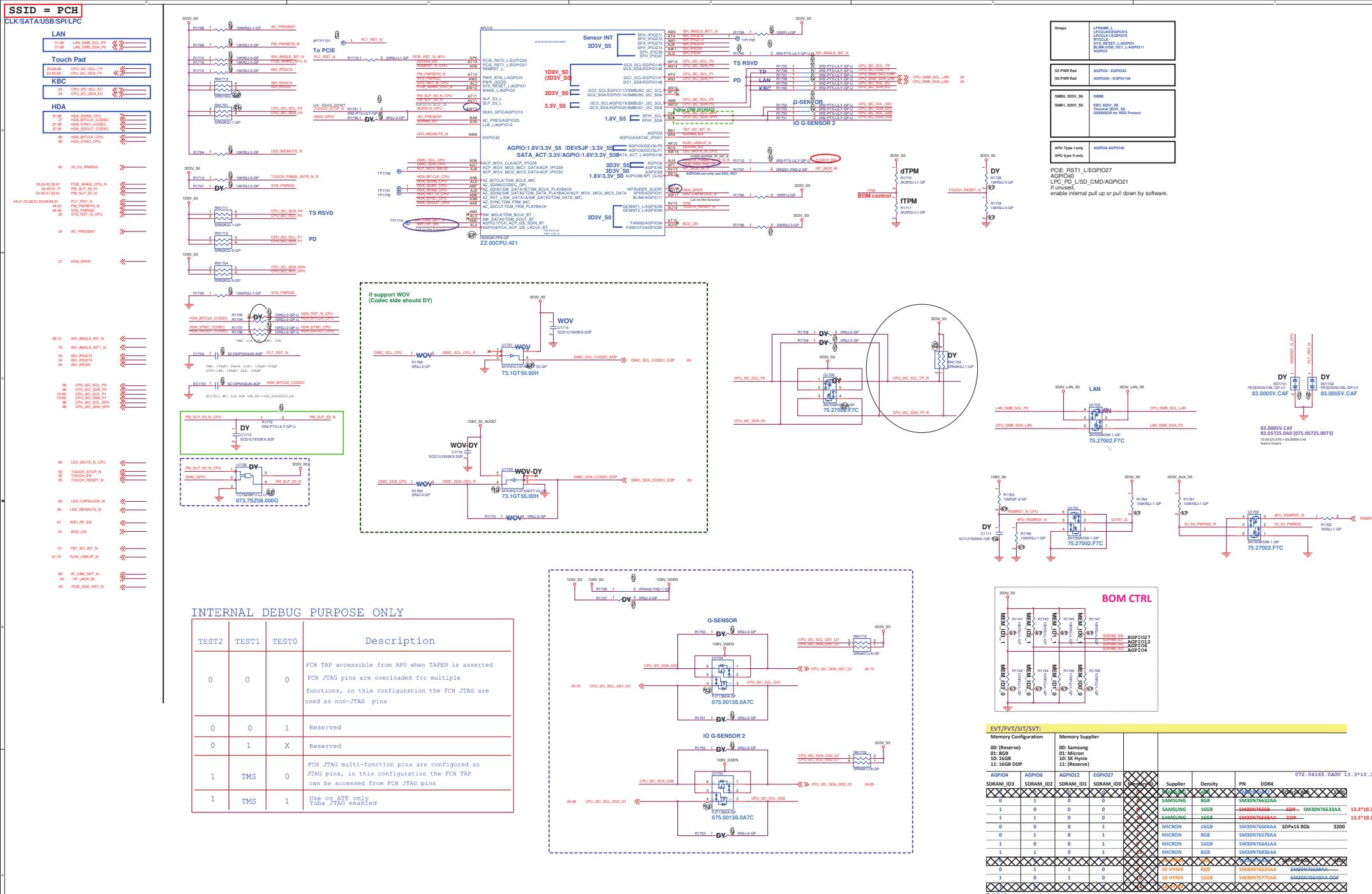
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Main Func = USB

USB3.0 Port3



USB3.0 Port4



BT



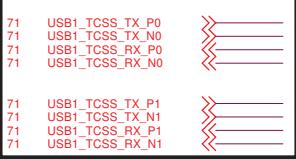
IR Camera



Type-C USB20



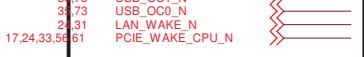
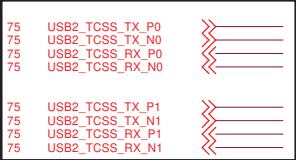
Type-C DK1



Type-C 2 USB20



Type-C 2



HUB(World Facing Camera,SCR,TS)



DK1 USB2.0 Port1

USB2.0 Port3

RGB & IR Camera

FP

Type-C 2 port2

USB2.0 Port4

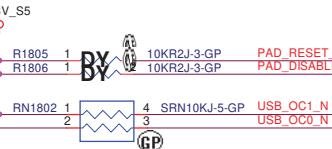
BT

HUB(World Facing Camera,SCR,TS)

World Facing Camera (Yoga only)

CPU_I2C_SCL_TYPEC

CPU_I2C_SDA_TYPEC



APU1J

USB

USBC0_DP/USB0_DP

USBC0_DN/USB0_DN

USB1_DP

USB2_DP

USB3_DP

USB3_DN

USB2_USB20_P

USB2_USB20_N

USB4_USB20_P

USB4_USB20_N

USB5_DP

USB5_DN

USB6_DP

USB6_DN

USB4_TC1P/USB4_TXP/DP3_TXP1

USBC4_TC1N/USB4_TXN/DP3_TXN2

USBC4_RX1P/USB4_RXP/DP3_TXP3

USBC4_RX1N/USB4_RXN/DP3_TXN3

USBC4_TC2P/DP3_TXP1

USBC4_TC2N/DP3_TXN1

USBC4_RX2P/DP3_TXP0

USBC4_RX2N/DP3_TXN0

USB5_TXP

USB5_TXN

USB5_RXP

USB5_RXN

FPC REV 0.92

PART 10 OF 13

RENOIR-FP6-GP

BP

ZZ.00CPU.421

AGPIO13/USB_OC5_L

If unused,
enable internal pull up or pull down by software.

1D8V_S5

USBC_I2C_SWITCH

R1803 0R0402-PAD-1-GP

R1804 0R2J-2-GP

DY

C1801 SCD1U16V2KX-3GP

1D8V_SS_PD

CPU_I2C_SCL_PD

Q1801

PT138KA-GP

075.00138.0A7C

CPU_I2C_SDA_PD

1D8V_S5

CPU_I2C_SCL_TYPEC

CPU_I2C_SDA_TYPEC

RN1803 SRN4K7-8-GP

96 CPU_I2C_SCL_TYPEC

96 CPU_I2C_SDA_TYPEC

Type C USB3.1 Gen2 + USB2.0 + DP

DK1 USB2.0 Port1

USB3.0 Port3

Type-C port2

USB3.0 Port4

LAR2 CZ

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FCH (RSVD)

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A4

Document Number

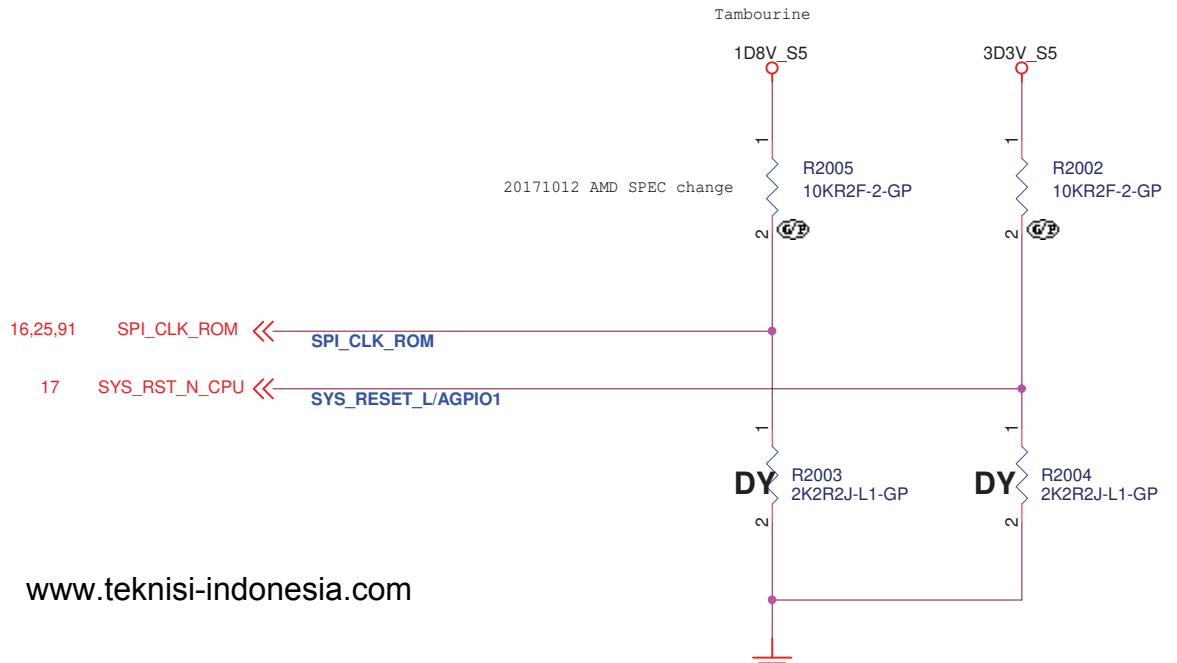
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STRAP PINS



	PIN SPI_CLK NET SPI_CLK_ROM	PIN SYS_RESET_L//AGPIO1 NET SYS_RST#_CPU
PULL HIGH	Configured for internal clock-generator 10kΩ(± 5%) pull-up resistor to VDD_18 (DEFAULT)	Normal powerup / reset timing 10kΩ(± 5%) pull-up resistor to VDD_33_S5 (DEFAULT)
PULL LOW	Reserved	Reserved

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FCH (Strap)	
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-2

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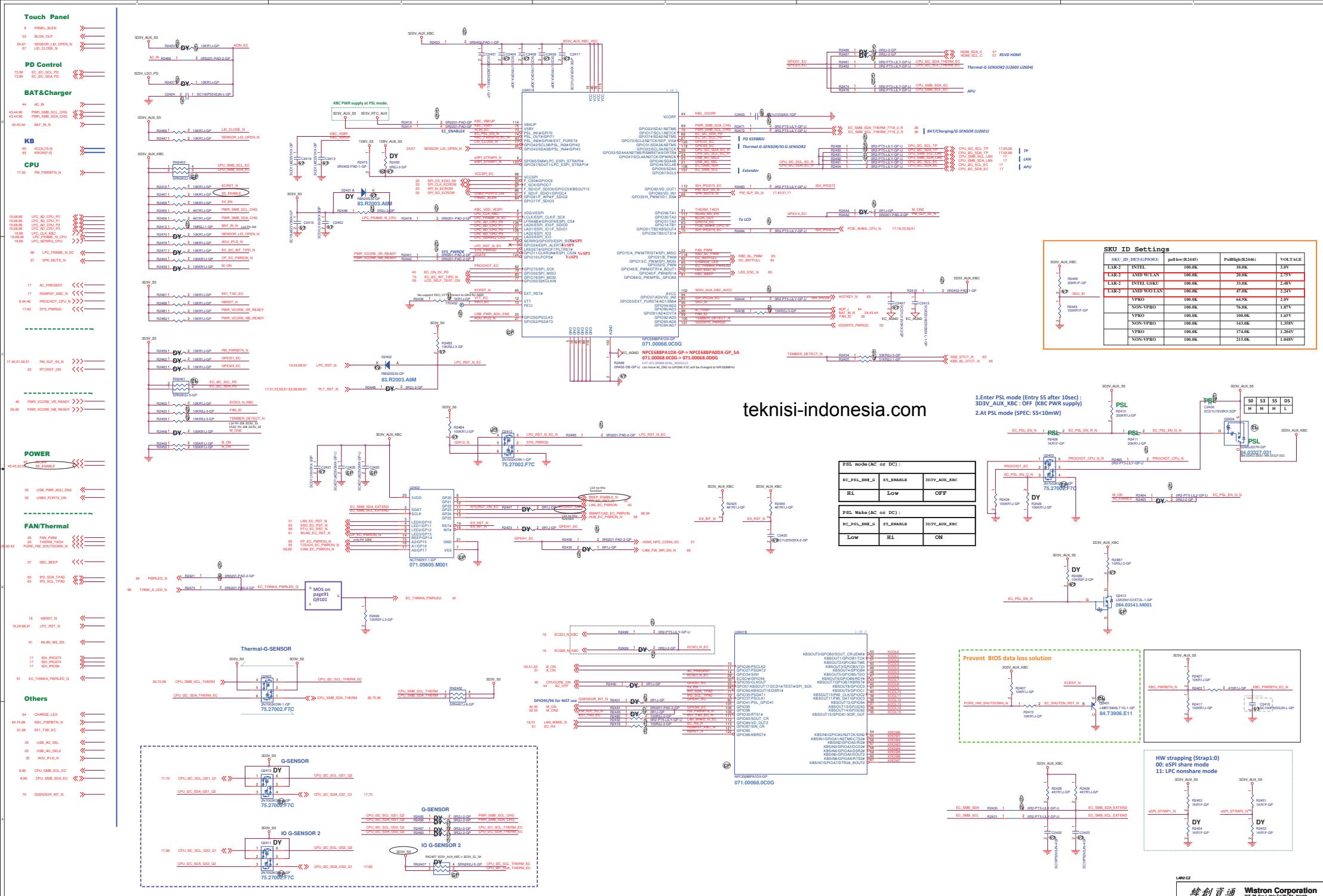
Date: Wednesday, July 28, 2021

Sheet 22 of 106

(Blanking)

LAR2 CZ

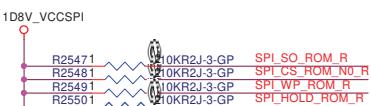
緯創資通		Wistron Corporation
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.
Title		
CPU (RSVD)		
Size A4	Document Number	Rev -2
LAR-2 CZ		Date: Wednesday, July 28, 2021
Sheet 23 of 106		



Main Func = SPI Flash

SPI FLASH ROM1 (32MByte) for BIOS

24 SPI_CLK_ECROM
24 SPI_SI_ECROM
24 SPI_CS_ECIO_NO
24 SPI_SO_ECROM



For ECRST# issue
U2502 JUST EVT ASM
RSVD

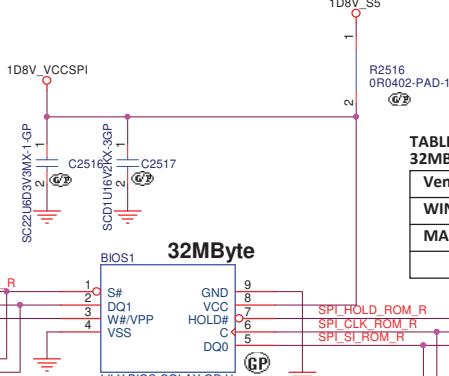
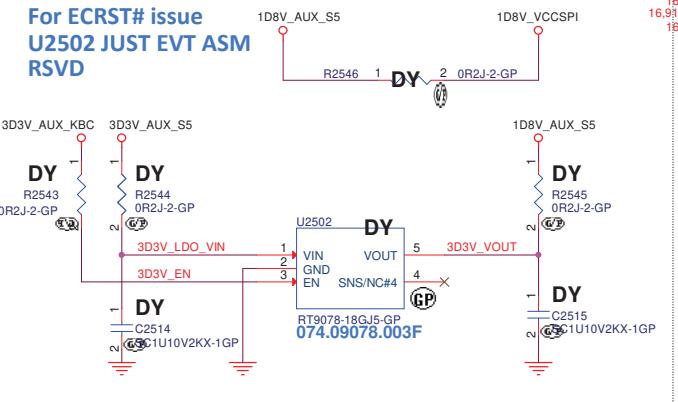


TABLE BIOS1
32MB WSOP 8

Vender	Vender P/N	Wistron P/N	
WINBOND	W74M25JWZEIQ	072.07425.0001	RPMC
MACRONIX	MX77U25650FZI42	072.77256.0A01	RPMC

1D8V_S5
R2516 0R0402-PAD-1-GP

1D8V_VCCSPI
R2517 10KR2J-3-GP

C2516 10KR2J-3-GP

C2517 10KR2J-3-GP

SC22U6P3MX-1GP

R2518 10KR2J-3-GP

R2519 10KR2J-3-GP

R2520 10KR2J-3-GP

1D8V_S5
R2521 10KR2J-3-GP

1D8V_VCCSPI
R2522 10KR2J-3-GP

1D8V_VCCSPI
R2523 10KR2J-3-GP

1D8V_VCCSPI
R2524 10KR2J-3-GP

1D8V_VCCSPI
R2525 10KR2J-3-GP

1D8V_VCCSPI
R2526 10KR2J-3-GP

1D8V_VCCSPI
R2527 10KR2J-3-GP

1D8V_VCCSPI
R2528 10KR2J-3-GP

1D8V_VCCSPI
R2529 10KR2J-3-GP

1D8V_VCCSPI
R2530 10KR2J-3-GP

1D8V_VCCSPI
R2531 10KR2J-3-GP

1D8V_VCCSPI
R2532 10KR2J-3-GP

1D8V_VCCSPI
R2533 10KR2J-3-GP

1D8V_VCCSPI
R2534 10KR2J-3-GP

1D8V_VCCSPI
R2535 10KR2J-3-GP

1D8V_VCCSPI
R2536 10KR2J-3-GP

1D8V_VCCSPI
R2537 10KR2J-3-GP

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1D8V_VCCSPI
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1D8V_VCCSPI
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1D8V_VCCSPI
R2541 10KR2J-3-GP

1D8V_VCCSPI
R2542 10KR2J-3-GP

1D8V_VCCSPI
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1D8V_VCCSPI
R2544 10KR2J-3-GP

1D8V_VCCSPI
R2545 10KR2J-3-GP

1D8V_VCCSPI
R2546 10KR2J-3-GP

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1D8V_VCCSPI
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R2557 10KR2J-3-GP

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R2558 10KR2J-3-GP

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1D8V_VCCSPI
R2686 10KR2J-3-GP

1D8V_VCCSPI
R2687 10KR2J-3-GP

1D8V_VCCSPI
R2688 10KR2J-3-GP

Main Func = Thermal Sensor

Thermal Sensor

Sensor	Target
U2601	SSD
U2603	DIMM
Q2601	CPU
Q2602	Charger

Close to PL4401(Charger)



Close to CPU (CPU1)

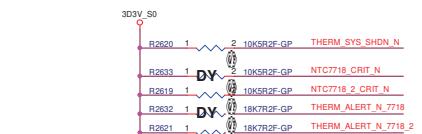


CPU backside or inside the socket

CPU TEMP:
H_THERMDA and H_THERMDC routing 10mil trace width
and spacing. Locate Capacity near Thermal diode.

ALERT# / T_CRT# Pull-up Resistor v.s. Alert temperature (°C)

NCT7718W Table:		2.0K	7.5K	10.5K	14.0K	18.7K
R2630	\ R2619 (R1633)	75	87	97	107	117
7.5K	90	89	99	109	119	
10.5K	105	81	95	101	111	121
14.0K	110	88	93	103	113	123
18.7K	115	85	95	105	115	125

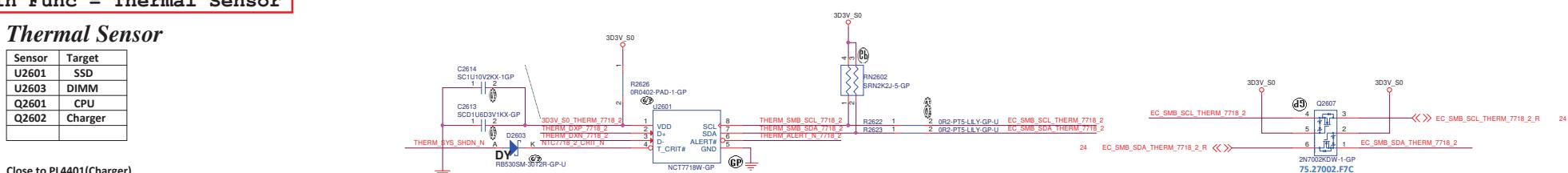


ALERT# point hardware power-on setting

The default value could be set after power up 100ms by different pull-up resistor of ALERT# pin:

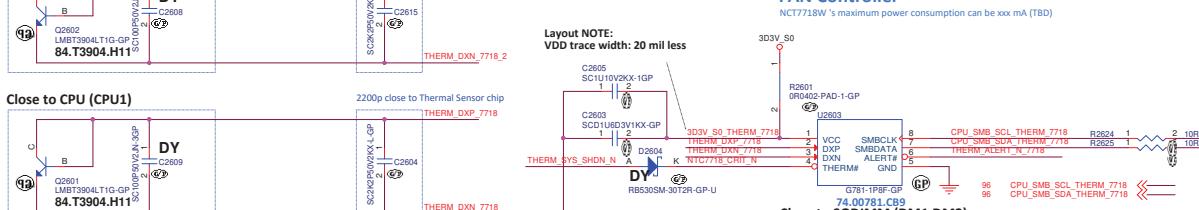
PULL-UP RESISTOR	TEMPERATURE (°C)
2kΩ	75
7.5kΩ	90
10.5kΩ	100
14kΩ	105
18.7kΩ	110

ID	Target	Function
RT2601		
RT2602		
RT2603		
RT2605		
RT2606		
RT2607		
RT2608		

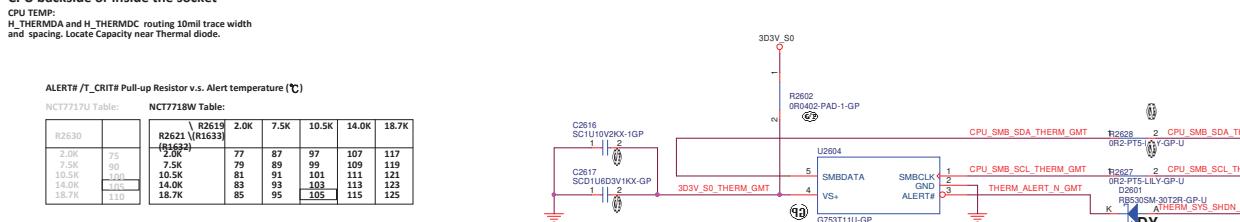


Close to SSD (SSD1)

Layout NOTE: VDD trace width: 20 mil less



Close to SODIMM (DM1,DM2)



Close to Charger



24.40.42 PURE_HW_SHUTDOWN_N

DY R2610 10KR2J-3-GP SC01UD3V1KX-1GP 064.27002.0L31

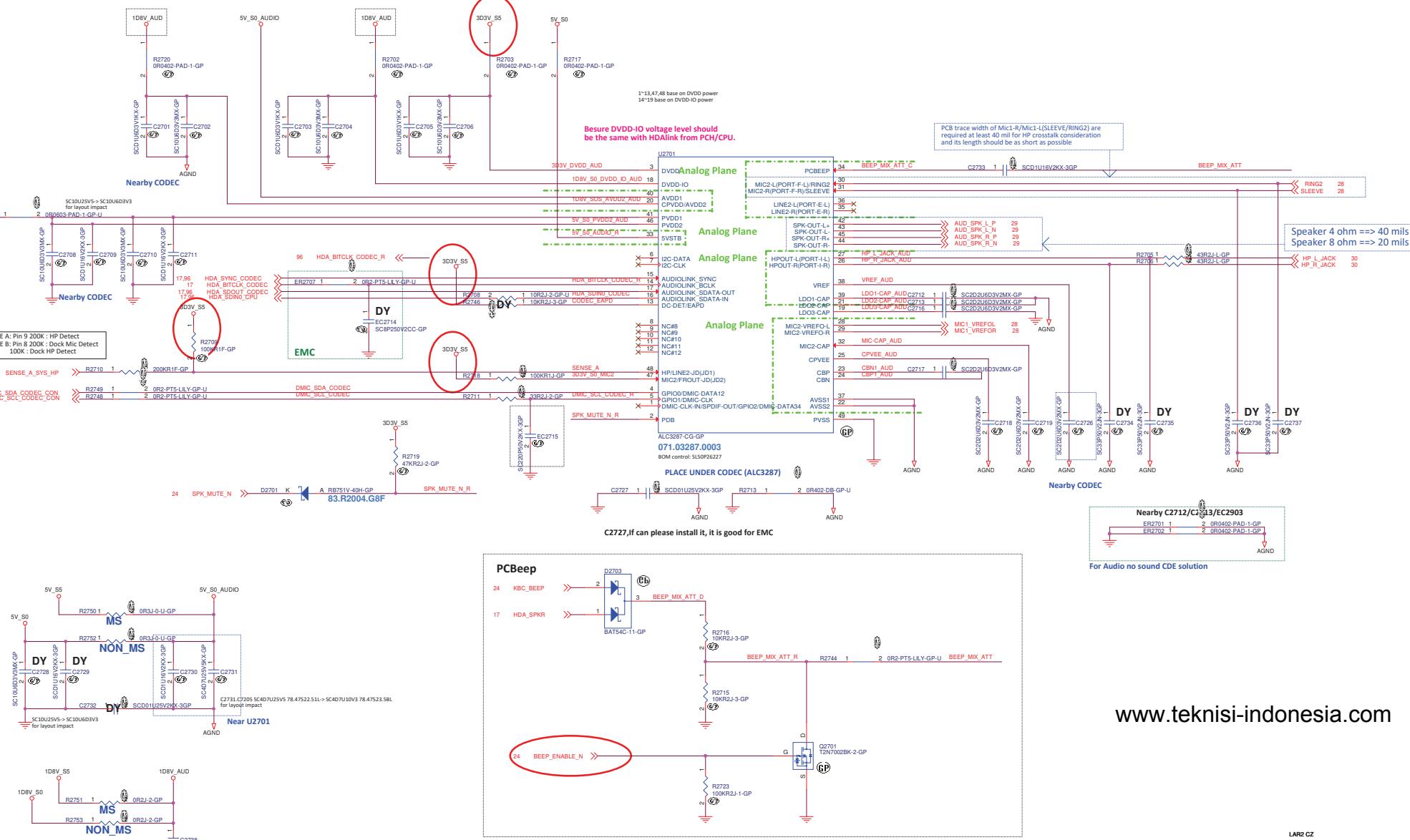
DY C2607 10KR2J-3-GP R2608 10KR2J-3-GP

THERM_SYS_SHDN_N R2608 10KR2J-3-GP

PWR_VCORE_NB_READY 24.46

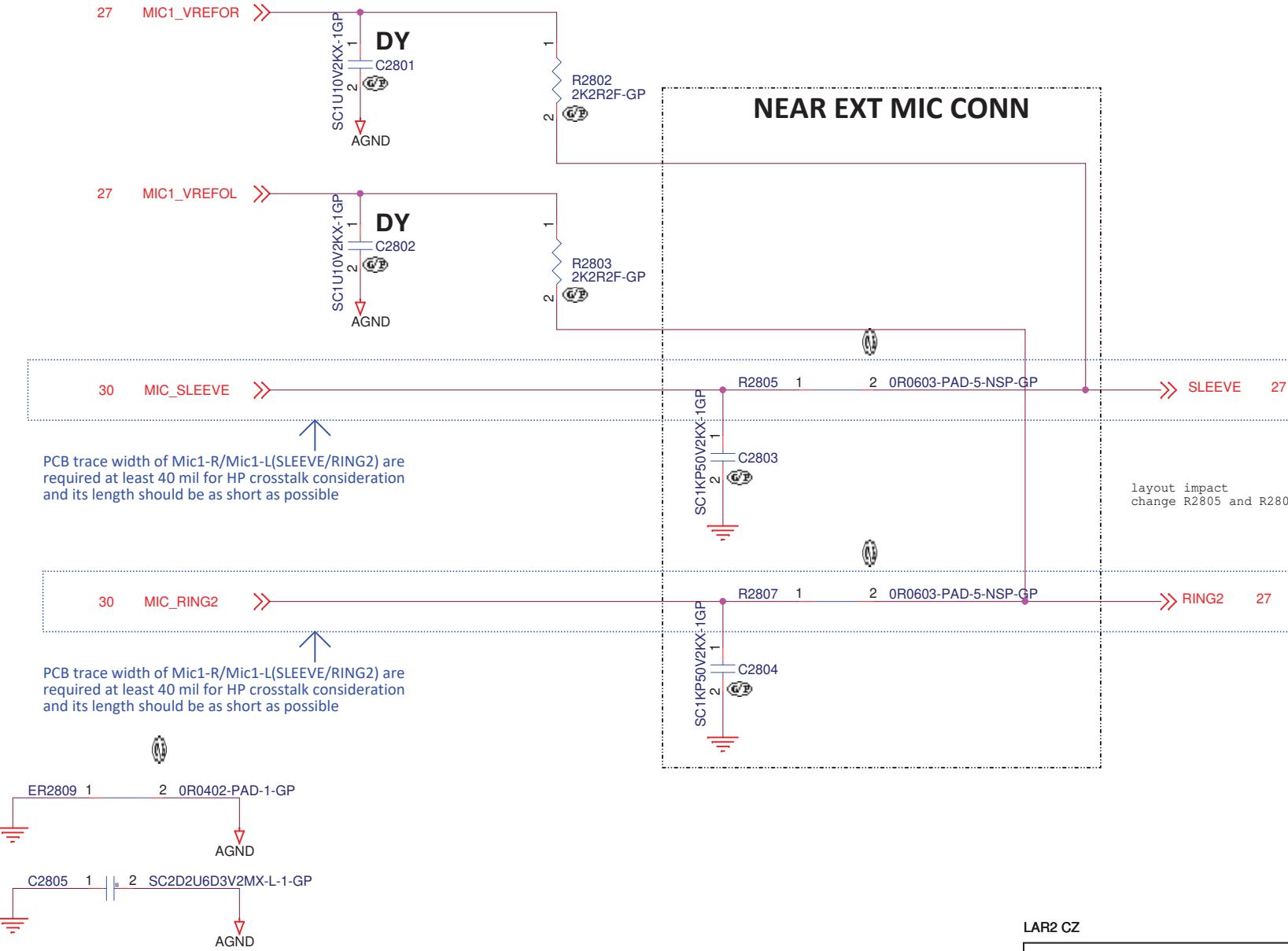
RT_COMP_OUT RT_COMP_OUT_R

PURE_HW_SHUTDOWN_N



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LAR2 CZ	Wistron Corporation 2F, 68, Sec. 1, Hsin-Tai Rd., Hsin-Chih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	AUDIO (CODEC ALC3287)	
Size Custom	Document Number	LAR-2 CZ
		Rev -2

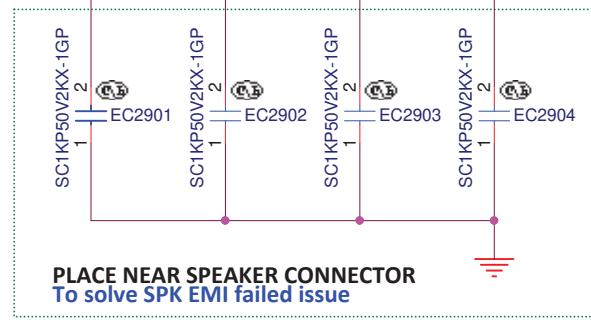


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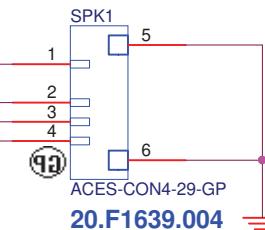
Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	AUDIO (MIC I/F)
Size	Document Number
A4	LAR-2 CZ
Date:	Wednesday, July 28, 2021
Sheet	28 of 106
Rev	-2

Main Func = AUDIO

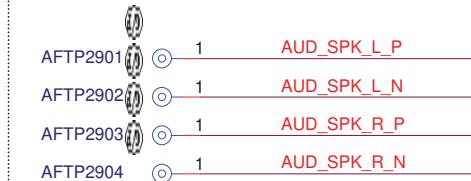
27 AUD_SPK_R_P
27 AUD_SPK_R_N
27 AUD_SPK_L_N
27 AUD_SPK_L_P



SPEAKER CONN



Near SPK1 (SPEAKER)



LAR2 CZ

緯創資通

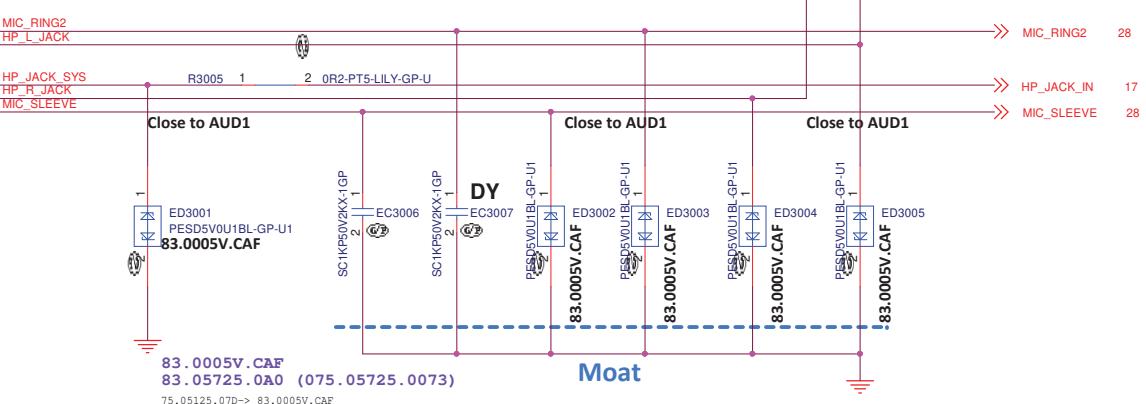
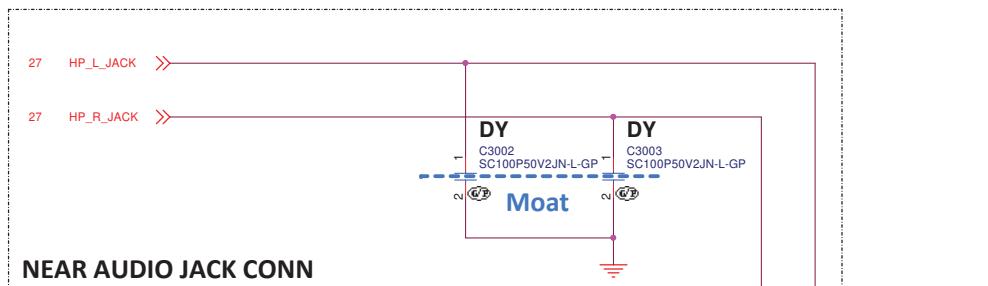
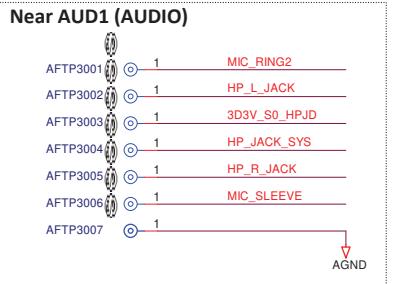
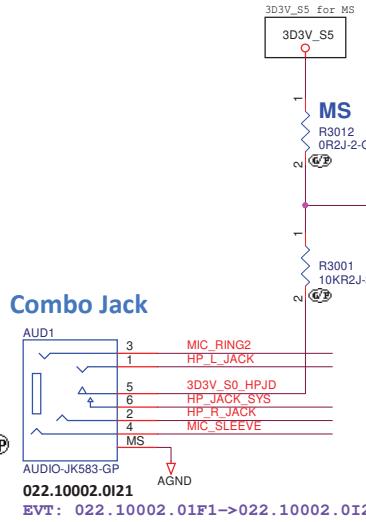
Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title **AUDIO (SPEAKER)**

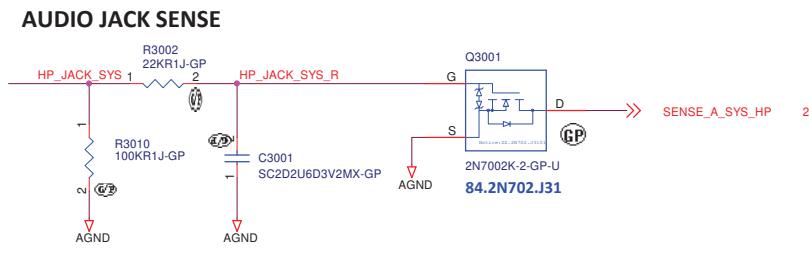
Size A4 Document Number **LAR-2 CZ** Rev **-2**

Date: Wednesday, July 28, 2021

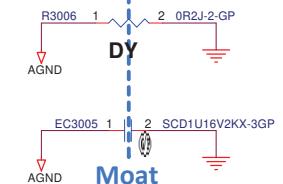
Sheet 29 of 106



AUDIO JACK SENSE CLOSE TO CODEC
6-10 mil trace recommend

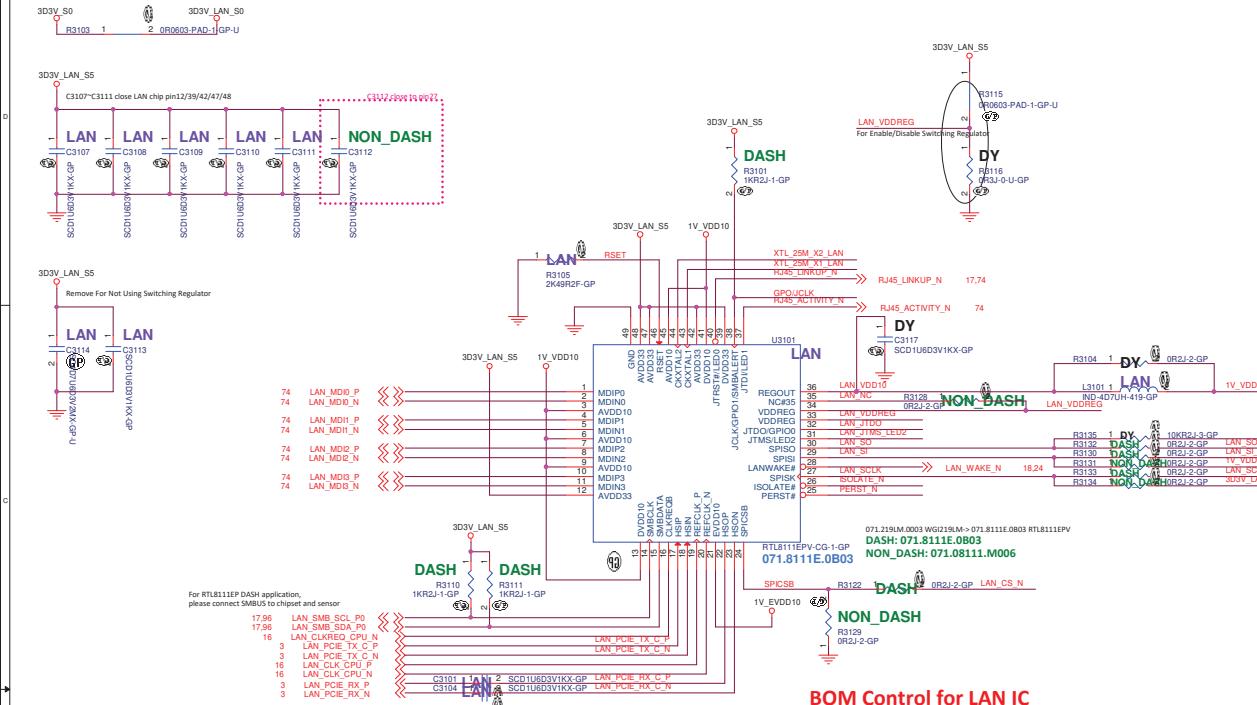


HGNDA/HGNDB trace width >70mil, changed to sharp will be better.



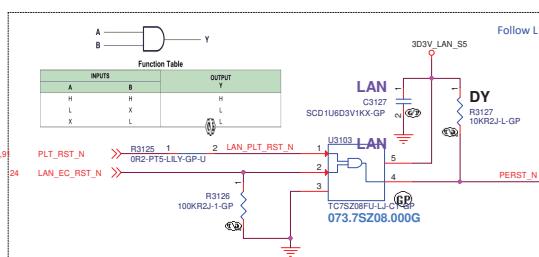
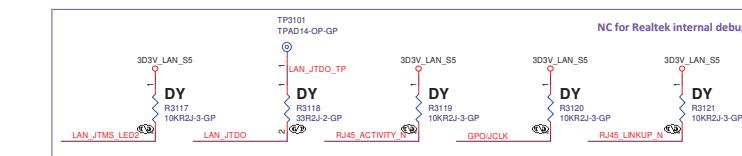
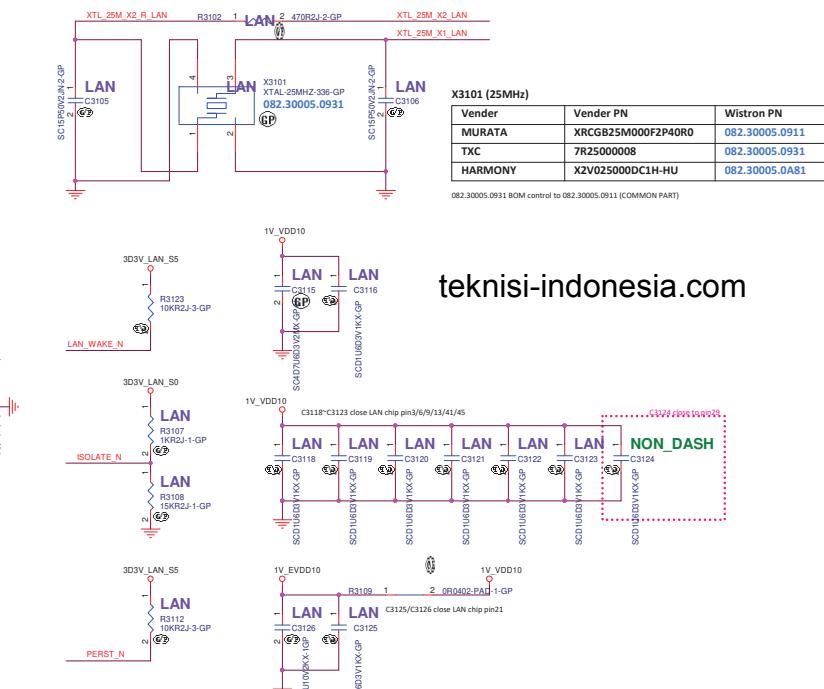
LAR2 CZ

Main Func = LAN



BOM Control for LAN

Table of LAN IC Option	
	Del "DUMMY" Property for BOM
W/ LAN DASH	NON_DASH
	LAN IC P/N : 071.8111.0003 REALTEK / RT8111EPV
W/ LAN NON_DASH	DASH
	LAN IC P/N : 071.08111.M006 REALTEK / RTL8111DRB
W/O LAN	LAN,DASH, NON-DASH
	LAN IC P/N : 071.08111.M006 REALTEK / RTL8111DRB



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LAR2 CZ

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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title
LAN (RSVD)

Size
A4 Document Number

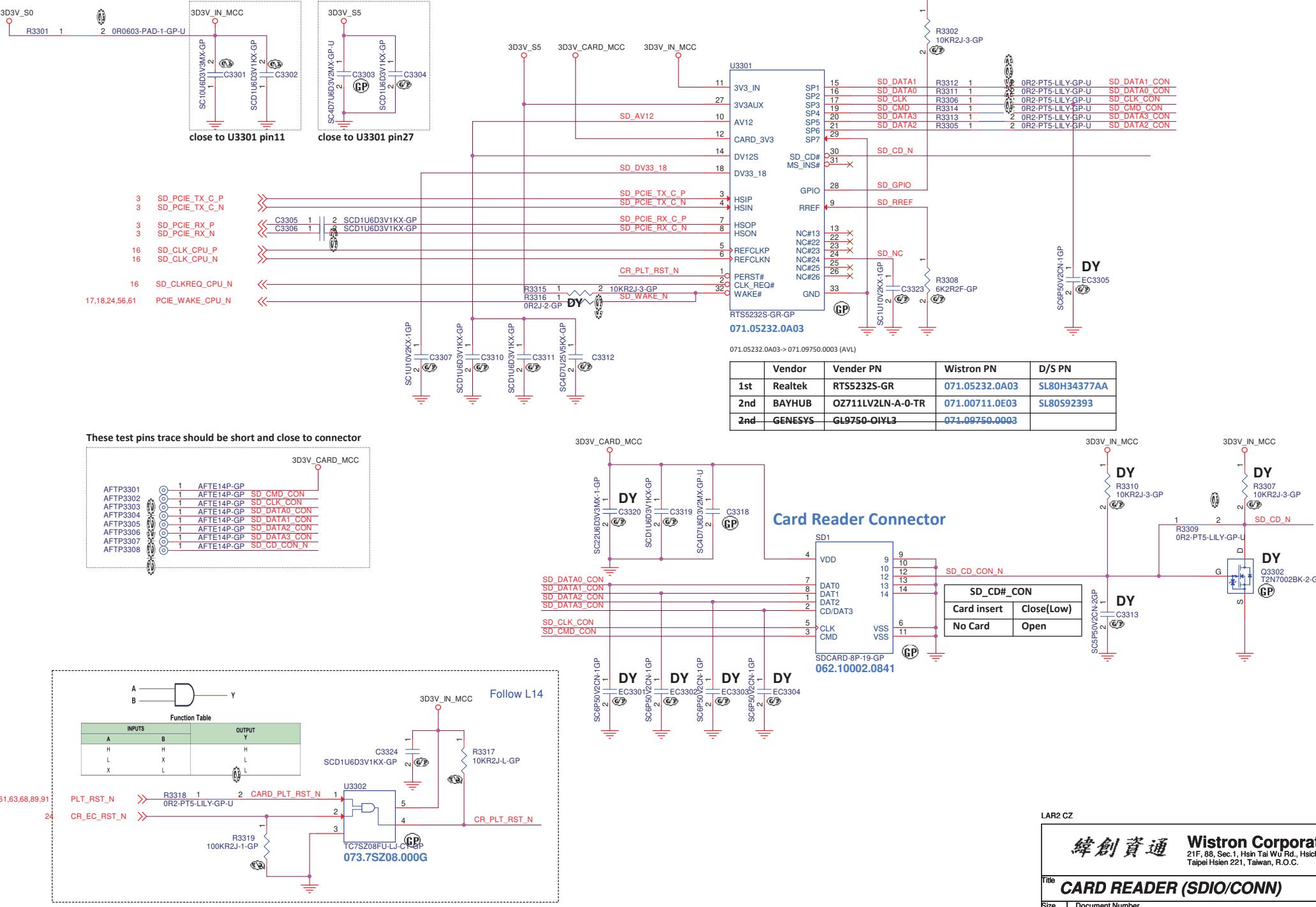
LAR-2 CZ

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-2

Date: Wednesday, July 28, 2021

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Main Func = Card Reader



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Taipei Hsien 221, Taiwan, R.O.C.

Title **USB (RSVD)**

Size
A4 Document Number

LAR-2 CZ

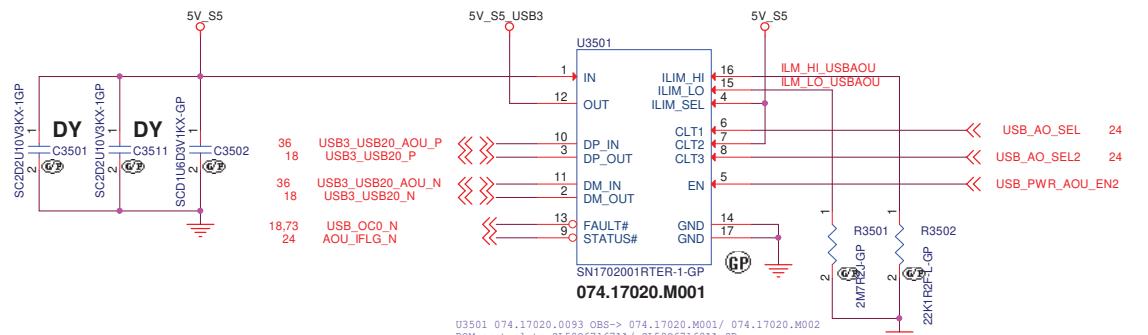
Rev
-2

Date: Wednesday, July 28, 2021

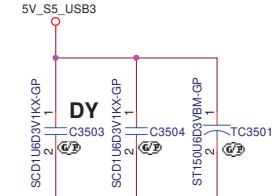
Sheet 34 of 106

Main Func = USB Charger

For USB3.0 System Port3 (For AOU)



Layout Note: Close USB3.0 Port3



Current Limit Target : 2.3A (2.1-2.45A)

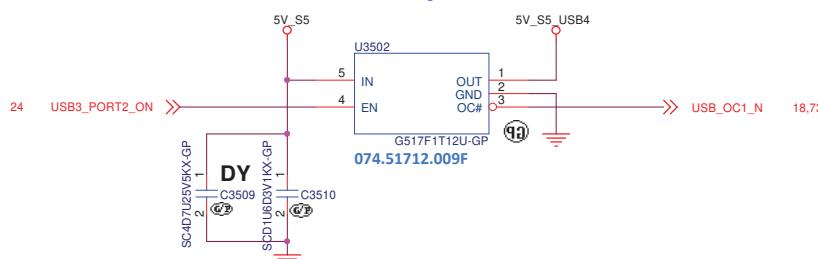
TABLE of AOU port: U3501

	Vendor	Vendor P/N	Wistron P/N
1st	TI	SN1702001RTER (PG 1.1)	074.17020.0093
2nd	Pericom	PI5USB2546HZHEX	074.52546.0D73

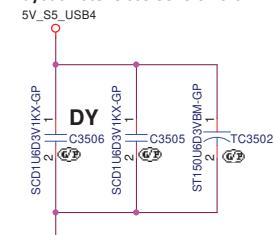
SL500Q67167AA

SL500Q67168AA

For USB3.0 System Port4



Layout Note: Close USB3.0 Port4



Continous Current Limit 1.5A

TABLE of USB 3.0 port: U3502

	Vendor	Vendor P/N	Wistron P/N
1st	GMT	G517F1T12U	074.51712.009F
2nd	SILERGY	SY6288C20AAC	074.06288.007B

074.09742.0A9F

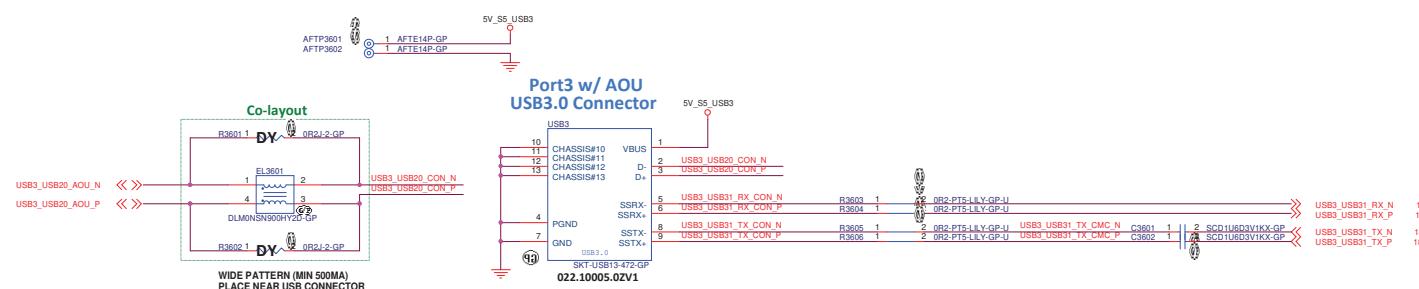
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074.06288.007B

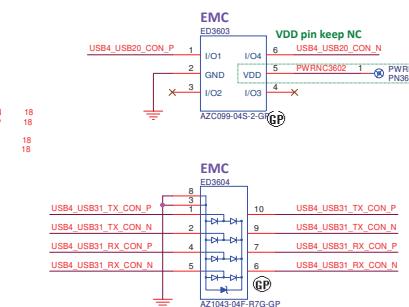
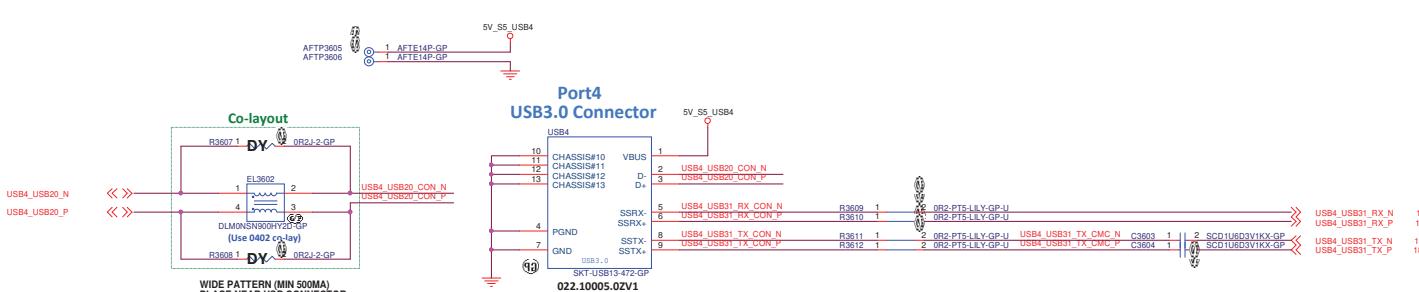
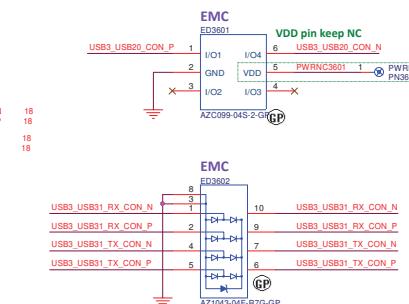
Please confirm VIH voltage level of G517F1T12U EN pin, DP_DIGON is 1.8V level.

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Main Func = USB3.0 Port3 w/ AOU
Main Func = USB3.0 Port4



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Title **USB (RSVD)**

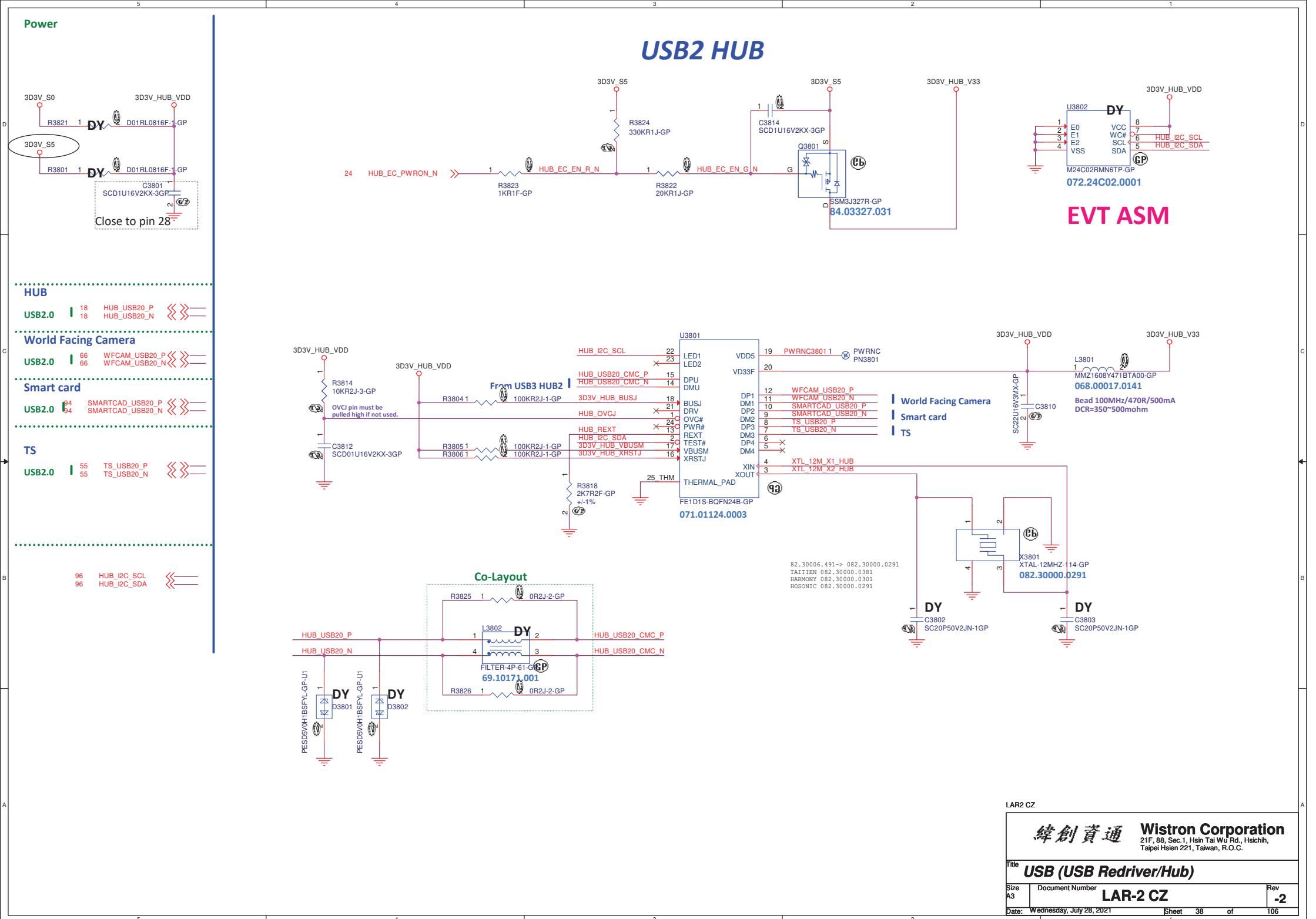
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Title

Sequence (RSVD)

Size
A4

Document Number

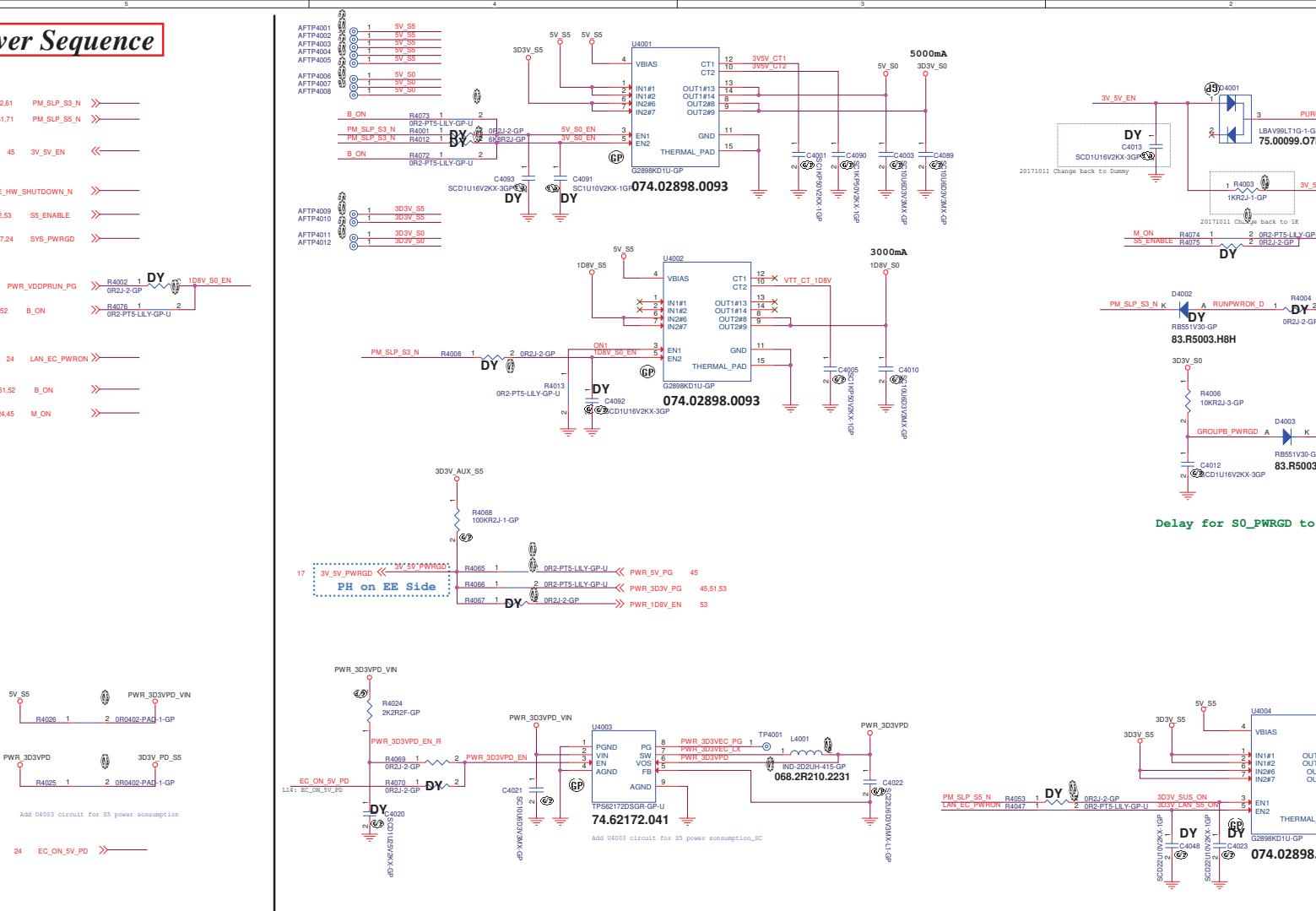
Rev
-2

LAR-2 CZ

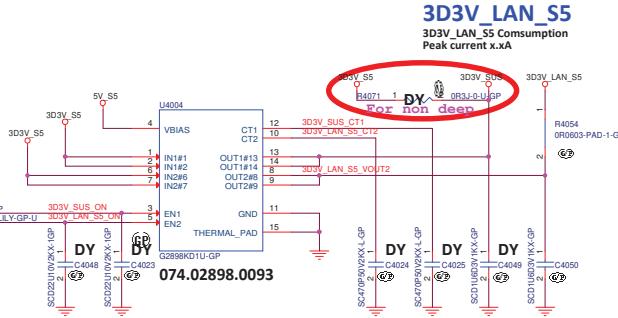
Date: Wednesday, July 28, 2021

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Power Sequence



Delay for S0_PWRGD to VCORE_EN



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Title

Sequence (RSVD)

Size
A4

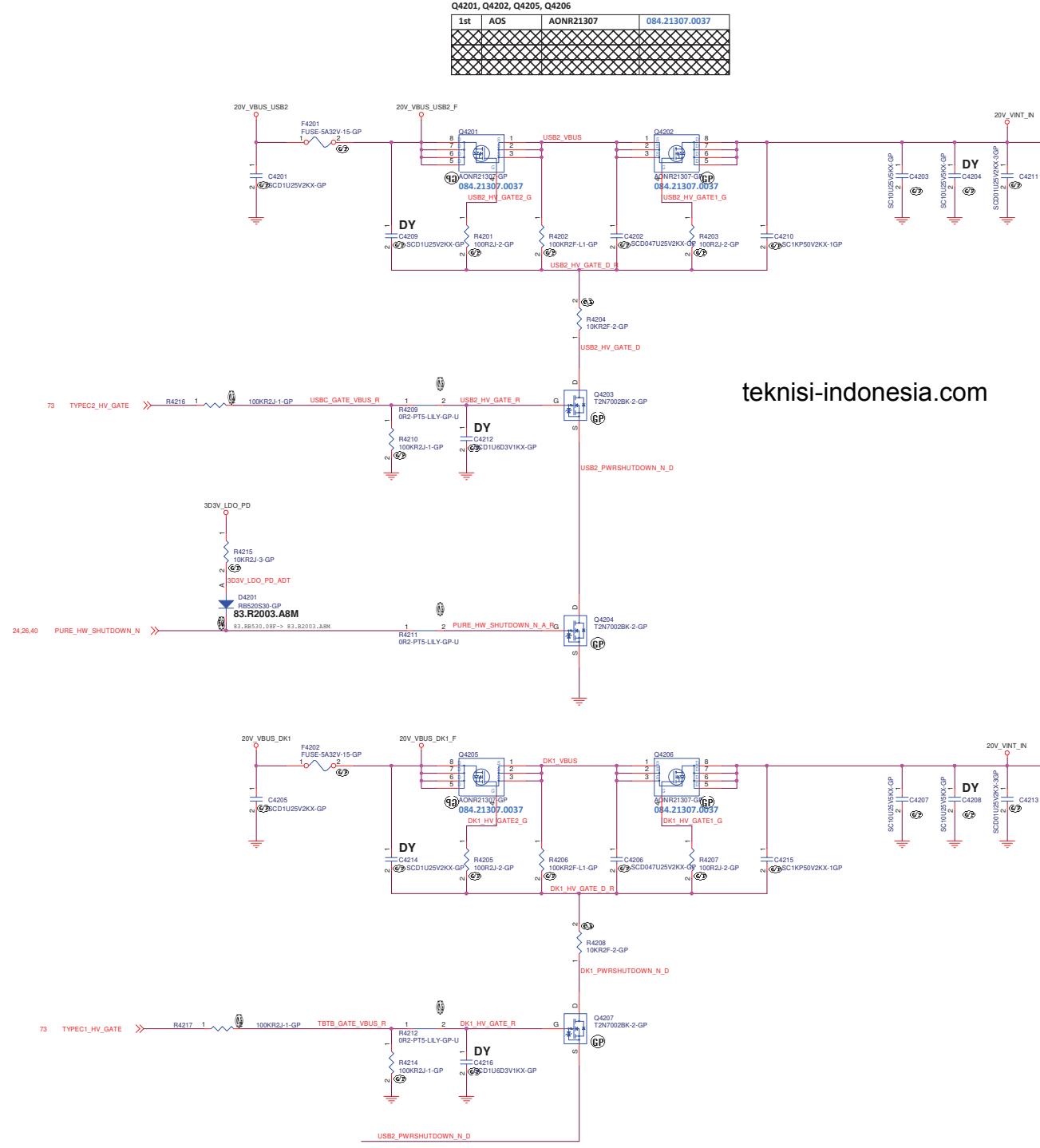
Document Number

Rev
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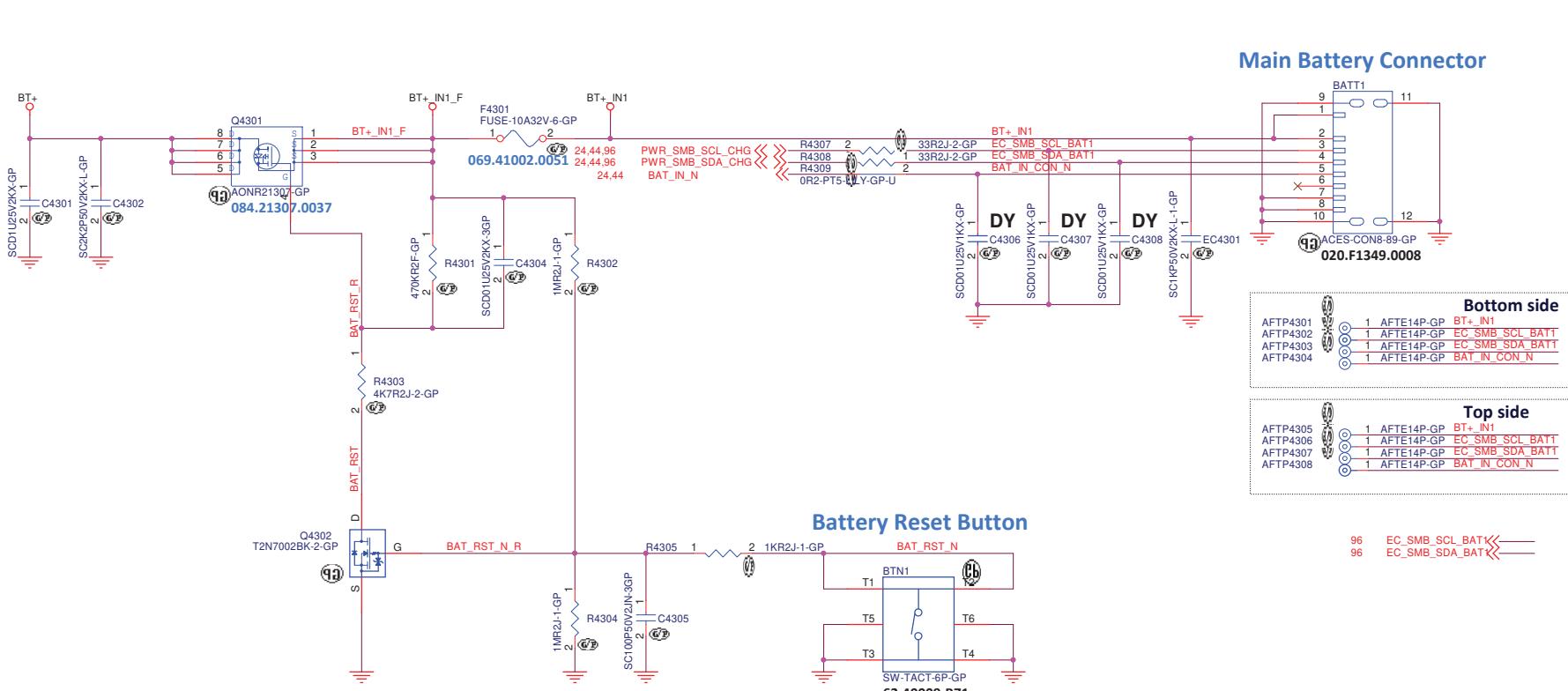
Date: Wednesday, July 28, 2021

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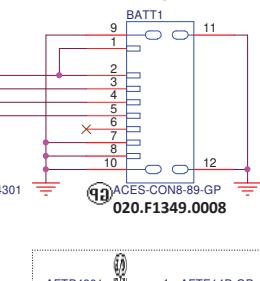


Main Func = M-BAT Input

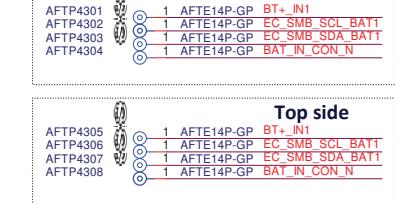
Main Func = BAT Reset



Main Battery Connector



Bottom side

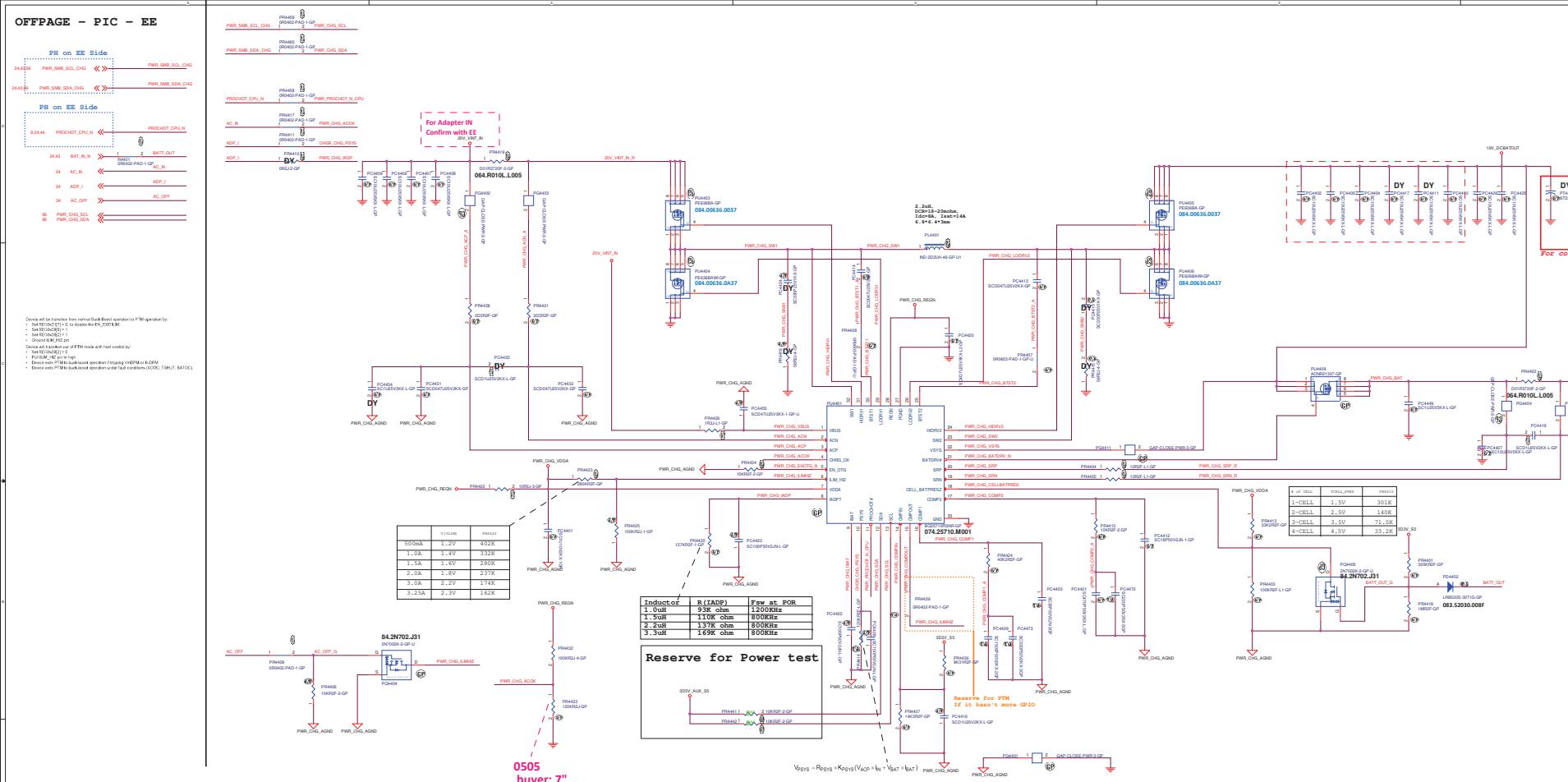


Top side

96 EC_SMB_SCL_BATT
96 EC_SMB_SDA_BATT

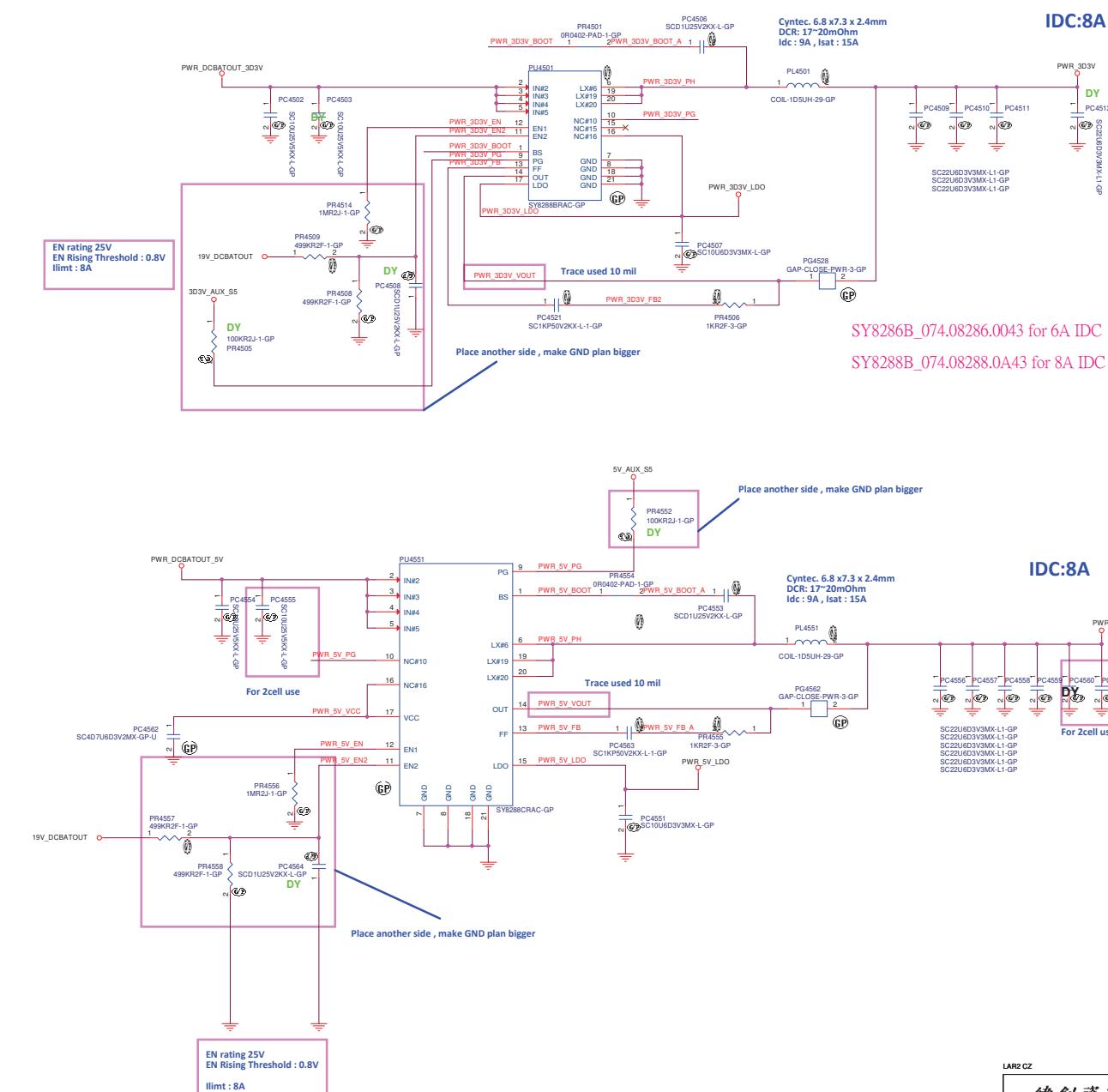
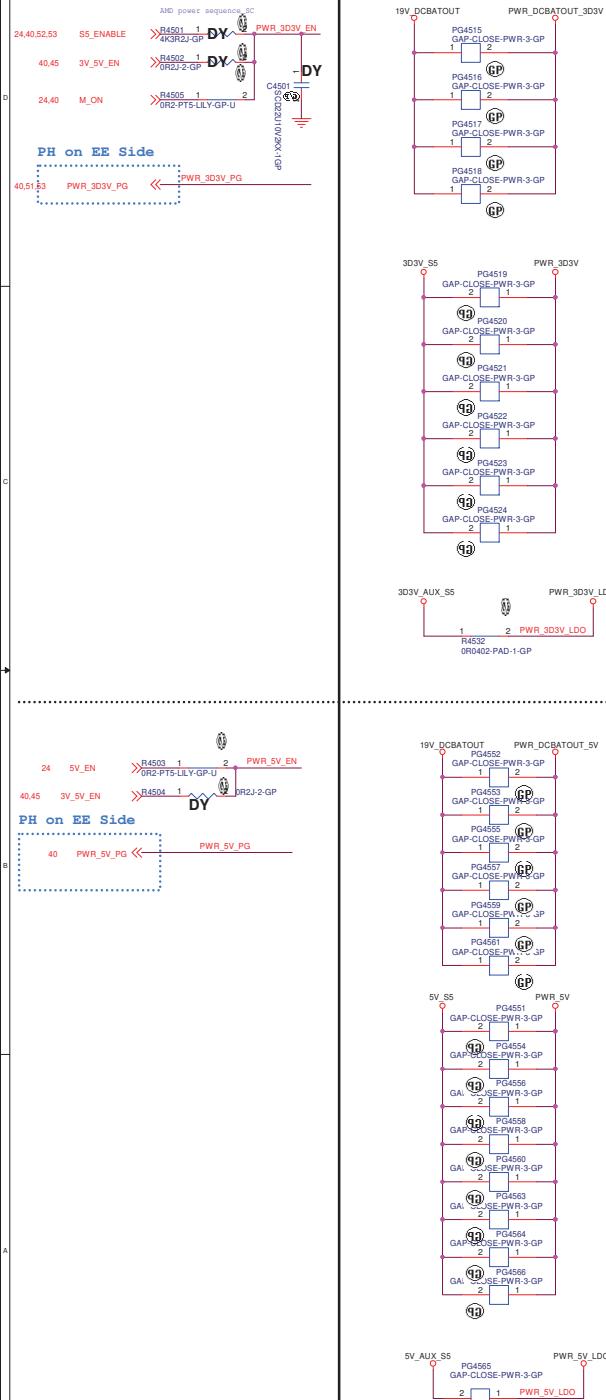
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緯創資通 Wistron Corporation	
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Title INT IO (ATX/ DC/ BATT Conn)	
Size A3	Document Number LAR-2 CZ
Date: Wednesday, July 28, 2021	Rev -2



OFFPAGE-Signal

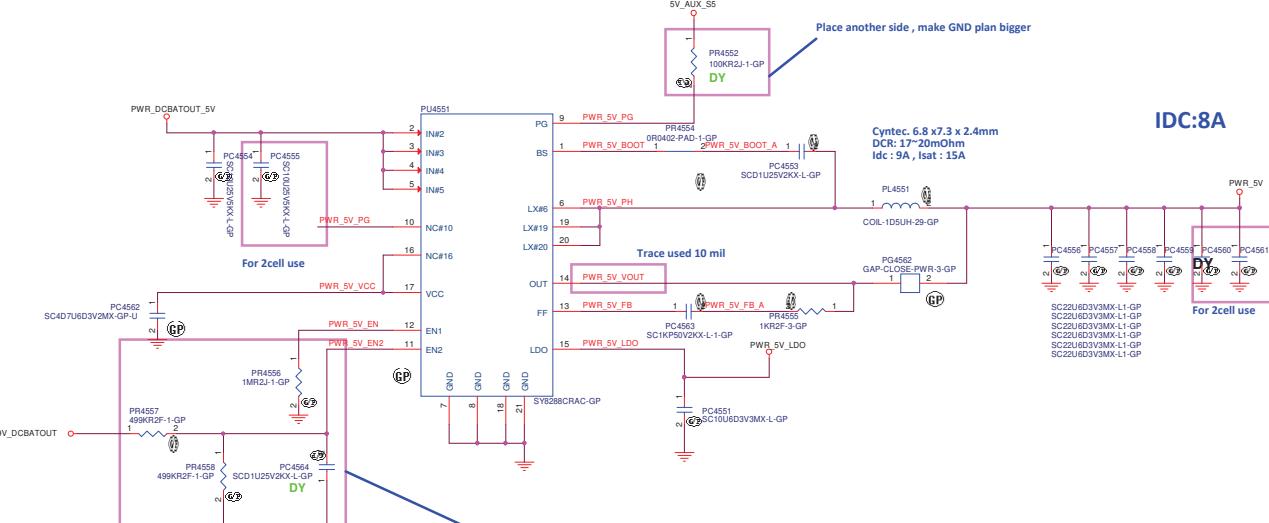
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SY8286B_074.08286.0043 for 6A IDC

SY8288B_074.08288.0A43 for 8A IDC

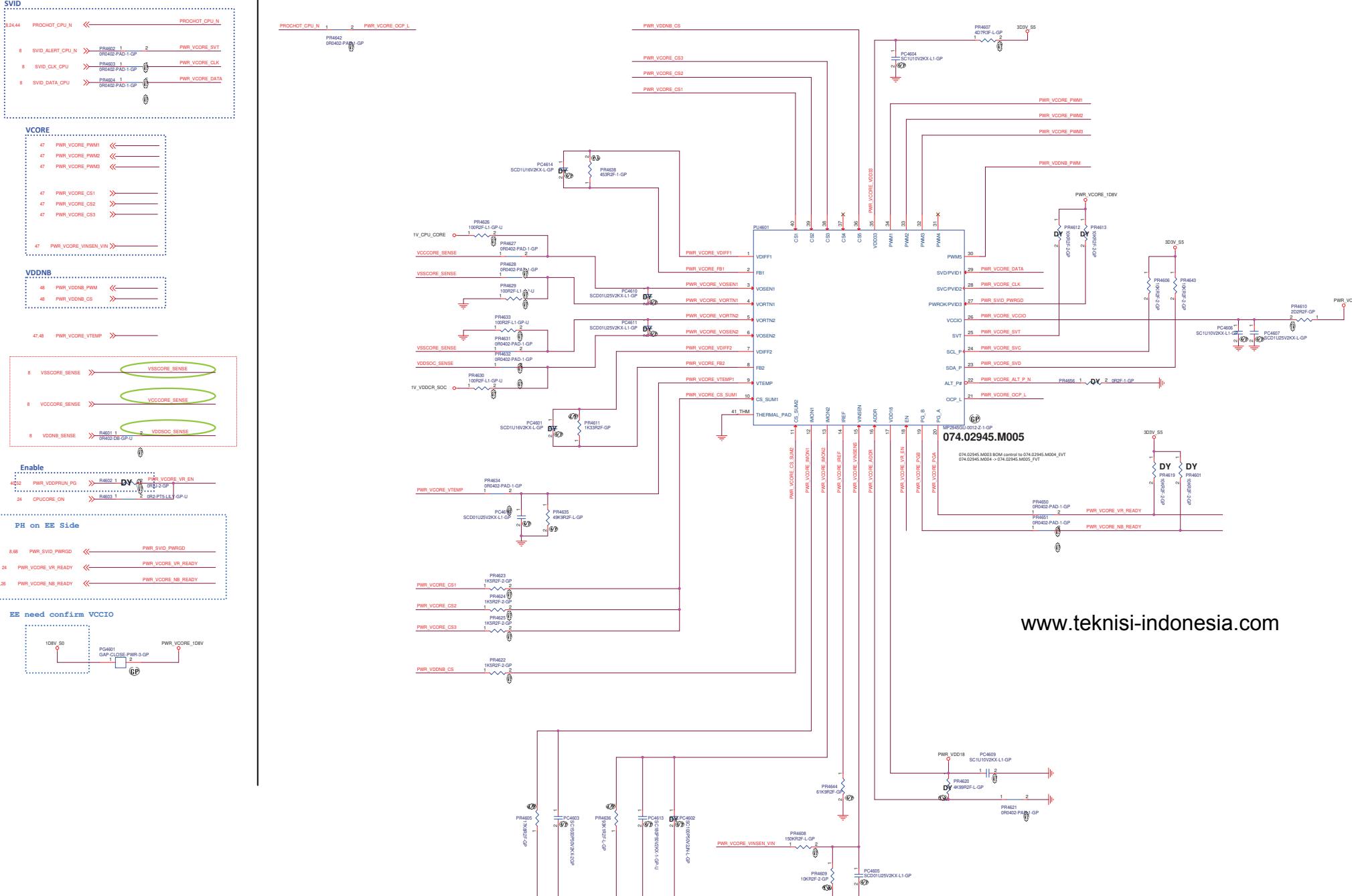
IDC:8A



Place another side , make GND plan bi

EN rating 25V
EN Rising Threshold : 0.8V

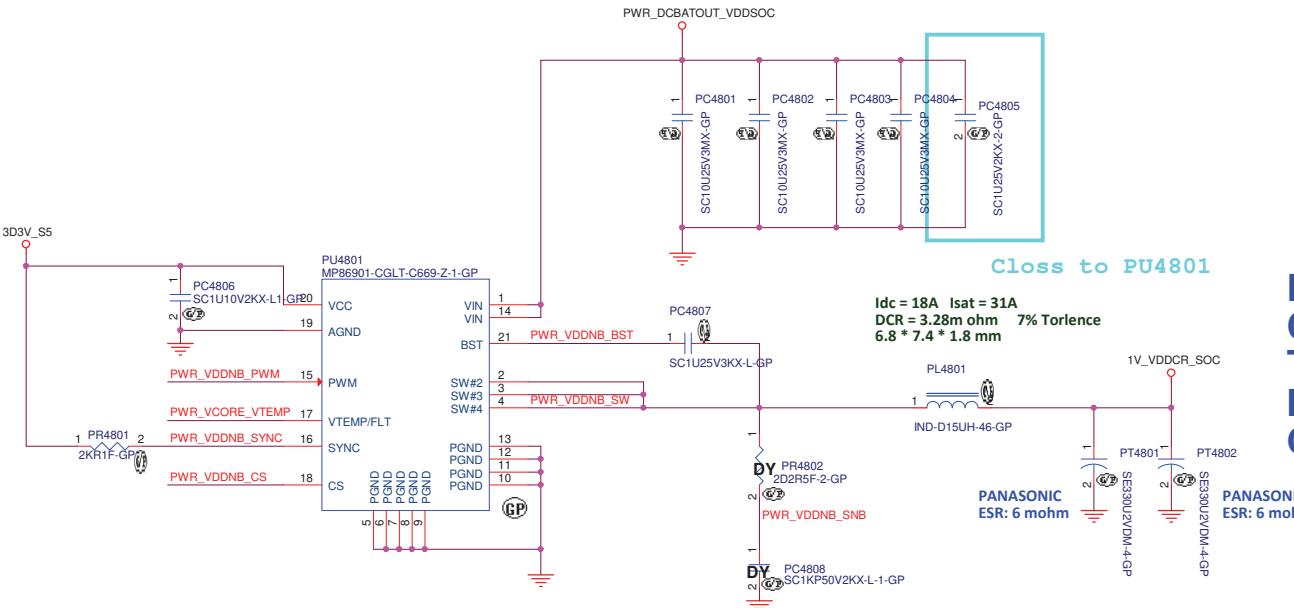
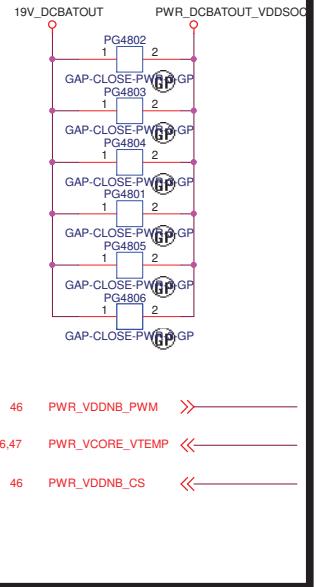
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OFFPAGE

Main Func = CPU_CORE



FP6_25W
CPU_SOC
TDC : 13A
Iccmax : 17A
OCP < 21.25A

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Size
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Title

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Size
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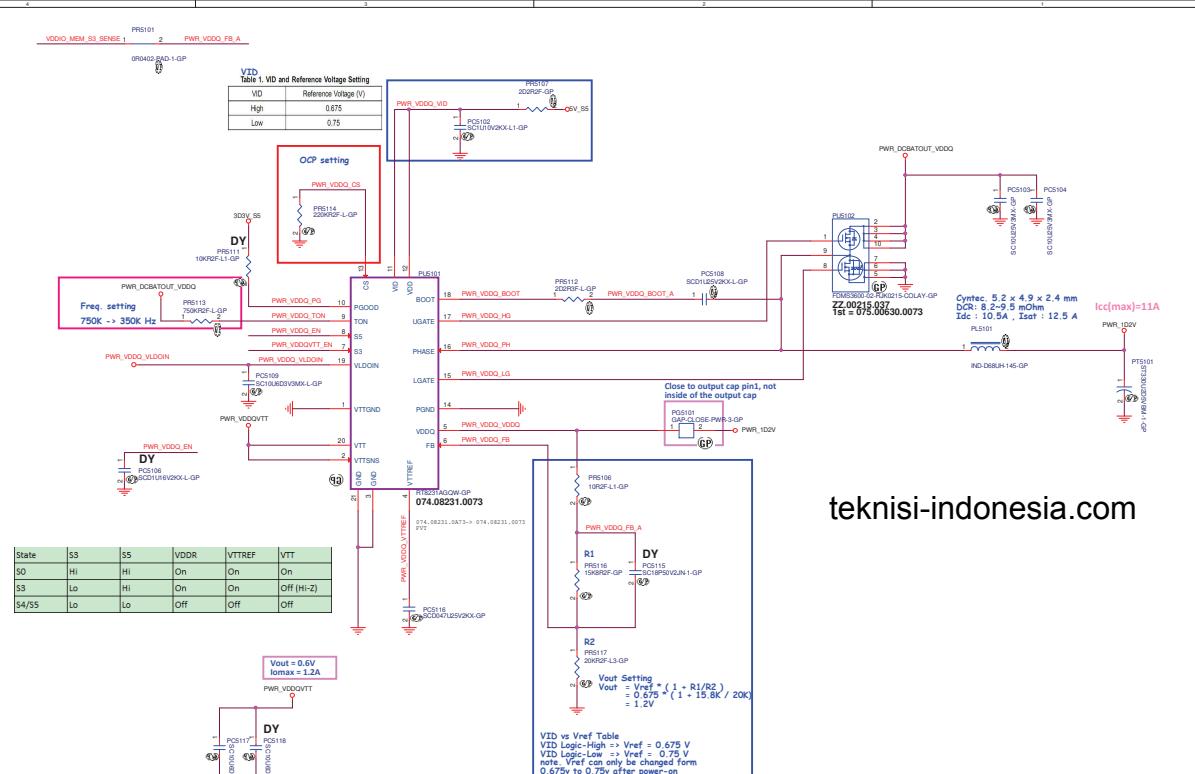
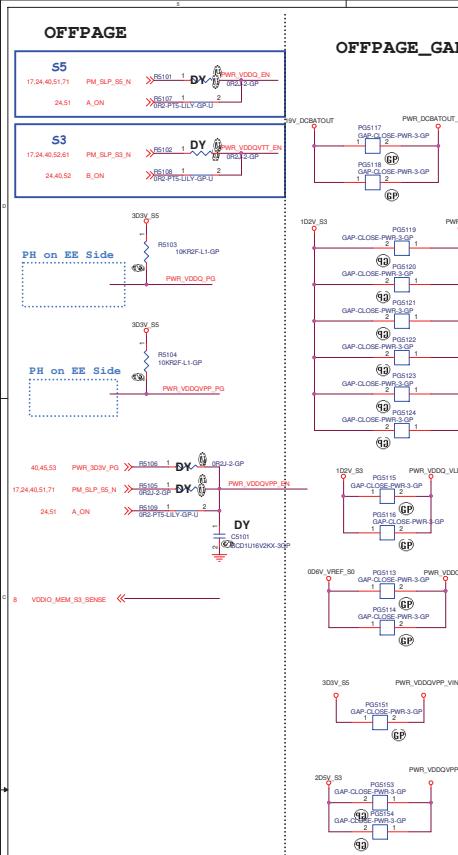
Document Number

Rev
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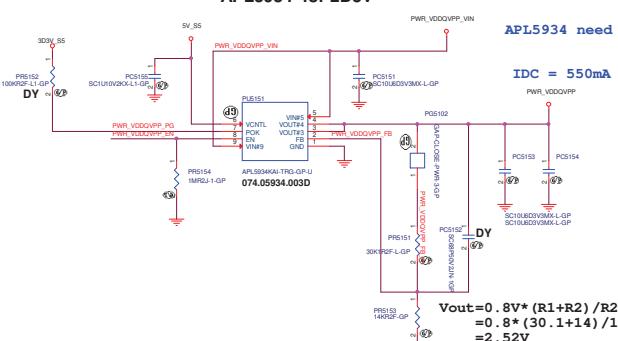
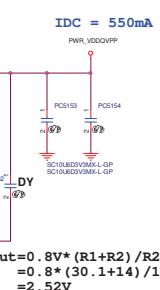
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Date: Wednesday, July 28, 2021

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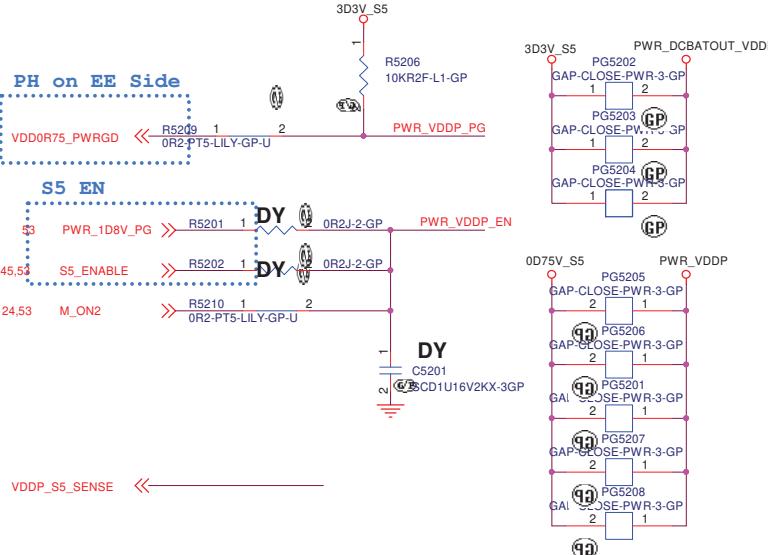
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APL5934 for 2D5V**APL5934 need < 1.8W**

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PR5202
1 PWR_VDDP_FB_A

OR0402-PAD-1-GP

PWR_DCBATOUT_VDDP

PGND

NC#5

LX

EN

SGND

PL5201
10R2F-L1-GP

PWR_VDDP_PH

PWR_VDDP_EN

DY

PC5204
SC22UD3V3MX-L1-GP

VIN

PGND

VDDP:0.756V
IDC:3A

PR5202
1 PWR_VDDP_FB_A

OR0402-PAD-1-GP

PWR_DCBATOUT_VDDP

PGND

NC#5

LX

EN

SGND

PL5201
10R2F-L1-GP

PWR_VDDP_PH

PWR_VDDP_EN

DY

PC5205
SC22UD3V3MX-L1-GP

VIN

PGND

VDDP:0.756V
IDC:3A

PR5208
1 PWR_VDDPRUN_FB_A

OR0402-PAD-1-GP

PWR_DCBATOUT_VDDPRUN

PGND

NC#5

LX

EN

SGND

PL5202
10R2F-L1-GP

PWR_VDDPRUN_PH

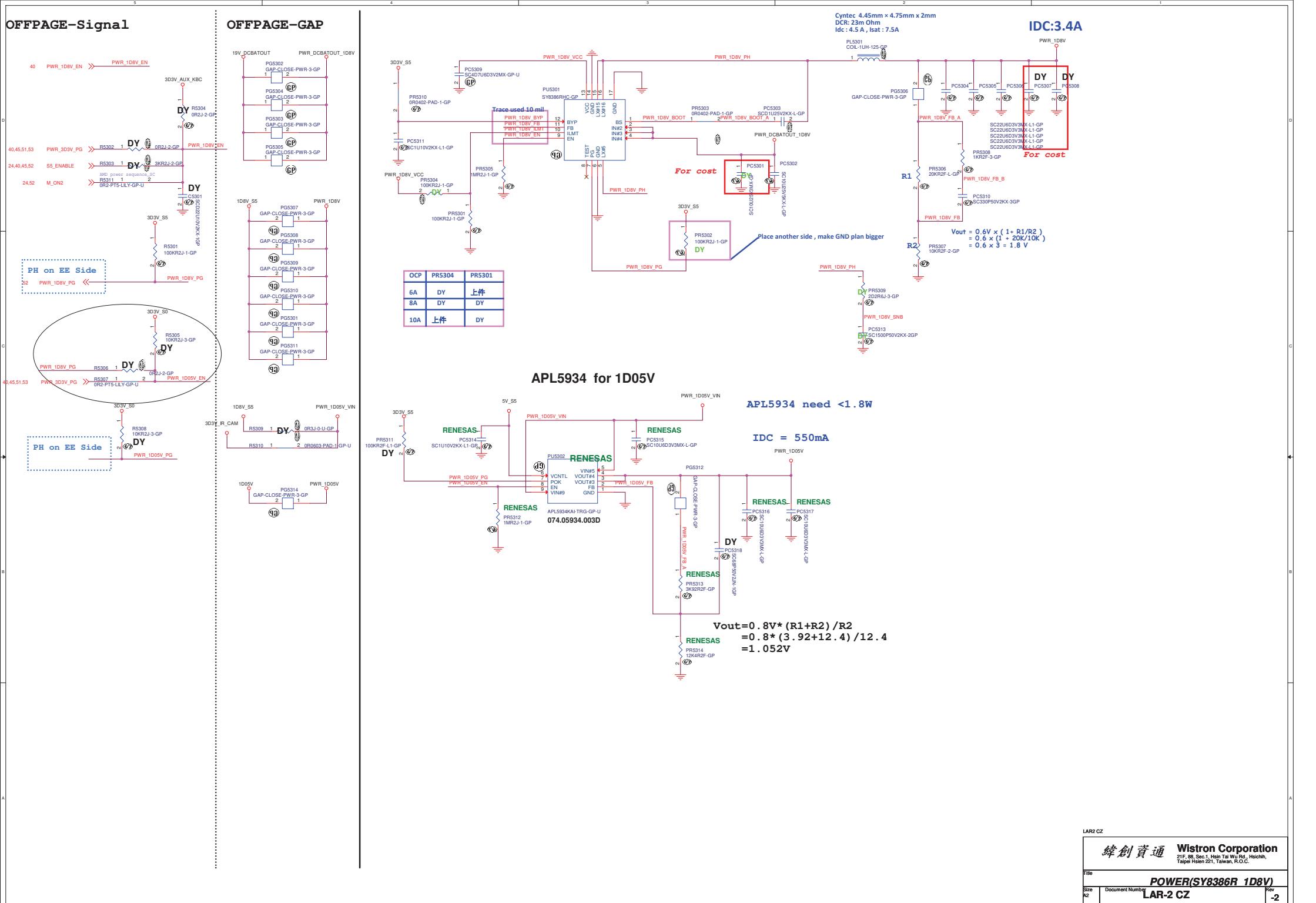
PWR_VDDPRUN_EN

DY

PC5209
SC22UD3V3MX-L1-GP

VIN

PGND



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Title

POWER(RSVD)

Size
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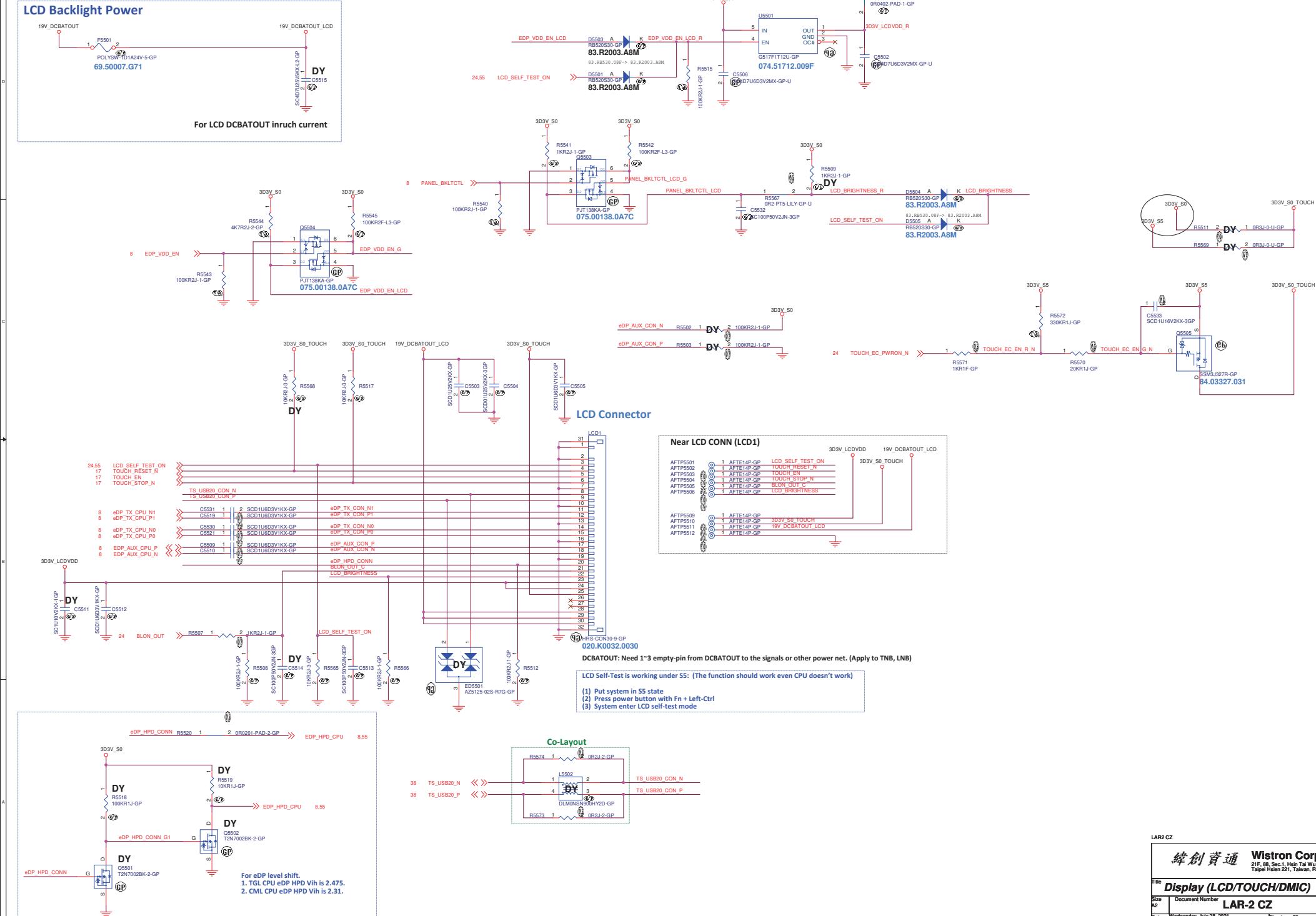
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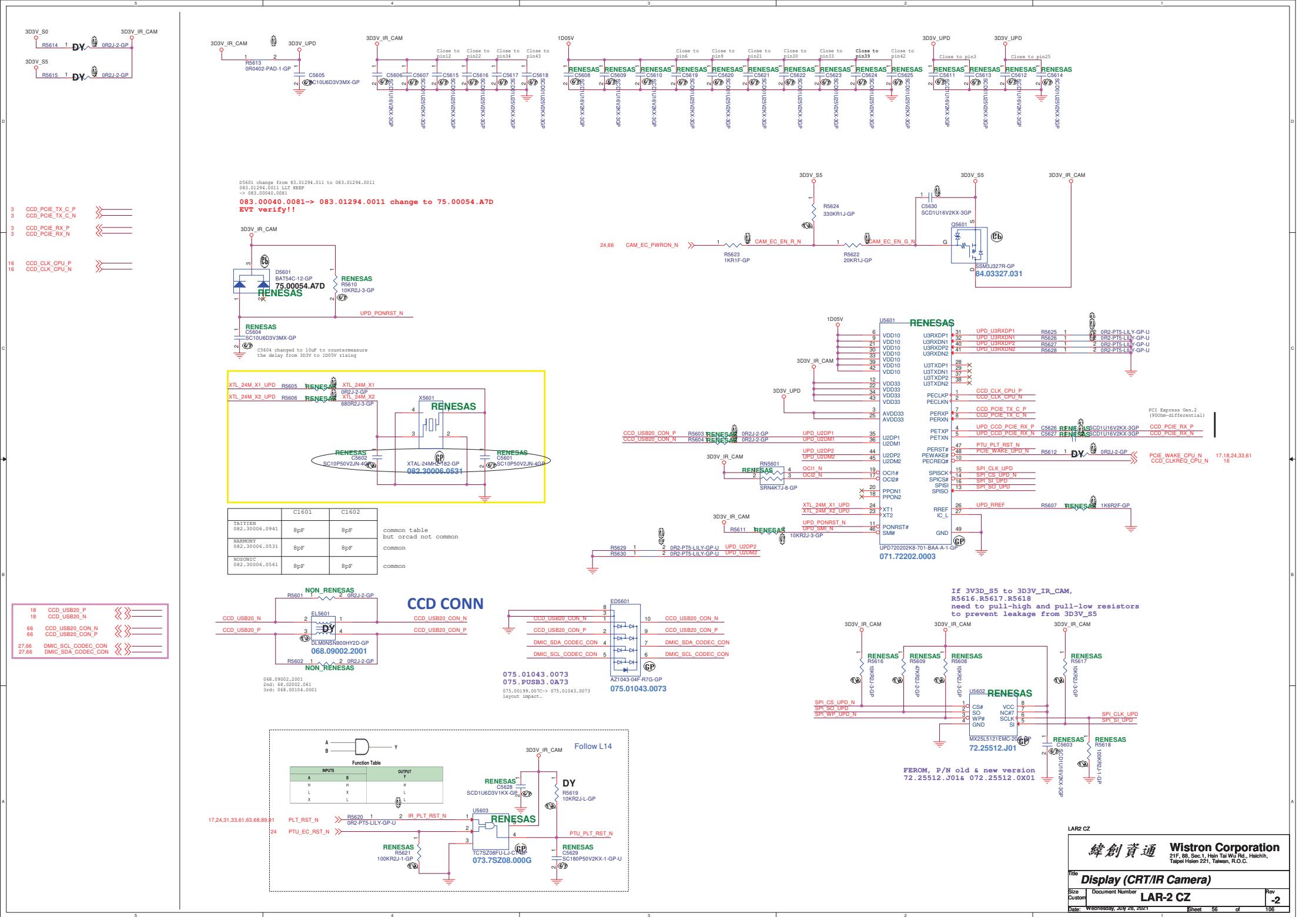
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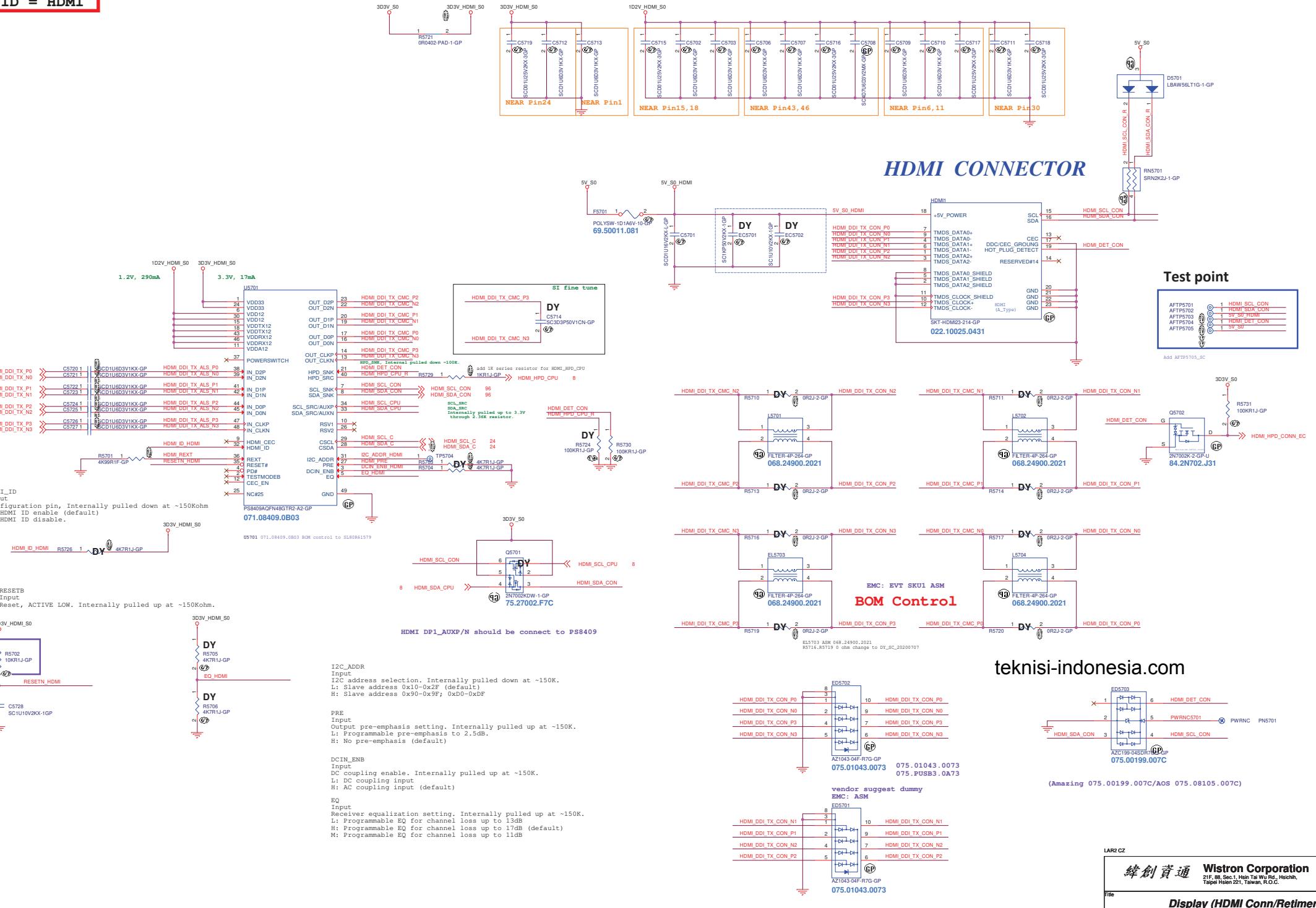
Date: Wednesday, July 28, 2021

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SSID = HDMI



5	4	3	2	1
D			D	
C			C	
B			B	
A			A	
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LAR2 CZ				
		<p>Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.</p>		
Title		<p>Display (RSVD) DP / DVI</p>		
Size A4	Document Number	<p>LAR-2 CZ</p>		Rev -2
Date: Wednesday, July 28, 2021		Sheet	58	of 106
5	4	3	2	1

5	4	3	2	1
D			D	
C			C	
B			B	
A			A	
(Blanking)				
LAR2 CZ				
緯創資通		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title		Display (RSVD)		
Size A4	Document Number	LAR-2 CZ		
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5	4	3	2	1

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Title

INT IO (RSVD)

Size
A4

Document Number

LAR-2 CZRev
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Date: Wednesday, July 28, 2021

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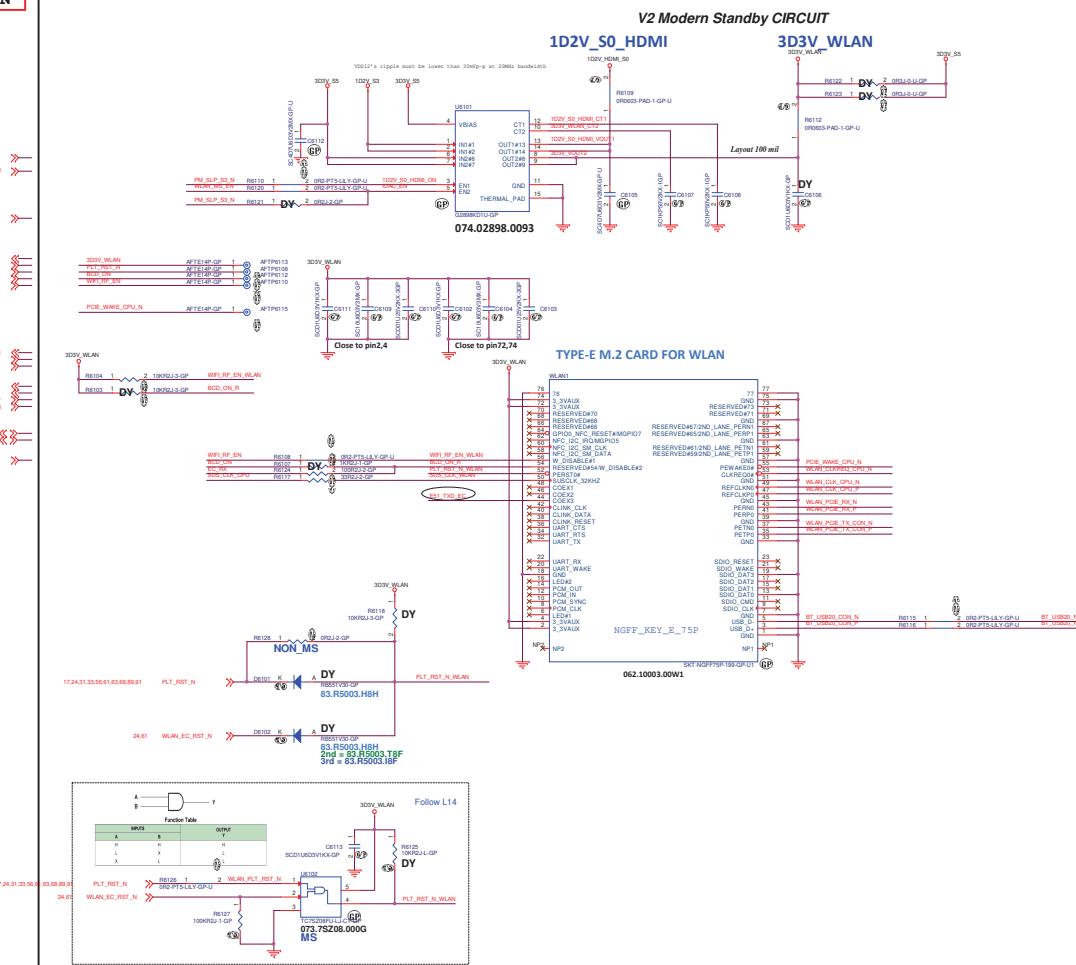


Table 3-1 Key AE 2230-platform and module pinout (H.2 revision fo

Pin #	Pin Name	Platform Pinout	Pin Name	Module Pinout	Voltage on Card Side	WLAN or BT
1	SUSCLK	REFCLK0	SUSCLK	REFCLK0	3.3 V	WLAN + BT
2	I ₂ C_D-	3.3 V	All			
3	USB_D+	3.3 V	BT			
4	I ₂ C_V	3.3 V	All			
5	USB_D-	3.3 V	BT			
6	LED1	LED4	3.3v	WLAN		
7	GND	GND				
8	Command #1	Command#1				
9	Command #2	Command#2				
10	Command #3	Command#3				
11	Command #4	Command#4				
12	Command #5	Command#5				
13	Command #6	Command#6				
14	Command #7	Command#7				
15	Command #8	Command#8				
16	LED2	LED2	3.3V	BT		
17	NC	NC	NA			
18	GND	GND				
19	NC	NC	NA			
20	NC	NC	NA			
21	NC	NC	NA			
22	NC	NC	NA			
23	NC	NC	NA			
24	Transmitter Key	Transmitter#key				
25	Command#key	Command#key				

Pin #	Pin Name	Platform Pinout	Pin Name	Module Pinout	Voltage on Card Side	WLAN or BT
26	RESERVE47	RESERVE47	NC			
27	RESERVE48	RESERVE48	NC			
28	RESERVE49	RESERVE49	NC			
29	RESERVE50	RESERVE50	NC			
30	RESERVE51	RESERVE51	NC			
31	RESERVE52	RESERVE52	NC			
32	NC	NC	NA			
33	GND	GND				
34	NC	NC	NA			
35	PETp0	PETp0	PCle PHY	WLAN		
36	NC	NC	NA			
37	PETp0	PETp0	PCle PHY	WLAN		
38	CLINK RESET (O)(0/3.3 V)	CLINK RESET (I)(0/3.3 V)	3.3 V	WLAN		
39	GND	GND				
40	CLINK DATA	CLINK DATA	CLINK PHY (1 V)	WLAN		
41	PETp0	PETp0	PCle PHY	WLAN		
42	CLINK CLK	CLINK CLK	CLINK PHY (1 V)	WLAN		
43	PETp0	PETp0	PCle PHY	WLAN		
44	COEX1(U0) (O)(0/1.8 V)	COEX1(U0) (O)(0/1.8 V)	1.8 V	WLAN + BT		
45	GND	GND				
46	COEX1(U0) (O)(0/1.8 V)	COEX1(U0) (O)(0/1.8 V)	1.8 V	WLAN + BT		
47	REFCLKp0	REFCLKp0	PCle PHY	WLAN		
48	COEX1 (U0)(0/1.8 V)	COEX1 (U0)(0/1.8 V)	1.8 V	WLAN + BT		

Pin #	Pin Name	Platform Pinout	Pin Name	Module Pinout	Voltage on Card Side	WLAN or BT
49	REFCLK0	REFCLK0	Pcie PHY	WLAN		
50	SUSCLK (O)(0/3.3 V)	SUSCLK (O)(0/3.3 V)	3.3 V	WLAN + BT		
51	GND	GND				
52	PERST# (O)(0/3.3 V)	PERST# (O)(0/3.3 V)	3.3 V	WLAN		
53	CLREQ# (O)(0/3.3 V)	CLREQ# (O)(0/3.3 V)	3.3 V	WLAN		
54	W_DISABLE# (O)(0/3.3 V)	W_DISABLE# (O)(0/3.3 V)	3.3 V	BT		
55	PWAKE# (O)(0/3.3 V)	PWAKE# (O)(0/3.3 V)	3.3 V	WLAN		
56	W_DISABLE1# (O)(0/3.3 V)	W_DISABLE1# (O)(0/3.3 V)	3.3V	WLAN		
57	GND	GND				
58	I ₂ C DATA (O)(0/1.8 V)	I ₂ C DATA (O)(0/1.8 V)	1.8 V	WLAN + BT		
59	PETp1	PETp1	PCle PHY	N/A		
60	I ₂ C CLK/UART_RX (O)(0/1.8 V)	I ₂ C CLK/UART_RX (O)(0/1.8 V)	1.8 V	WLAN + BT		
61	PETp1	PETp1	PCle PHY	N/A		
62	ALERT#(UART_CTS (O)(0/1.8 V))	ALERT#(UART_RTS (O)(0/1.8 V))	1.8 V	WLAN + BT		
63	GND	GND				

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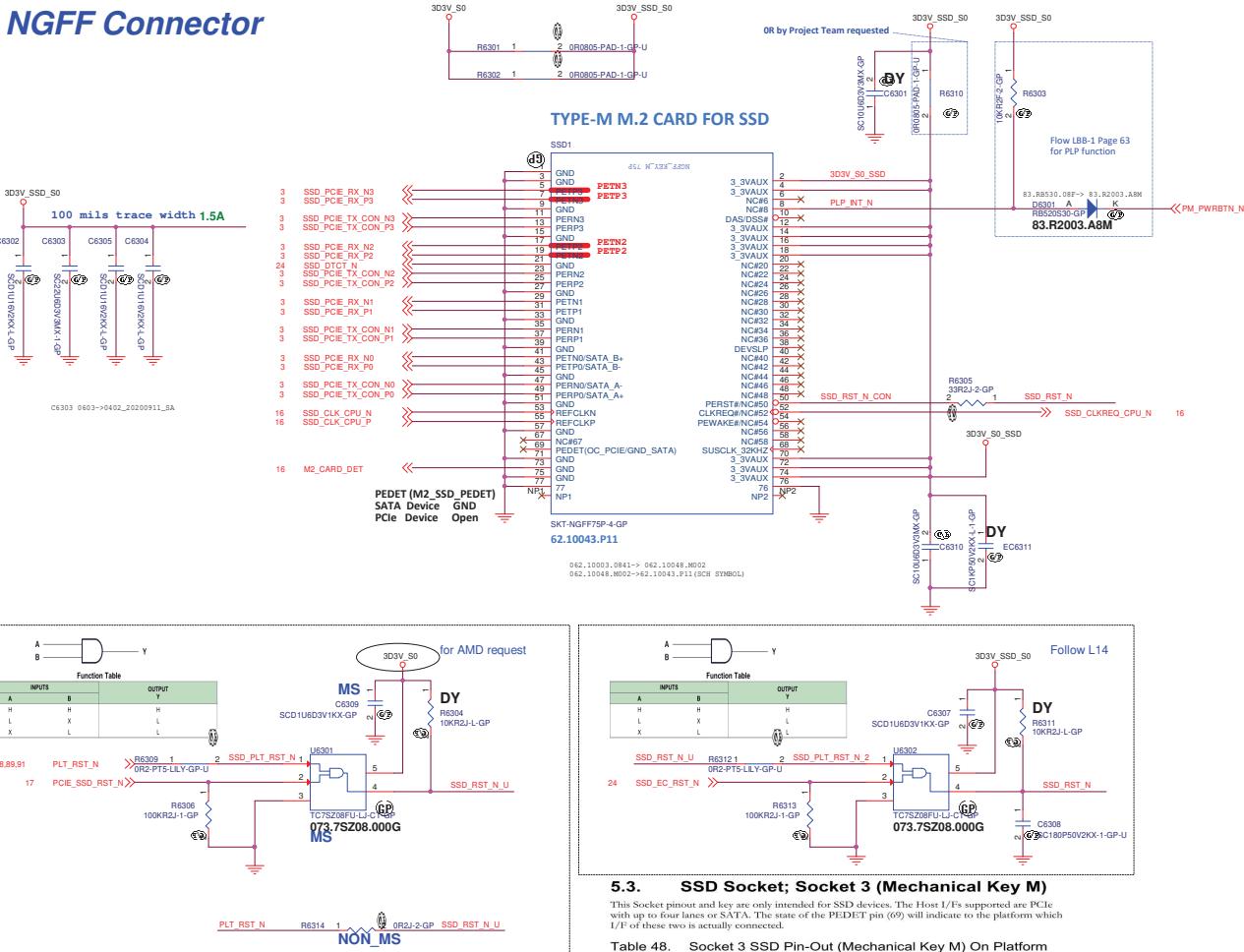
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Title **INT IO (RSVD)**

Size A4 Document Number **LAR-2 CZ** Rev **-2**

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NGFF Connector



Pin #	Function	Definition	Pin #	Function	Definition
1	GND	Ground	2	3.3V	3.3 V Source
3	GND	Ground	4	3.3V	3.3 V Source
5	PETn3	PCIe Tx3-	6	N/C	N/C
7	PETp3	PCIe Tx3+	8	PLP INIT#	PLP INIT#
9	GND	Ground	10	LED1#	Device Activity Signal
11	PERn3	PCIe Rx3-	12	3.3V	3.3 V Source
13	PERp3	PCIe Rx3+	14	3.3V	3.3 V Source
15	GND	Ground	16	3.3V	3.3 V Source
17	PETn2	PCIe Tx2-	18	3.3V	3.3 V Source
19	PETp2	PCIe Tx2+	20	N/C	N/C
21	GND	Ground	22	N/C	N/C
23	PERn2	PCIe Rx2-	24	N/C	N/C
25	PERp2	PCIe Rx2+	26	N/C	N/C
27	GND	Ground	28	N/C	N/C
29	PETn1	PCIe Tx1-	30	PLP_FDBK#	Reserved for PLP_FDBK#
31	PETp1	PCIe Tx1+	32	N/C	N/C
33	GND	Ground	34	N/C	N/C
35	PERn1	PCIe Rx1-	36	N/C	N/C
37	PERp1	PCIe Rx1+	38	N/C	N/C
39	GND	Ground	40	SMB_CLK	SMbus Clock (Default disabled)
41	PERn0	PCIe Tx0-	42	SMB_SDA	SMbus Data (Default disabled)
43	PERp0	PCIe Tx0+	44	ALERT#	Alert notification (Default disabled)
45	GND	Ground	46	N/C	N/C
47	PERn0	PCIe Rx0-	48	N/C	N/C
49	PERp0	PCIe Rx0+	50	PERST#	PCIe Reset
51	GND	Ground	52	CLKREQ#	PCIe Device Clock Request
53	REFCLKn	PCIe Reference Clock-	54	N/C	N/C
55	REFCLKp	PCIe Reference Clock+	56	N/C	N/C
57	GND	Ground	58	N/C	N/C
67	N/C	N/C	68	SUSCLK	N/C
69	PEDET	N/C	70	3.3V	3.3 V Source
71	GND	Ground	72	3.3V	3.3 V Source
73	GND	Ground	74	3.3V	3.3 V Source
75	GND	Ground			

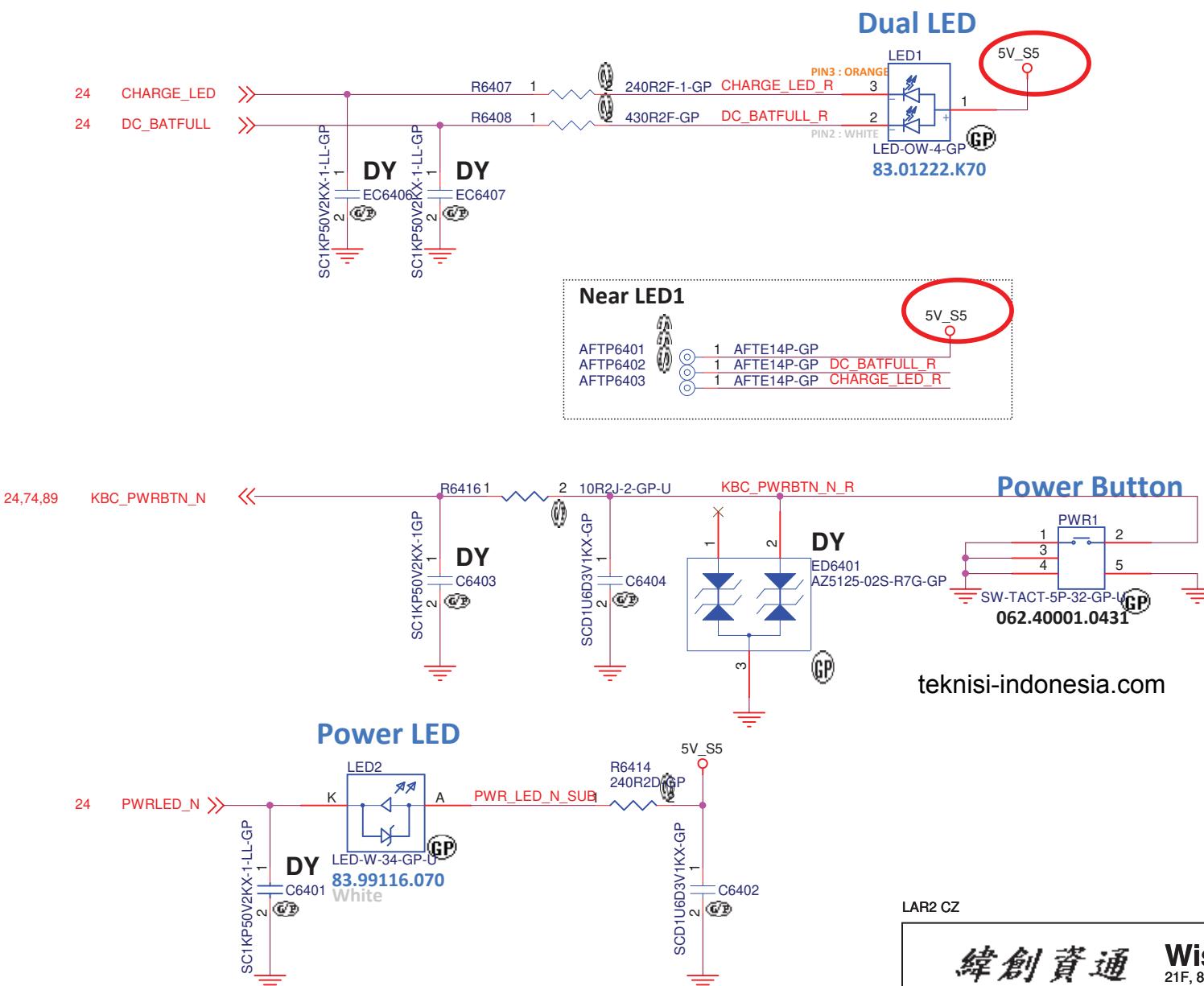
5.3. SSD Socket; Socket 3 (Mechanical Key M) On Platform

This Socket pinout and key are only intended for SSD devices. The Host I/Fs supported are PCIe with up to four lanes or SATA. The state of the PEDET pin (69) will indicate to the platform which I/F of these two is actually connected.

Table 48. Socket 3 SSD Socket Pin-Out (Mechanical Key M) On Platform

74	3.3V	GND	75	3.3V	3.3 V Source
72	3.3V	GND	73	3.3V	3.3 V Source
70	0	GND	71	3.3V	3.3 V Source
68	SUSCLK(HIGH) (0.010V/3.3V)	N/C	69	3.3V	3.3 V Source
	Connector Key	Connector Key			

LAR2 CZ



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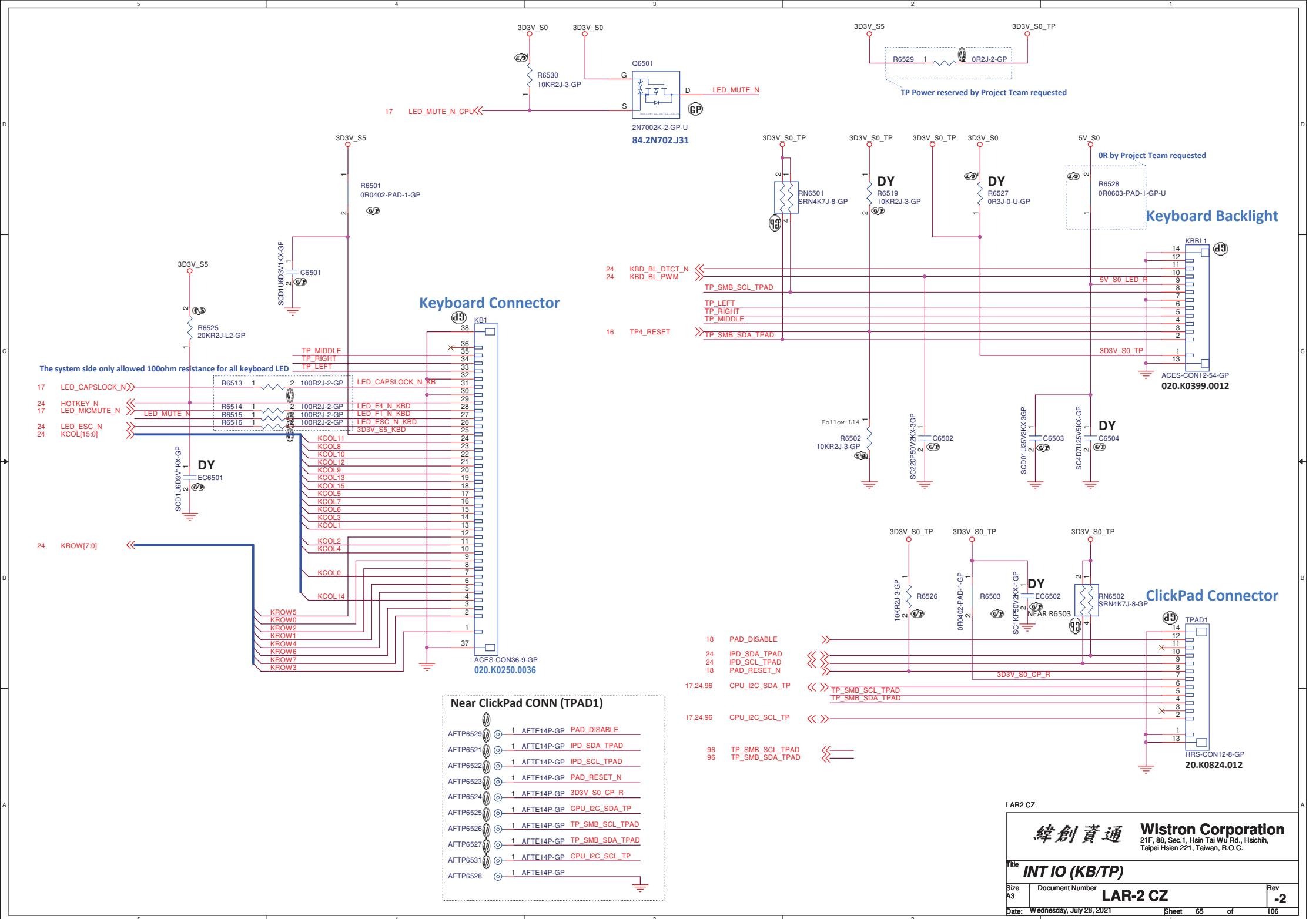
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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

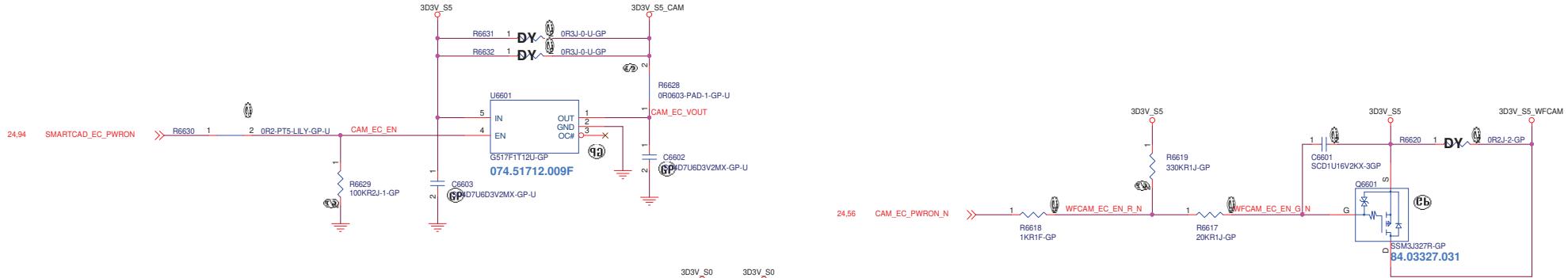
LED/BTN/POWER BTN

Size A4 Document Number LAR-2 CZ Rev -2

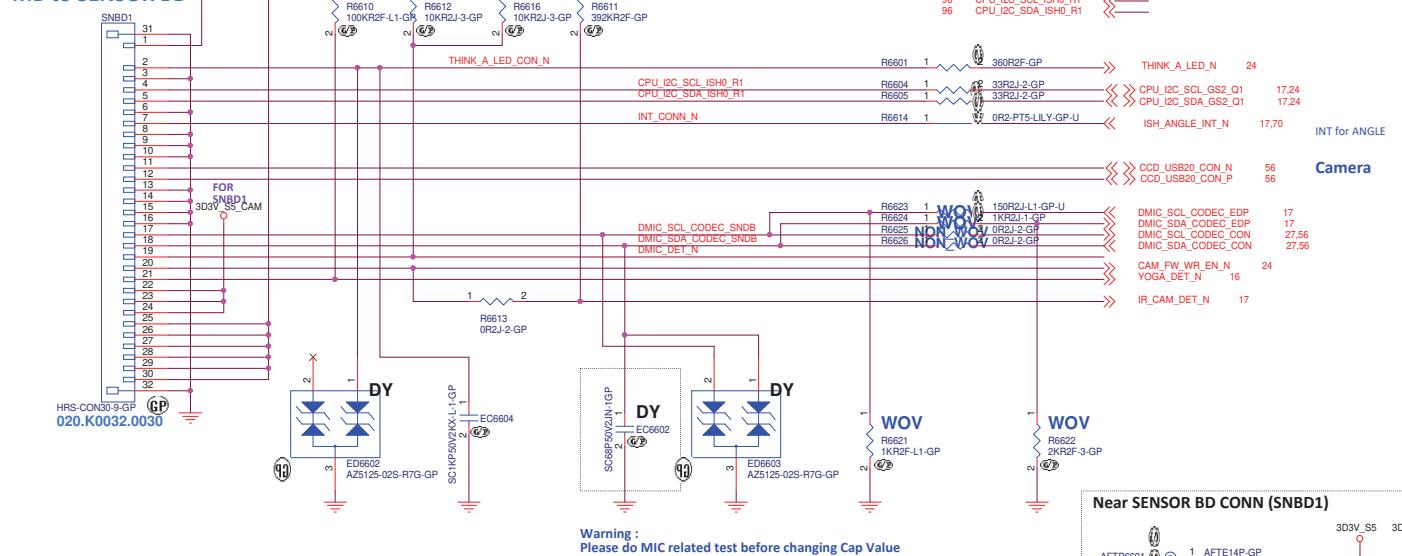
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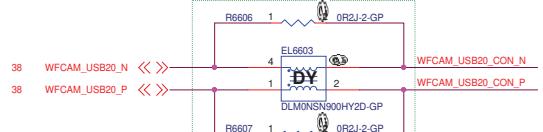




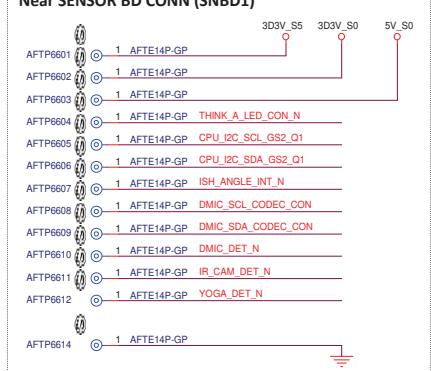
MB to SENSOR BD



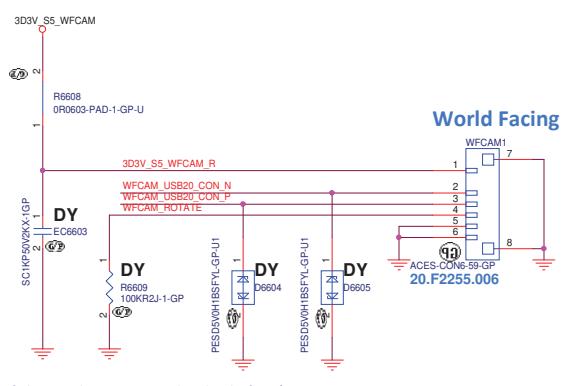
Co-Layout



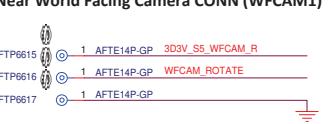
Near SENSOR BD CONN (SNBD1)



World Facing Camera

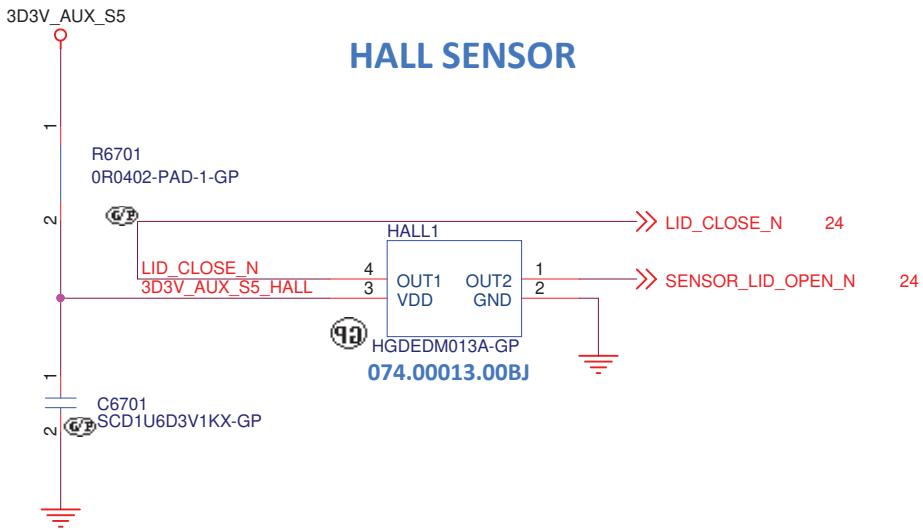


Near World Facing Camera CONN (WFCAM1)



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Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Heilong, Taipei 11211, Taiwan, R.O.C.	
Title	IO BOARD CONN (SNBD/WFCAM)
Size	Document Number
Custom	LAR-2 CZ
Date:	Wednesday, July 28, 2021
Rev	-2

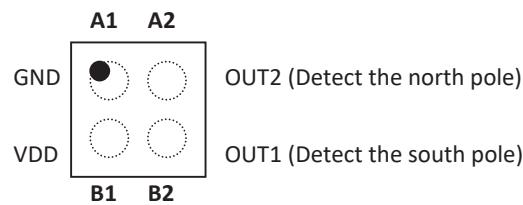


Pin1 need place at "Upper Right Corner"

LID_CLOSE_N : NB Lid function
SENSOR_LID_OPEN#: Tablet detect function

Pin Configuration

TOP VIEW (pads not visible)



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Title Sensor (Hall-Sensor)	
Size A4	Document Number
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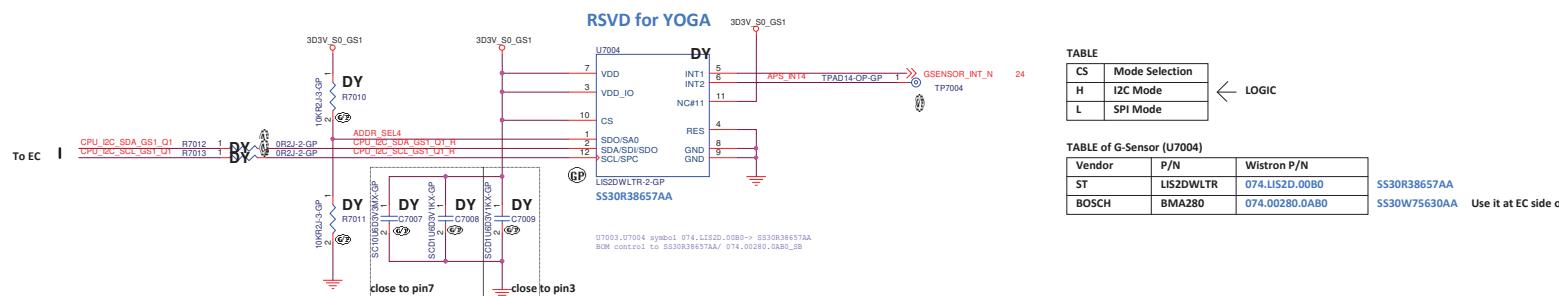
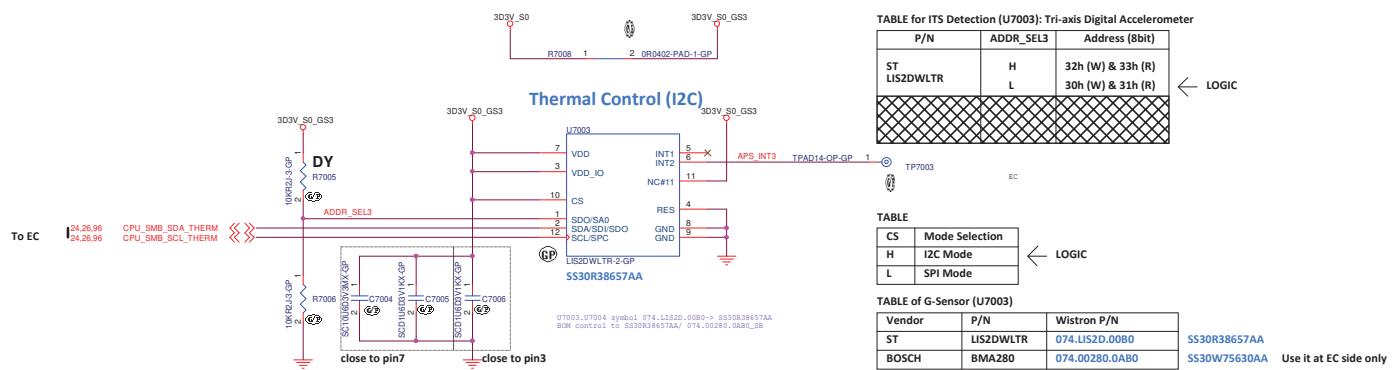
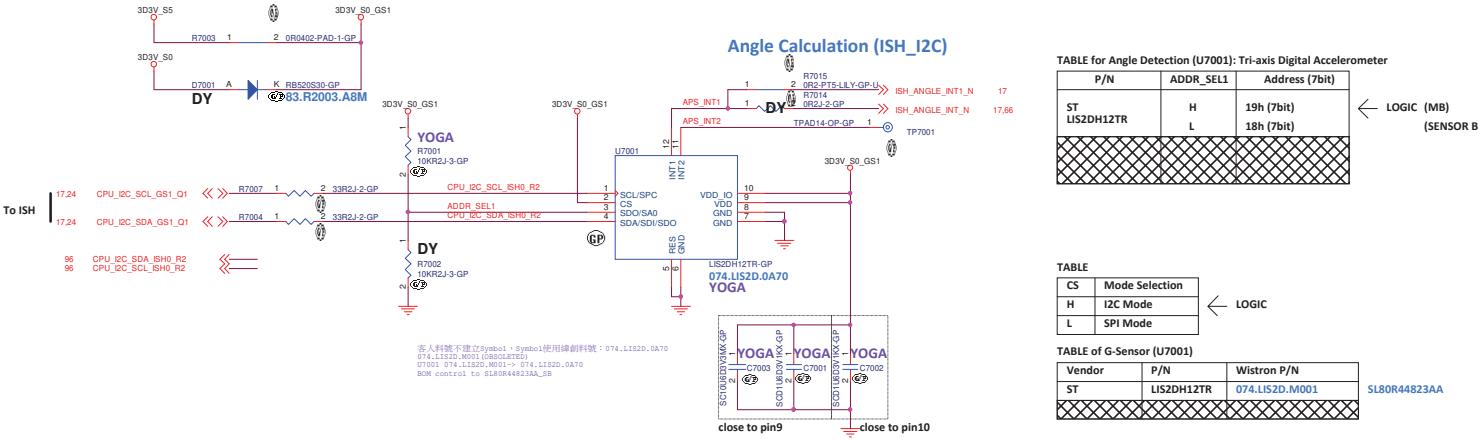
LAR2 CZ

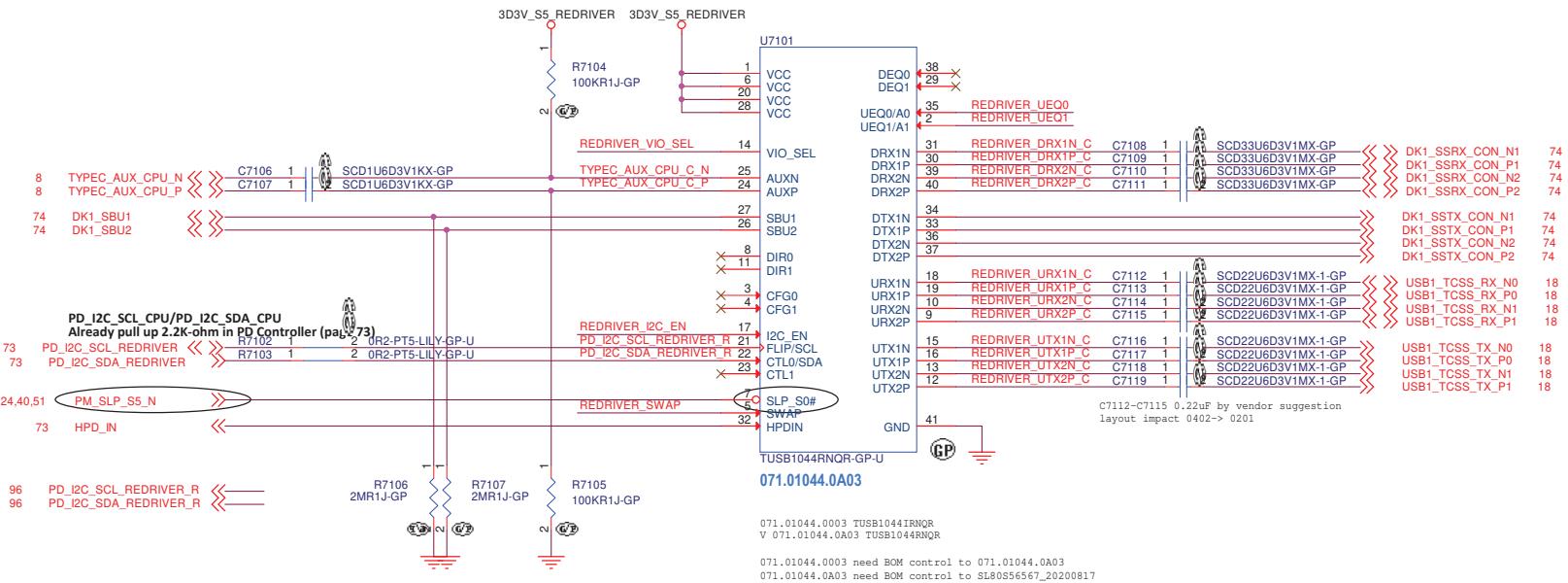
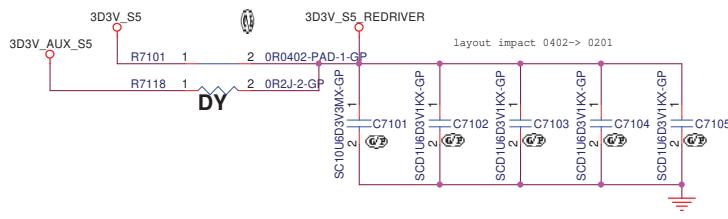
緯創資通

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title
Sensor (RSVD)

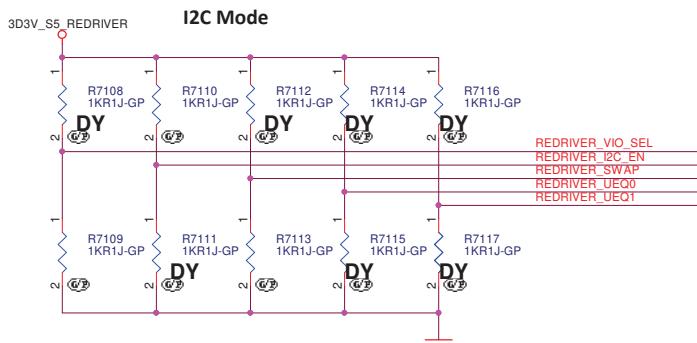
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To TYPEC USB3

HOST (From CPU)



I2C_EN: 1=I2C enabled
VIO_SEL: 0 = 3.3-V configuration I/O voltage, 3.3-V I 2C interface (Default)
SWAP: 0 - Do not swap channel directions and EQ settings (Default)
UEQ0/A0 and UEQ1/A1:FF

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Title THUNDERBOLT RE TIMER(1/2)	
Size A3	Document Number LAR-2 CZ
Date: Wednesday, July 28, 2021	Rev -2
Sheet 71	of 106

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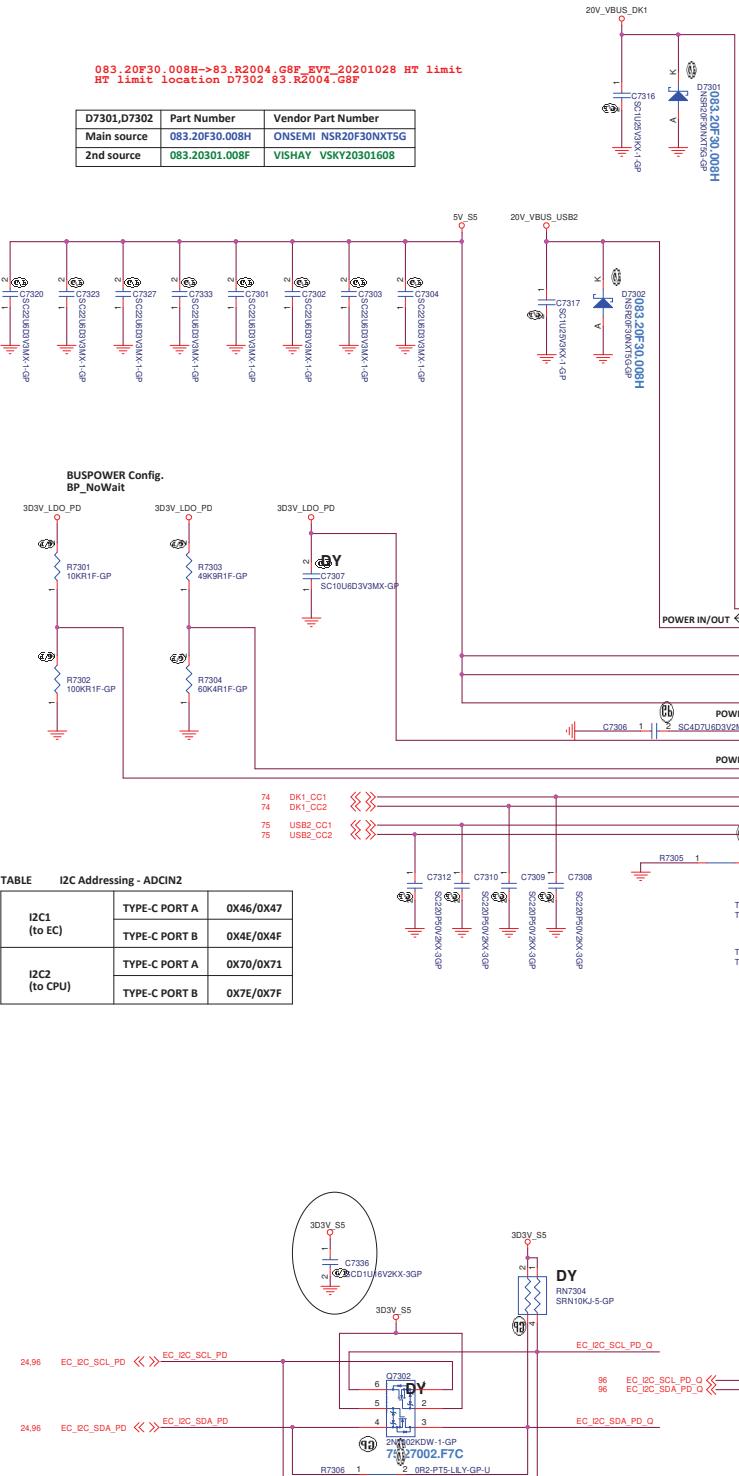
LAR2 CZ

緯創資通

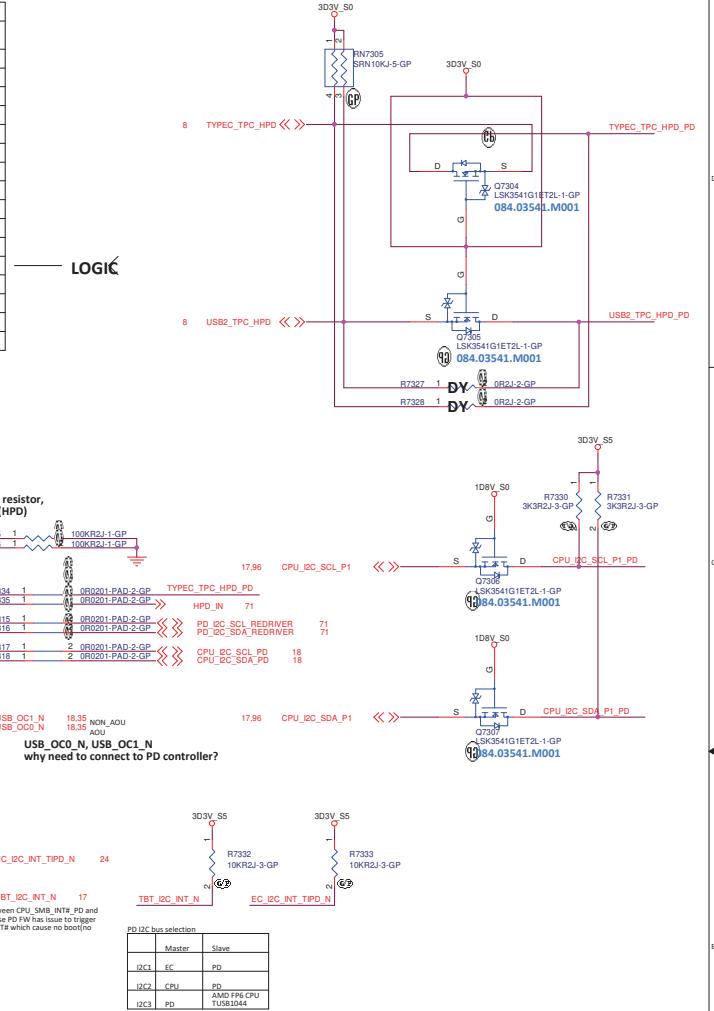
Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title **THUNDERBOLT RE TIMER(2/2)**

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Date: Wednesday, July 28, 2021		Sheet 72	of 106

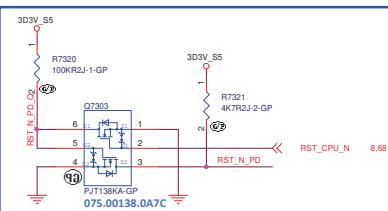
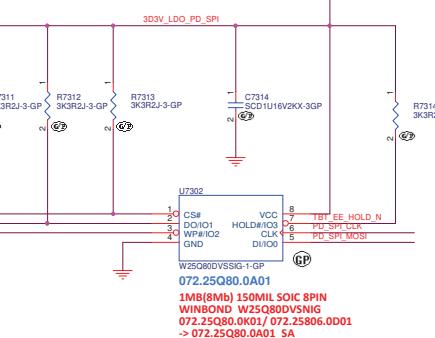


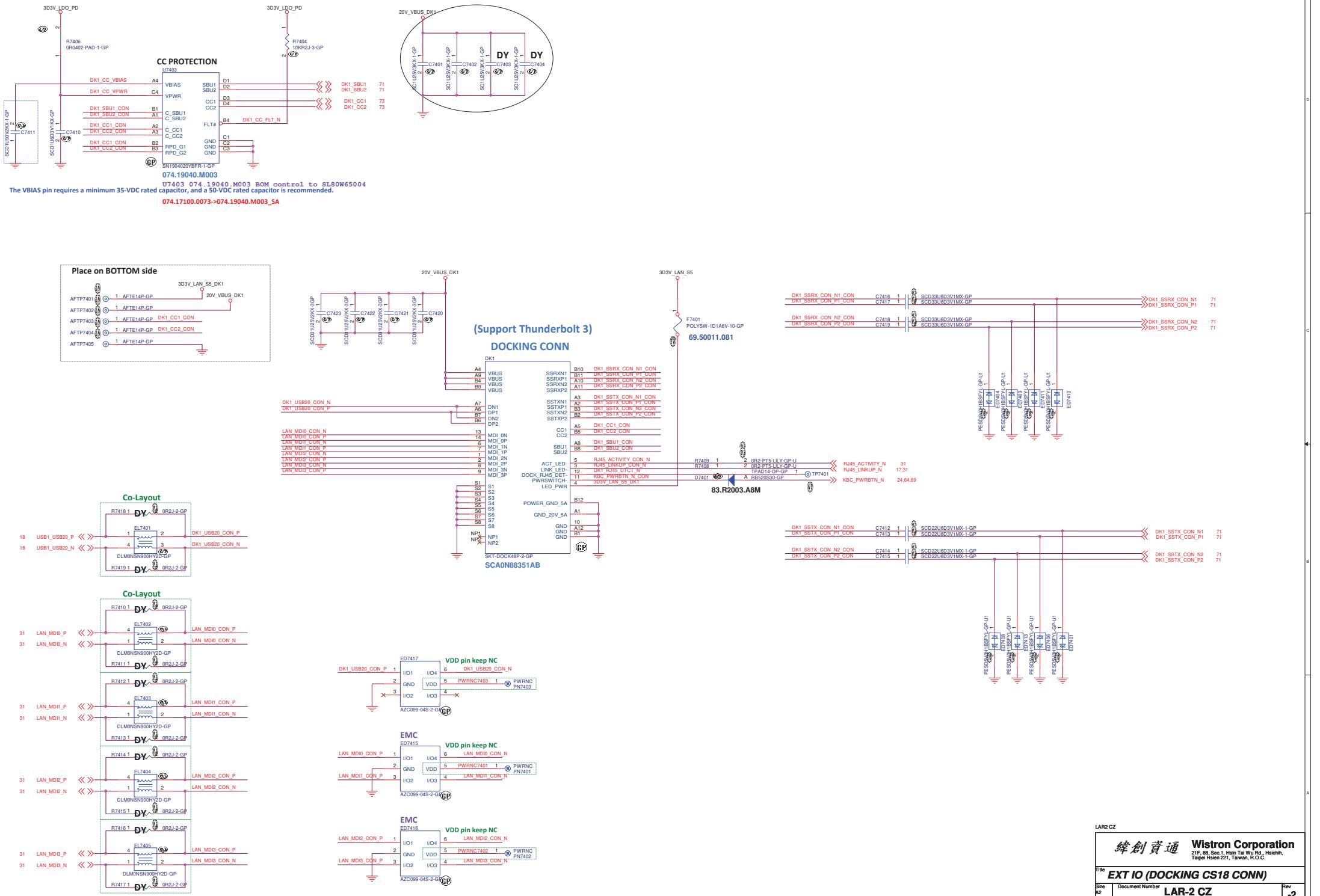
BUSPOWER Configuration - ADCIN1 DV1 = R2/(R1+R2)					
SPI_MISO	DIV MIN	DIV MAX	Dead_Battery		Default_Config
1	0	0.18	BP_NoResponses		SAFE
1	0.2	0.28	BP_WaitFor3V3_Internal		SAFE
1	0.3	0.38	BP_ECWAIT_Internal		(Infinite) wait for patch until (ETC[3])==>SAFE
1	0.4	0.48	BP_WaitFor3V3_External		SAFE
1	0.5	0.58	BP_ECWAIT_Internal		(Infinite) wait for patch until (ETC[5])==>SAFE
1	0.6	1	BP_NoWait (No Switch is closed)		SAFE
0	0	0.08	BP_NoResponse(85 Device)		0
0	0.1	0.18	BP_NoResponse		1
0	0.2	0.28	BP_NoWait		2
0	0.3	0.38	BP_ECWAIT_Internal		(Infinite) wait for patch until (ETC[3])==>SAFE
0	0.4	0.48	BP_NoWait		3
0	0.5	0.58	BP_ECWAIT_Internal		(Infinite) wait for patch until (ETC[5])==>SAFE
0	0.6	0.68	BP_NoWait		4
0	0.7	0.78	RSVD		RSVD
0	0.8	0.88	RSVD		RSVD
0	0.9	1.0	BP_NoWait		5

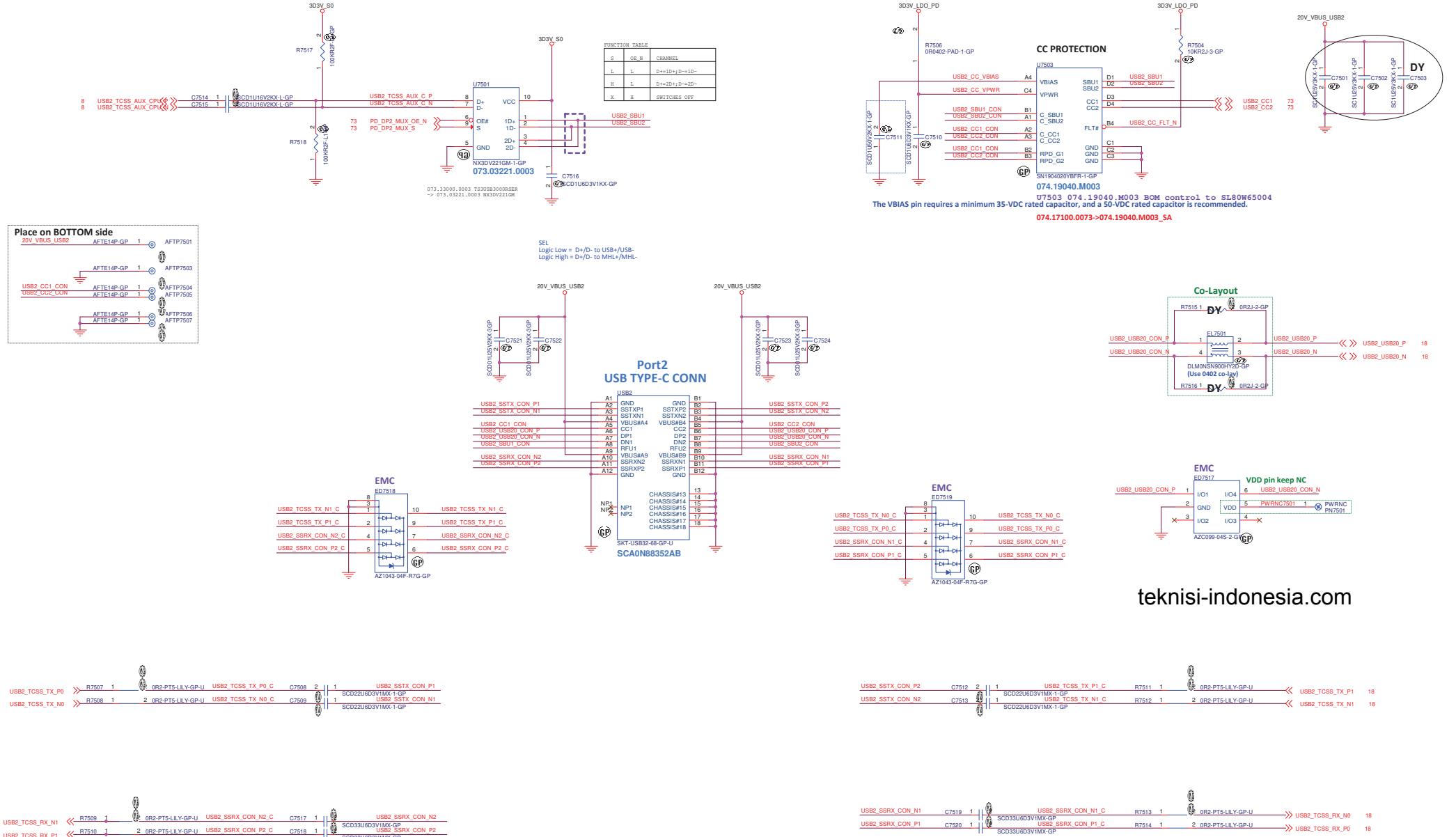


083.00520.0D8F change to 83.R2003.A8M
EVT verify

Add SPI ROM for SPI less architecture mitigation. 32kB is required at minimum.







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Title
GPU (RSVD)

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Title
GPU (RSVD)

Size
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Title

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GPU (RSVD)

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Title
GPU (RSVD)

Size
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A			A	
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Title

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Title

GPU (RSVD)

Size
A4

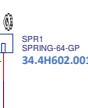
Document Number
LAR-2 CZ

Rev
-2

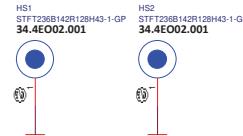
Date: Wednesday, July 28, 2021

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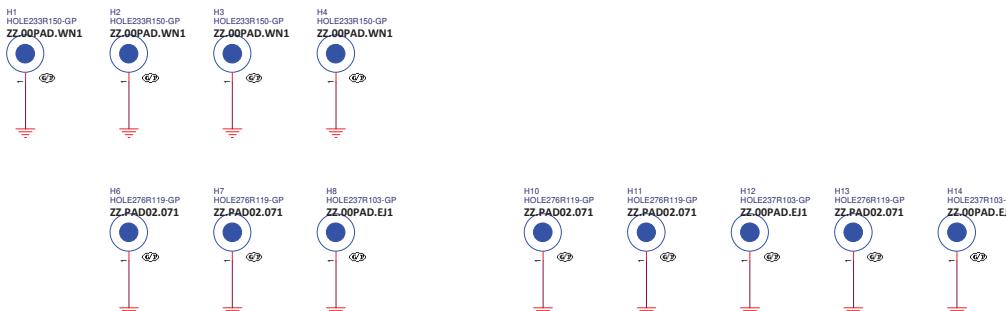
EMI Spring



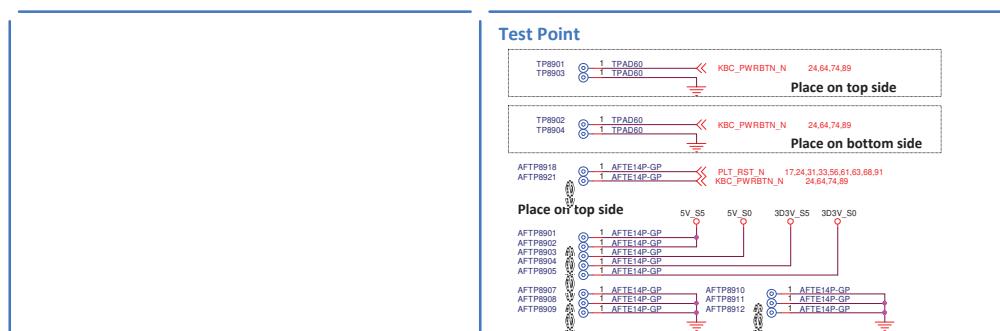
Stand Off



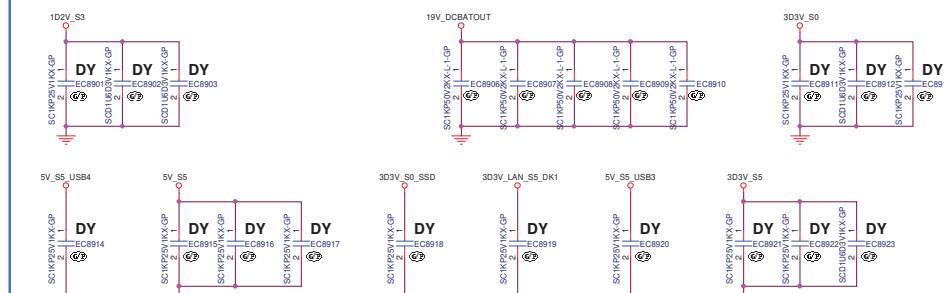
Screw Pad



RF CAPS

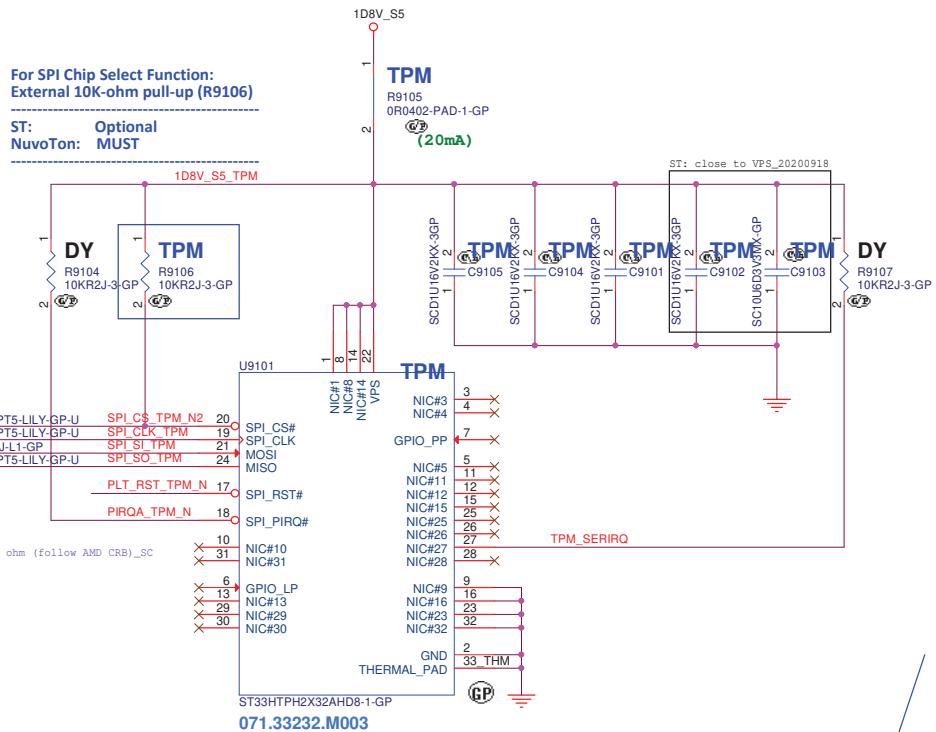


EMI CAPS



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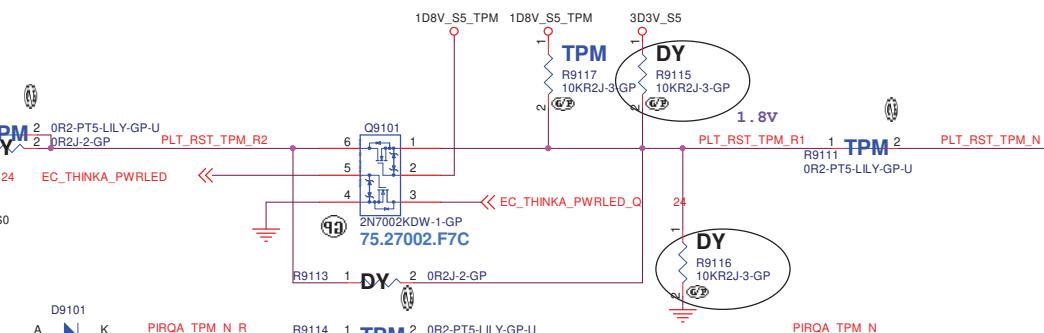
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Title	INT IO (RSVD)			
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SPI Chip Select Pin: ST (SPI_CS#) Internal pull-up
Nuvoton (SCS#) Internal pull-up is disabled if the pin is part of the recognized host interface

TPM TABLE		
1st	ST33HTPH2X32AHD8	071.33232.M003
2nd	NPCT750LADYX	071.00750.0H03

Nuvoton TPM FW: 7.2.1.0 part will be dropped, and instead by new one_20200603
Nuvoton PNLenovo PNTPM FW
NPCT750LADYXSL80W591227.2.2.0
NPCT750LABYXSL80R401587.2.2.0



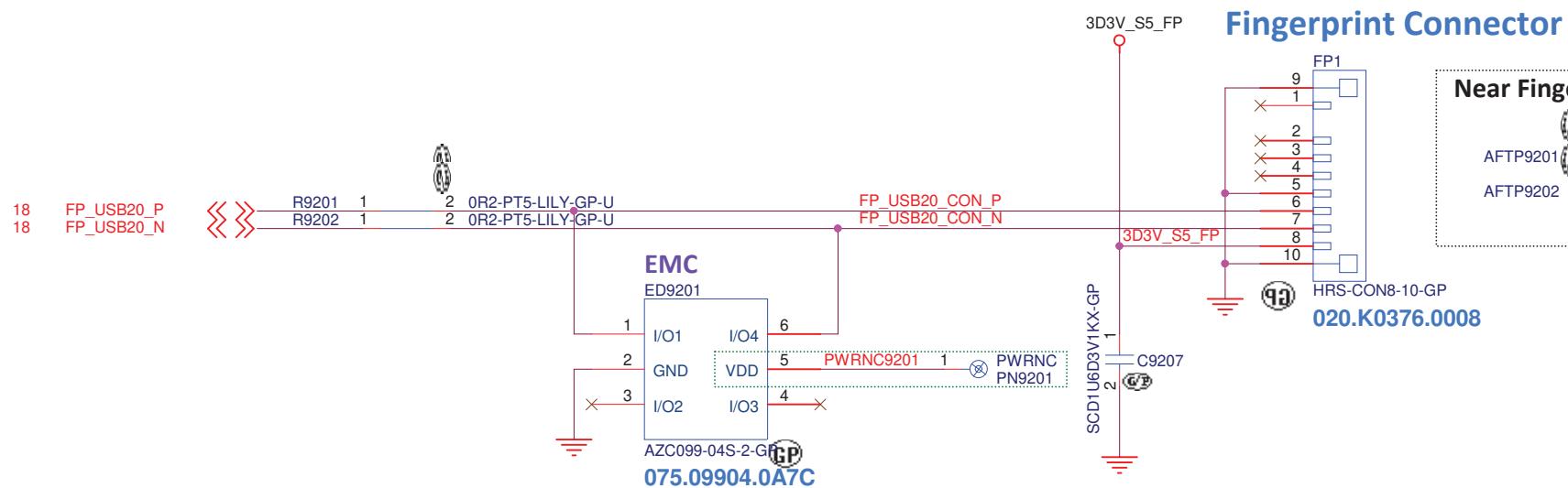
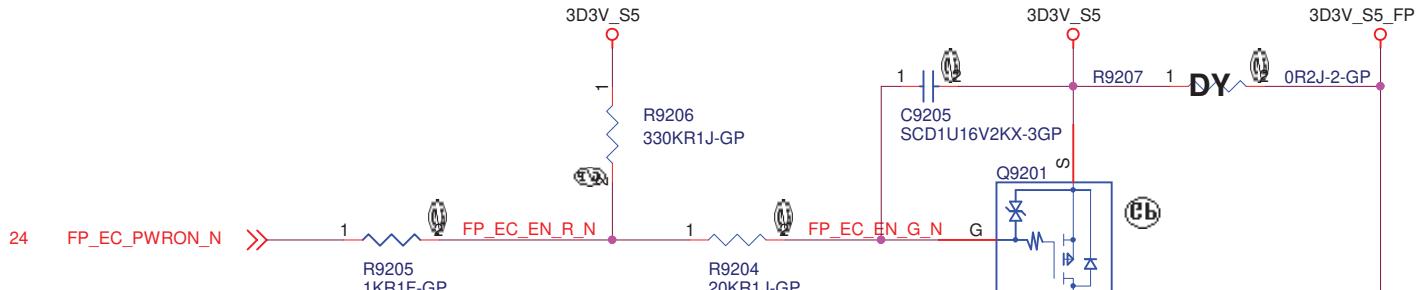
83.R5003.V8F change to 83.R2003.A8M
EVT verify!!

TABLE 071.33232.M003 071.00750.0H03

Pin No	TCG PTP Spec(V38)	ST ST33HTPH2X32AHD8	NuvoTon NPCT750LADYX	Pin Description
P	1 VDD	NC	VSB	VDD
	2 GND	GND	NC	GND
	3 NC	NC	NC	NC
	4 GPIO	NC	GPIO/PP	NC
	5 NC	NC	NC	NC
	6 GPIO	GPIO_LP	GPIO3	GPIO
	7 GPIO	GPIO_PP	NC	DR
	8 VDD	NC	VHIO	VDP
P	9 NC	NC	NC	GND
	10 NC	NC	NC	NC
	11 NC	NC	NC	NC
	12 NC	NC	NC	NC
	13 GPIO	NC	GPIO4	NC
	14 NC	NC	NC	NC
	15 NC	NC	NC	NC
	16 GND	NC	GND	NC
P	17 SPI_RST#	SPI_RST#	RST#	RST#
	18 SPI_PIRQ#	SPI_PIRQ#	PIRQ#/GPIO2	PIRQ#
	19 SPI_CLK	SPI_CLK	SCLK	SCLK
	20 SPI_CS#	SPI_CS#	SCS#/GPIO5	CS#
	21 MOSI	MOSI	MOSI/GPIO7	MOSI
	22 VDD	VPS	VHIO	VDD
	23 GND	NC	GND	GND
	24 MISO	MISO	MISO	MISO
P	25 NC	NC	NC	NC
	26 NC	NC	NC	NC
	27 NC	NC	NC	NC
	28 NC	NC	NC	NC
	29 SDA(GPIO1	NC	SDA/GPIO0	NC
	30 SDA(GPIO0	NC	SCL/GPIO1	NC
	31 NC	NC	NC	NC
	32 NC	NC	NC	GND

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Title INT IO (TPM)				
Size A3	Document Number LAR-2 CZ			Rev -2
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Title **INT IO (FINGERPRINT)**

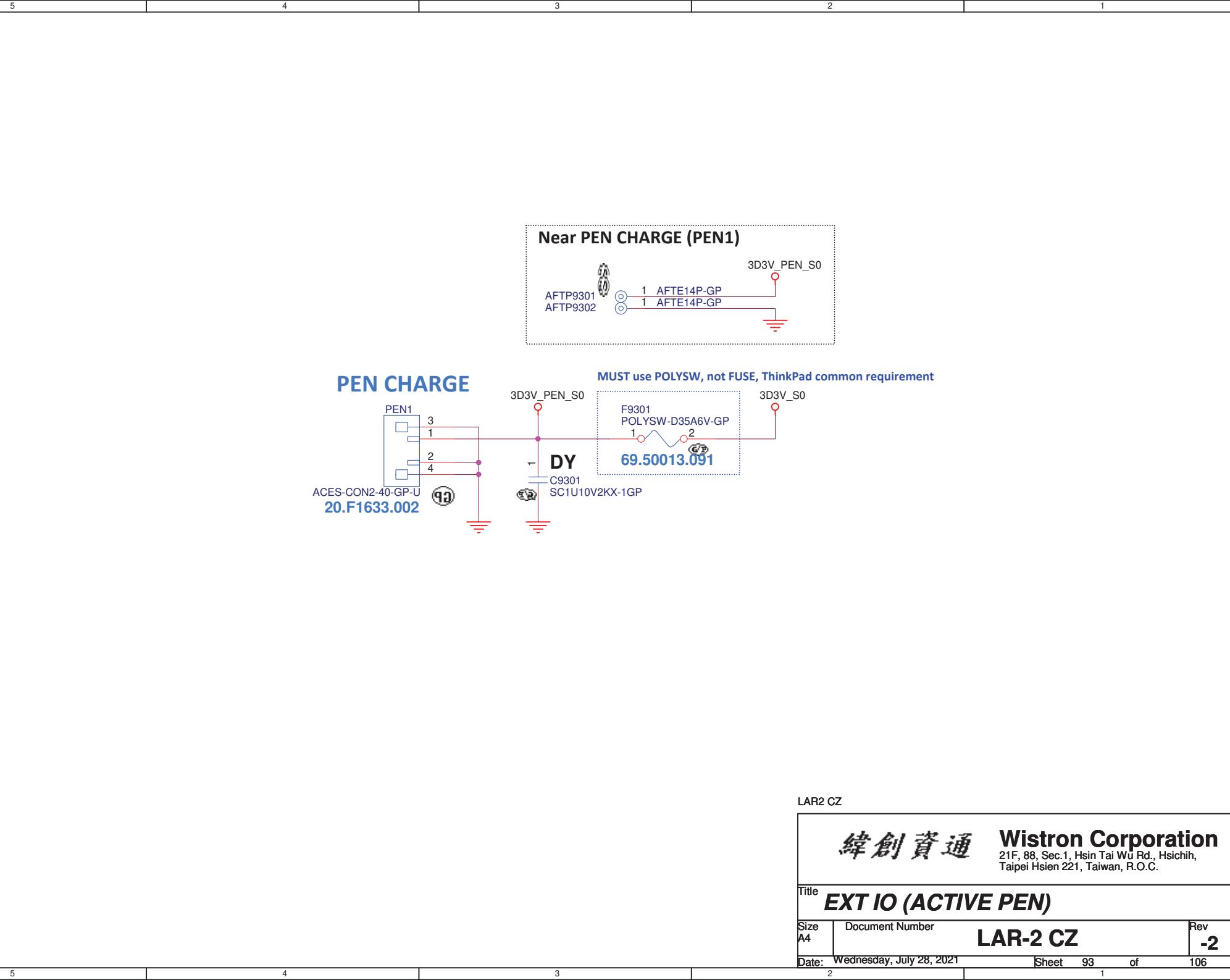
Size A4 Document Number

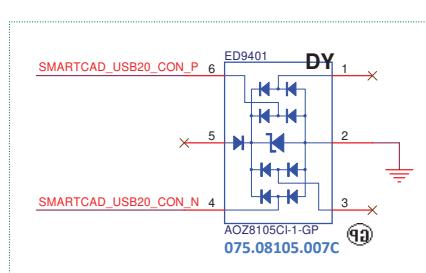
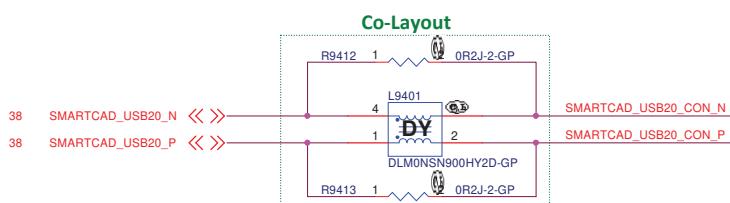
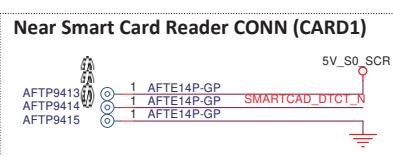
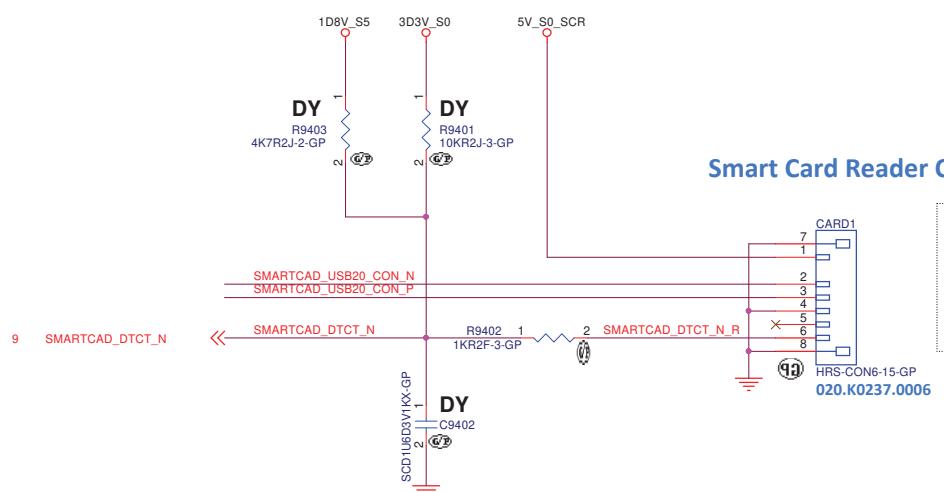
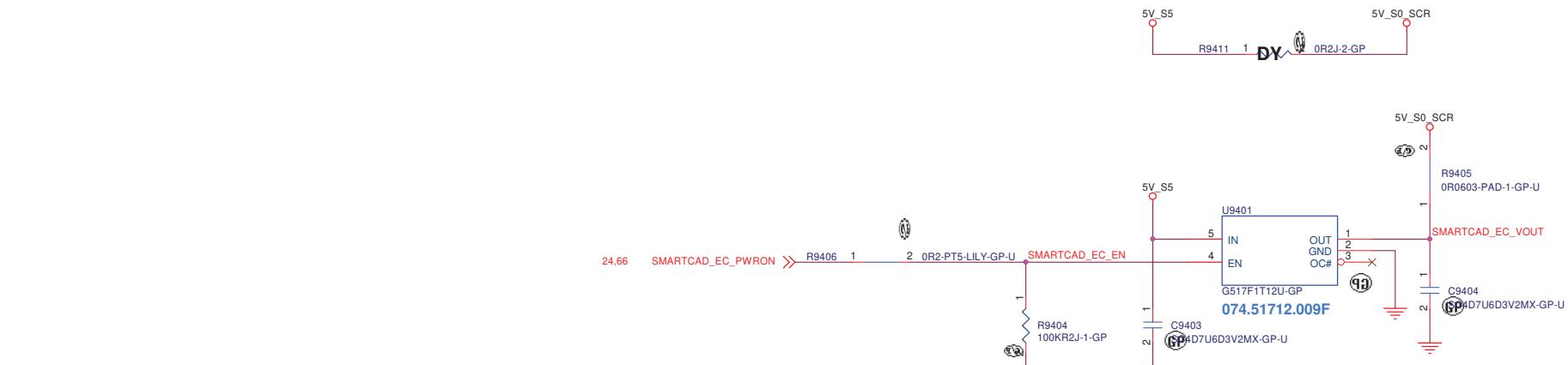
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Title
EXT IO (RSVD)

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SITP DSN Template for 203088_LAR2



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		<p>Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.</p>		
Title		<p>Commercial (RSVD)</p>		
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Title **Commercial (RSVD)**

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Title **Debug (RSVD)**

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Title

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Title

Power Sequence

Size
A4

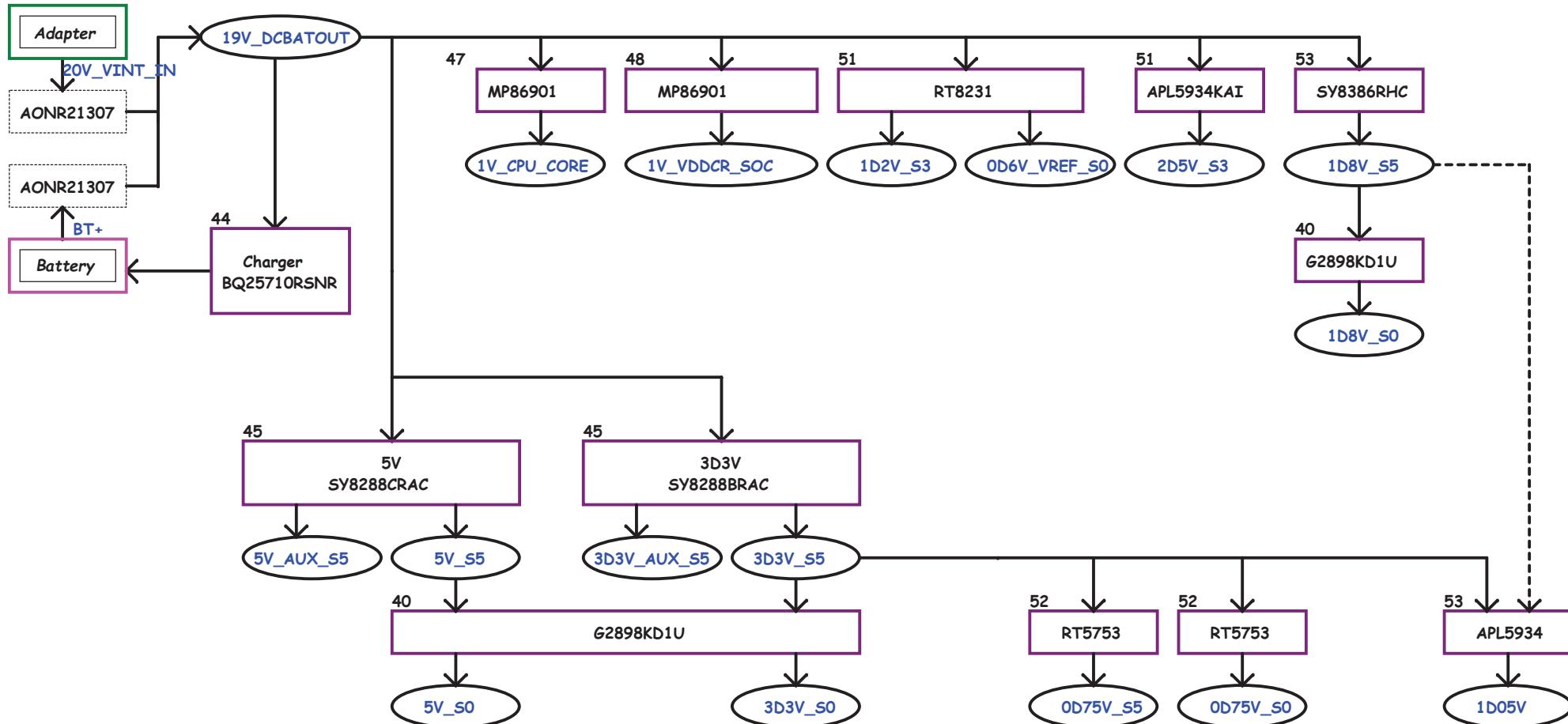
Document Number

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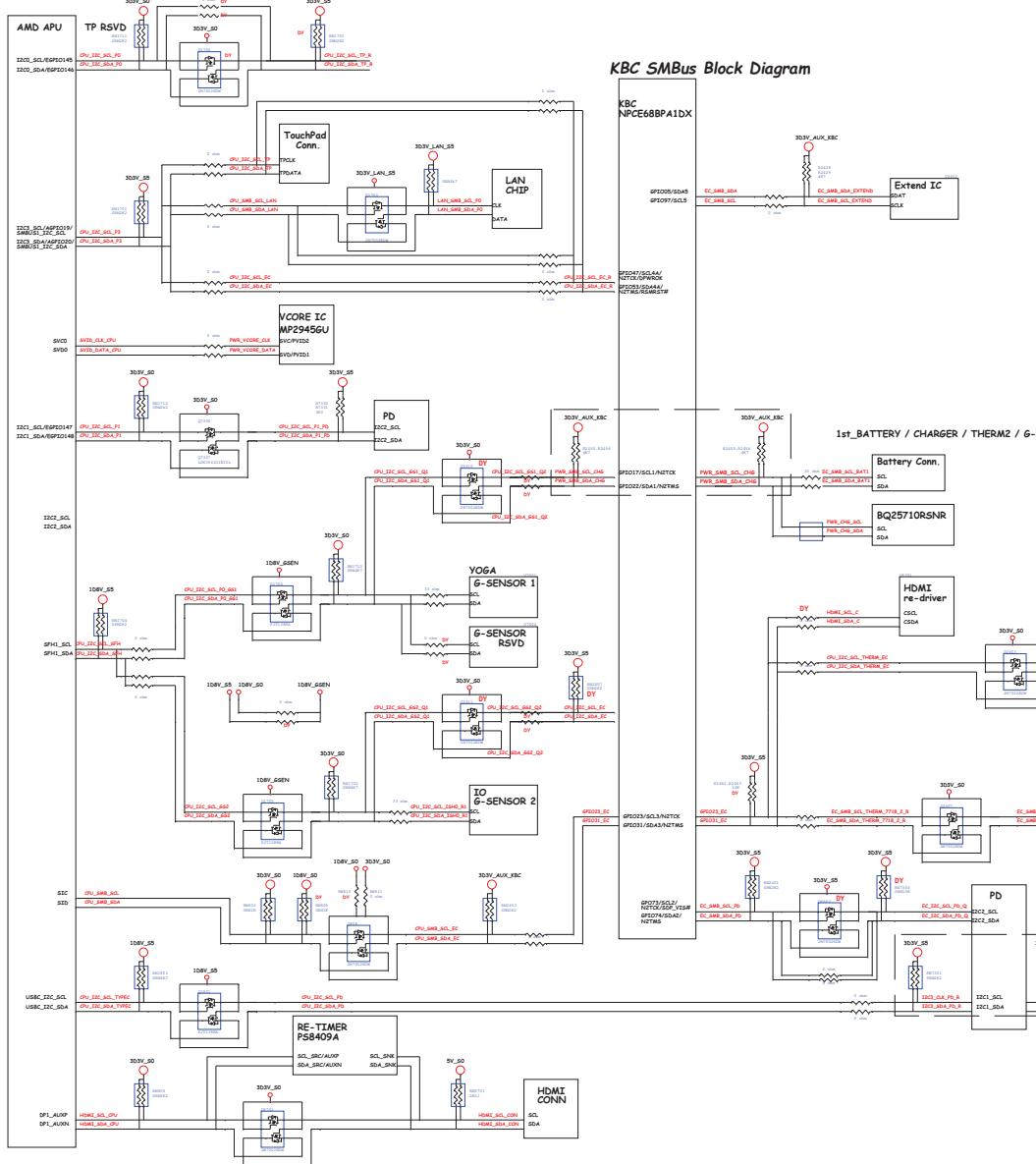
LAR-2 CZ

Date: Wednesday, July 28, 2021

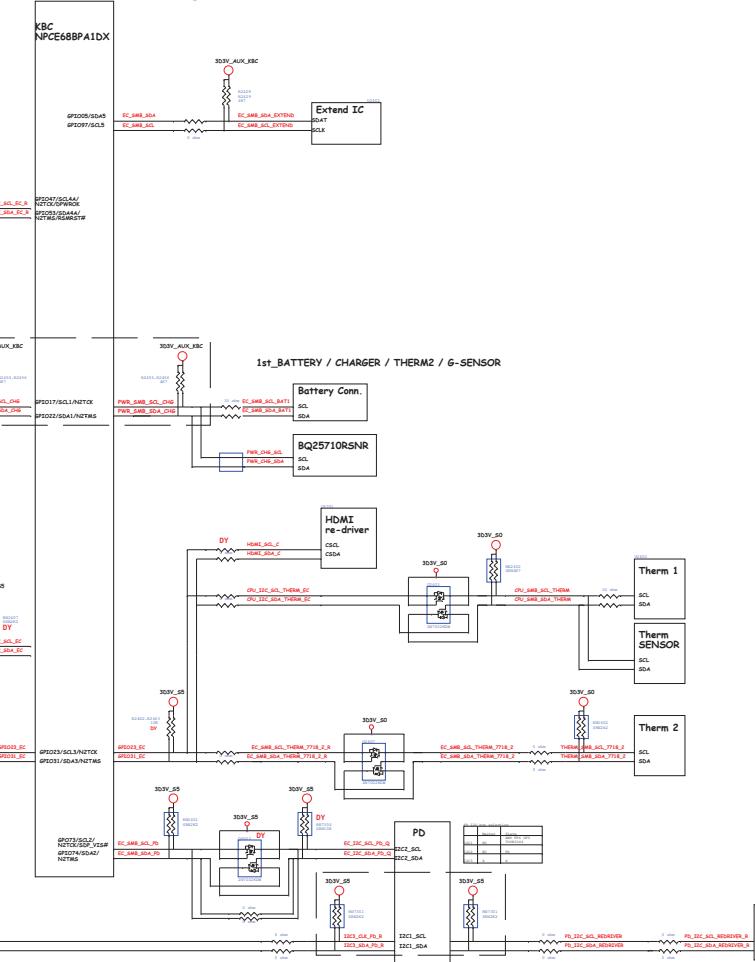
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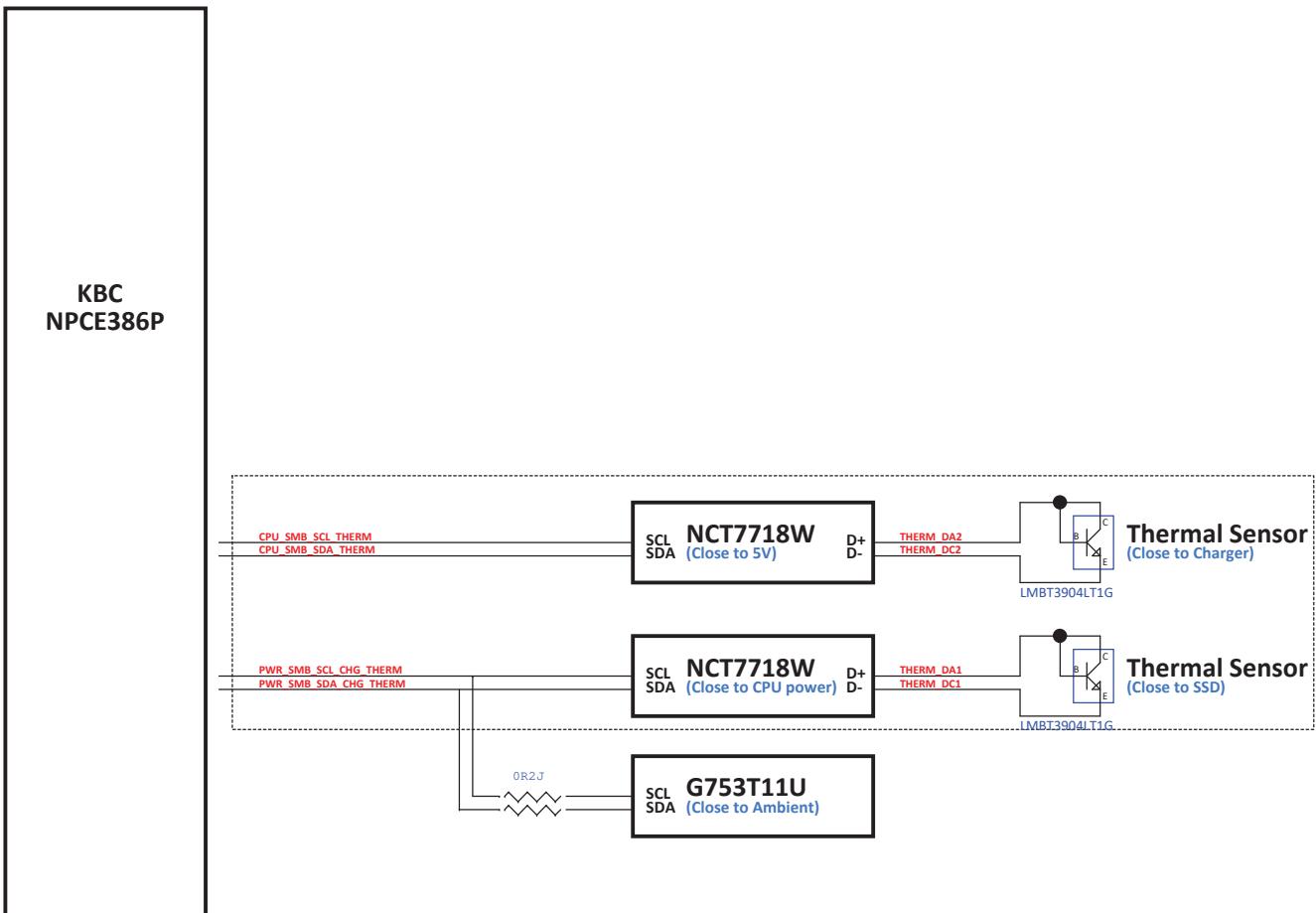
APU SMBus Block Diagram



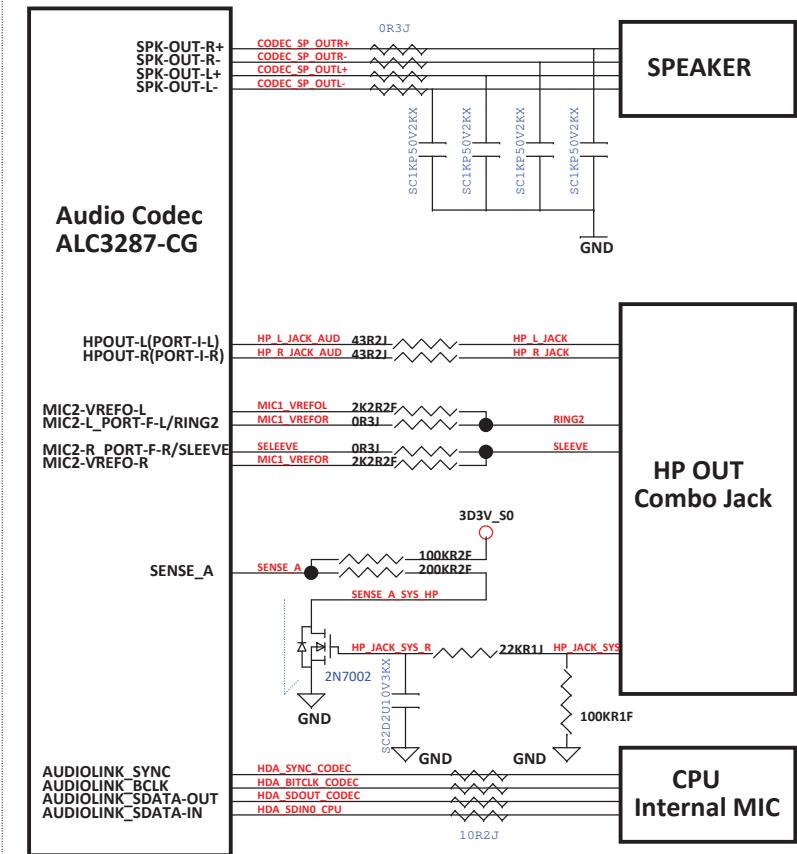
KBC SMBus Block Diag



Thermal Block Diagram



Audio Block Diagram



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Title THERMAL/AUDIO BLOCK DIAGRAM	
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CLK Block Diagram

